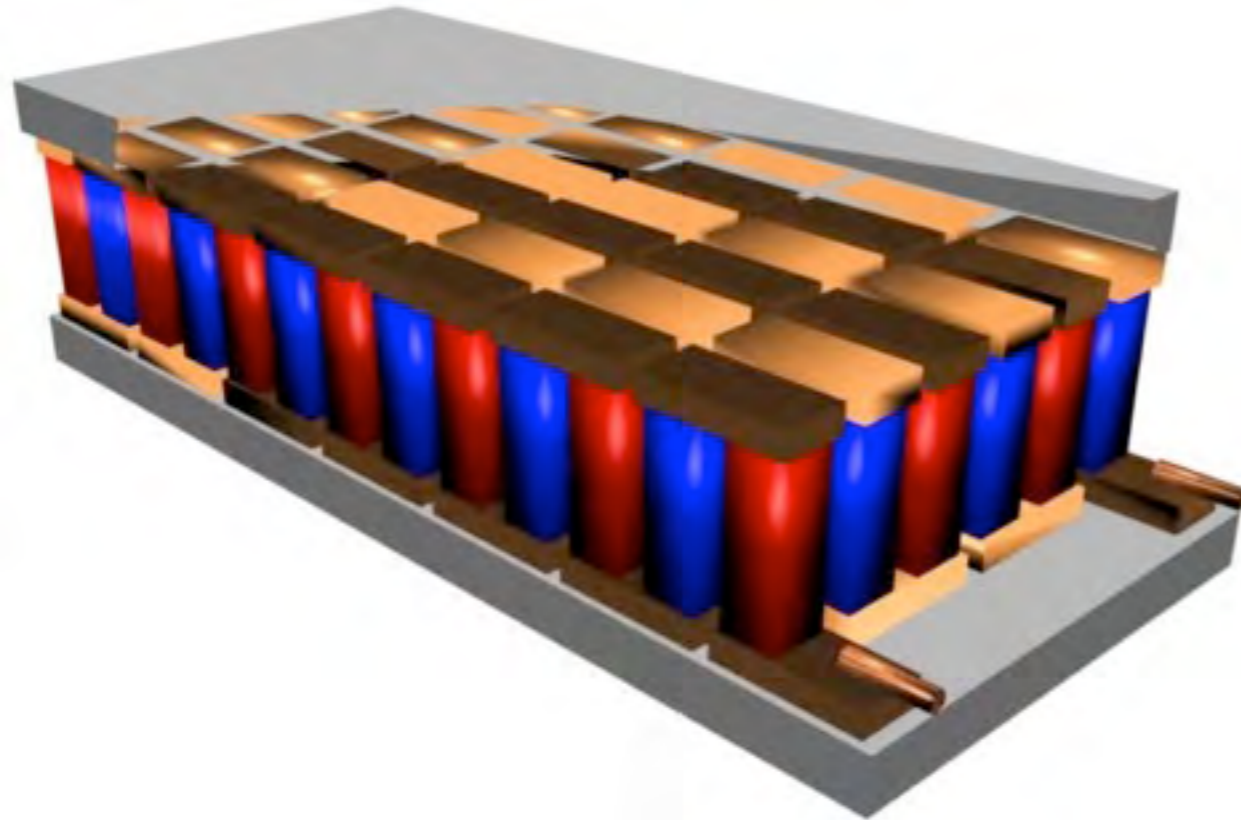
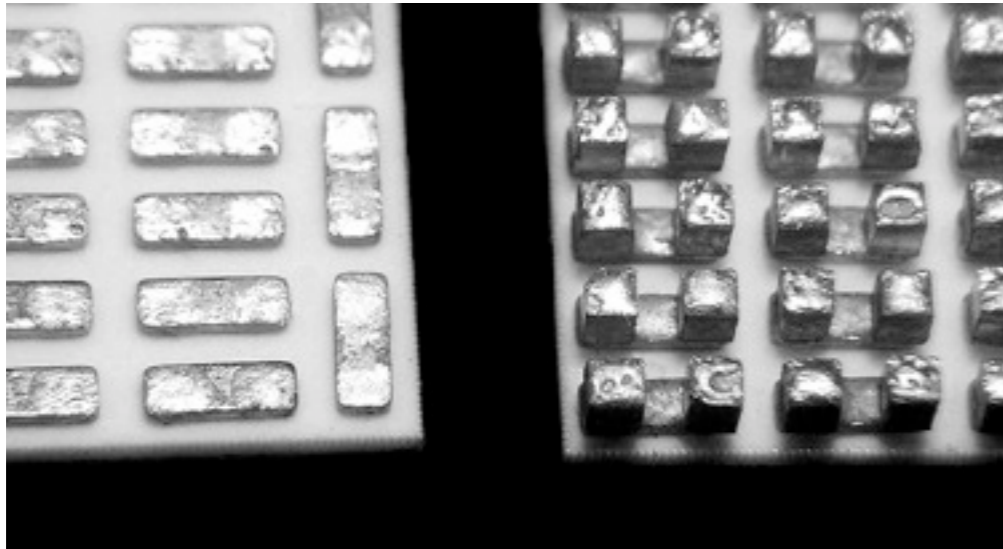


Thermoelectric Energy Harvesting



Douglas J. Paul

**School of Engineering
University of Glasgow, U.K.**



***D.J. Paul
School of Engineering***



**University
of Glasgow**

- **Established in 1451**
- **6 Nobel Laureates**
- **16,500 undergraduates, 5,000 graduates and 5,000 adult students**
- **£130M research income pa**



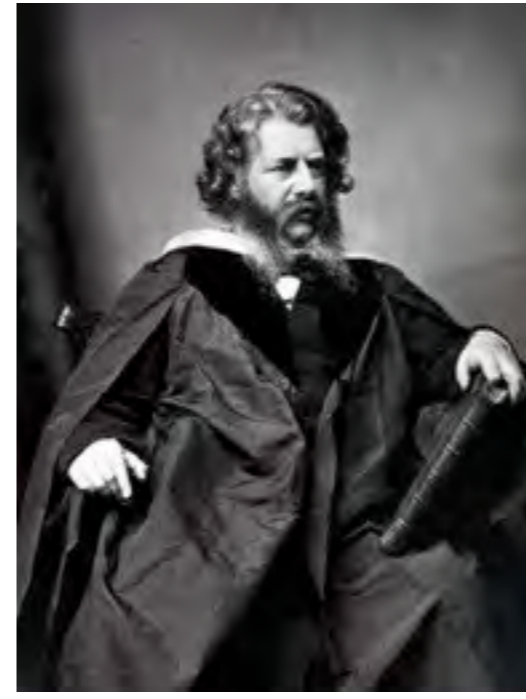
- **400 years in High Street**
- **Moved to Gilmorehill in 1870**
- **Neo-gothic buildings by Gilbert Scott**



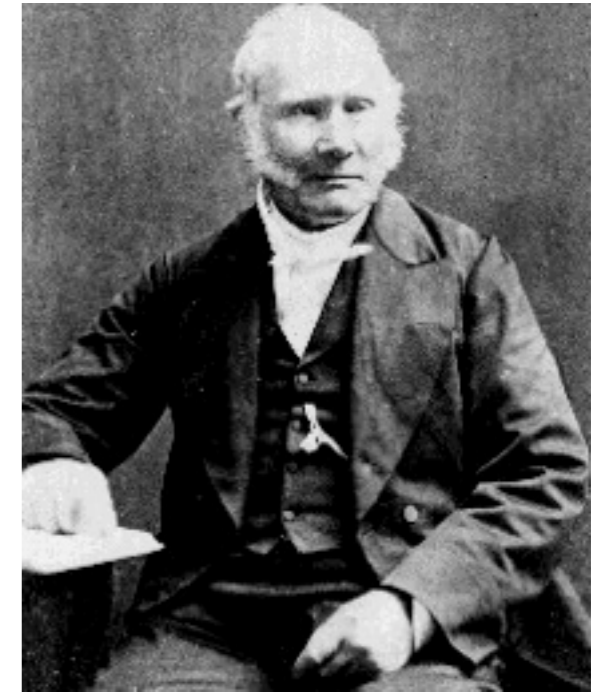
**William Thomson
(Lord Kelvin)**



James Watt



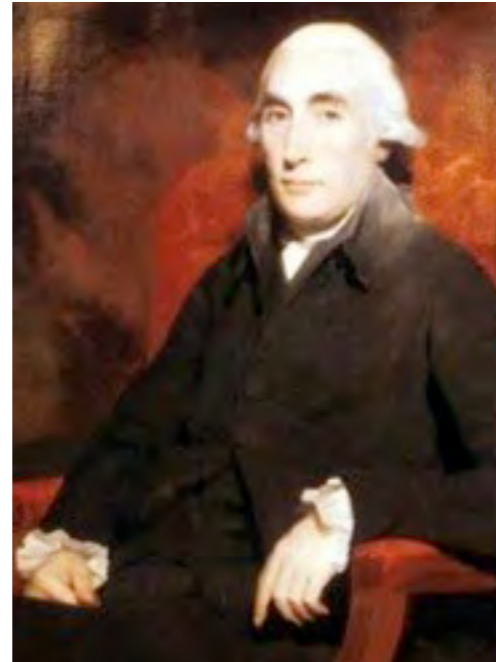
**William John
Macquorn Rankine**



Rev Robert Stirling



Rev John Kerr



Joseph Black

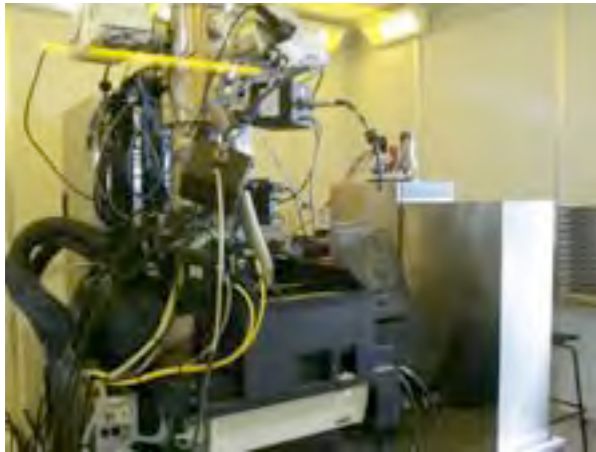


John Logie Baird



Adam Smith

Vistec VB6 & EBPG5



E-beam lithography



Süss MA6 optical & nanoimprint lithography

8 RIE / PECVD



- **750m² cleanroom - pseudo-industrial operation**
- **18 technicians + 5 research technologists
(PhD level process engineers)**
- **Large number of process modules**
- **Processes include: Si/SiGe/Ge, III-V, II-VI, piezoelectric MMICs, optoelectronics, metamaterials, MEMS**
- **Commercial access through KNT**
- **<http://www.jwnc.gla.ac.uk>**

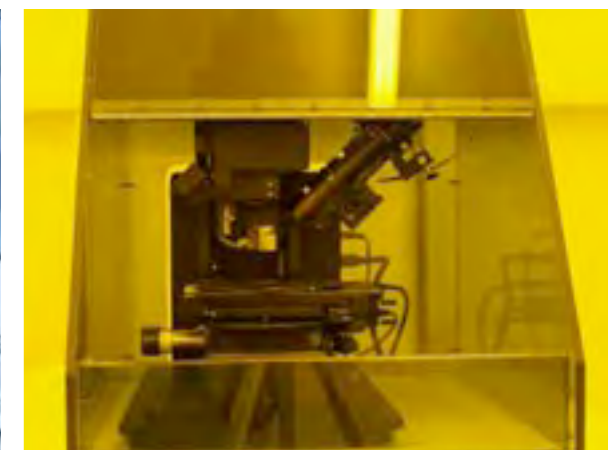
3 Metal dep tools



4 SEMs: Hitachi S4700



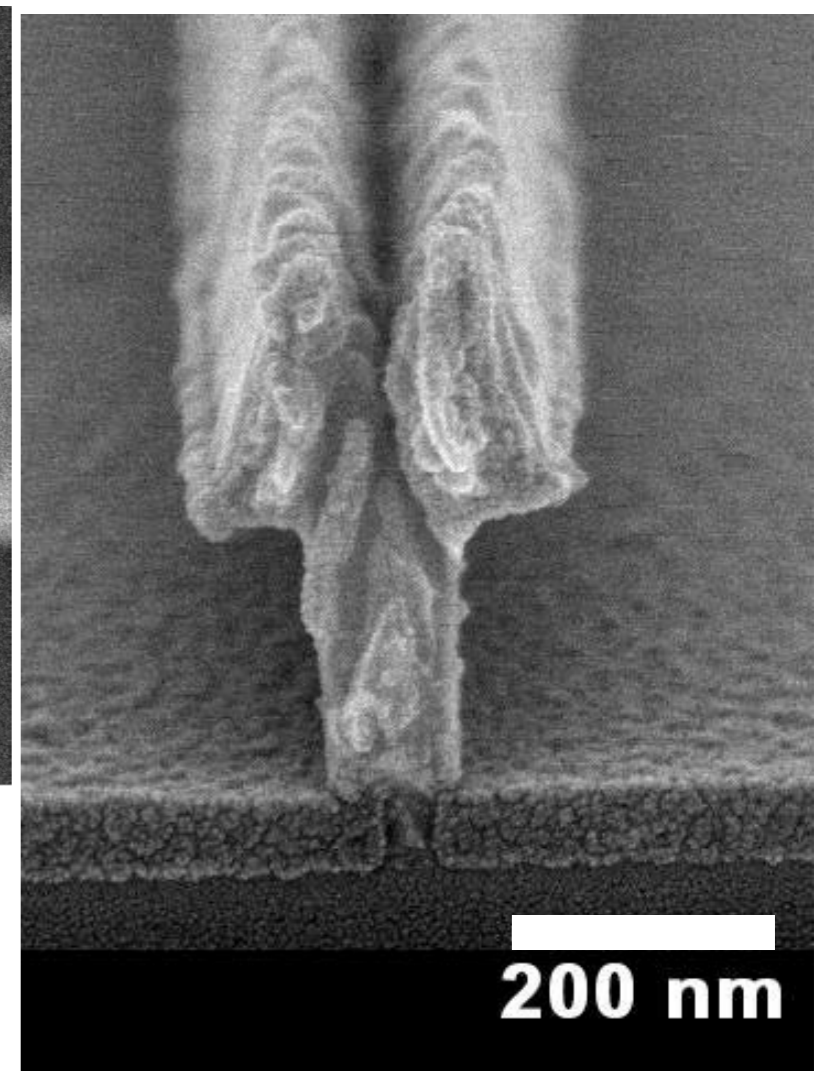
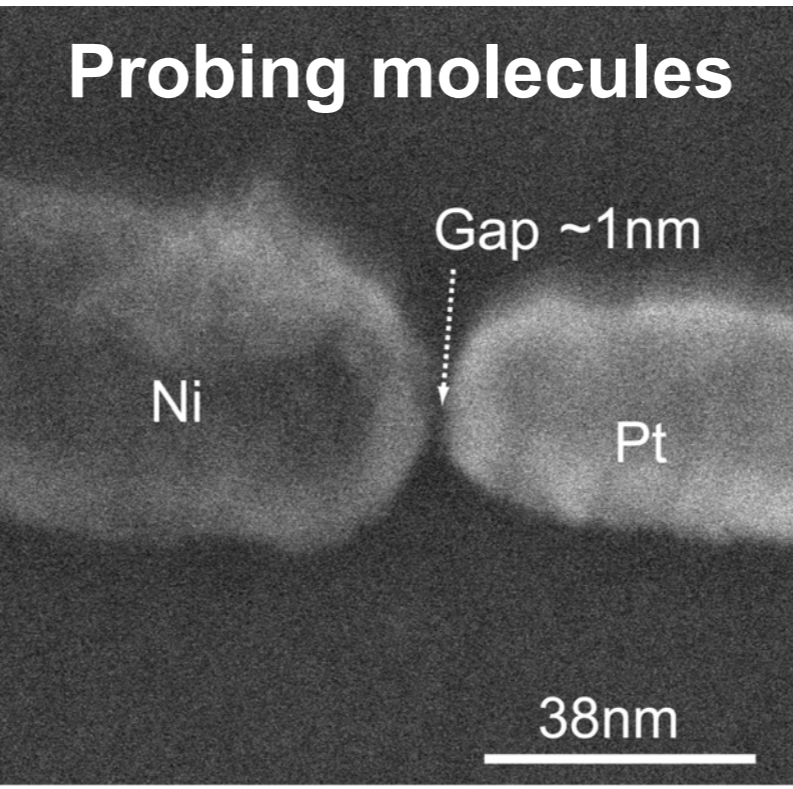
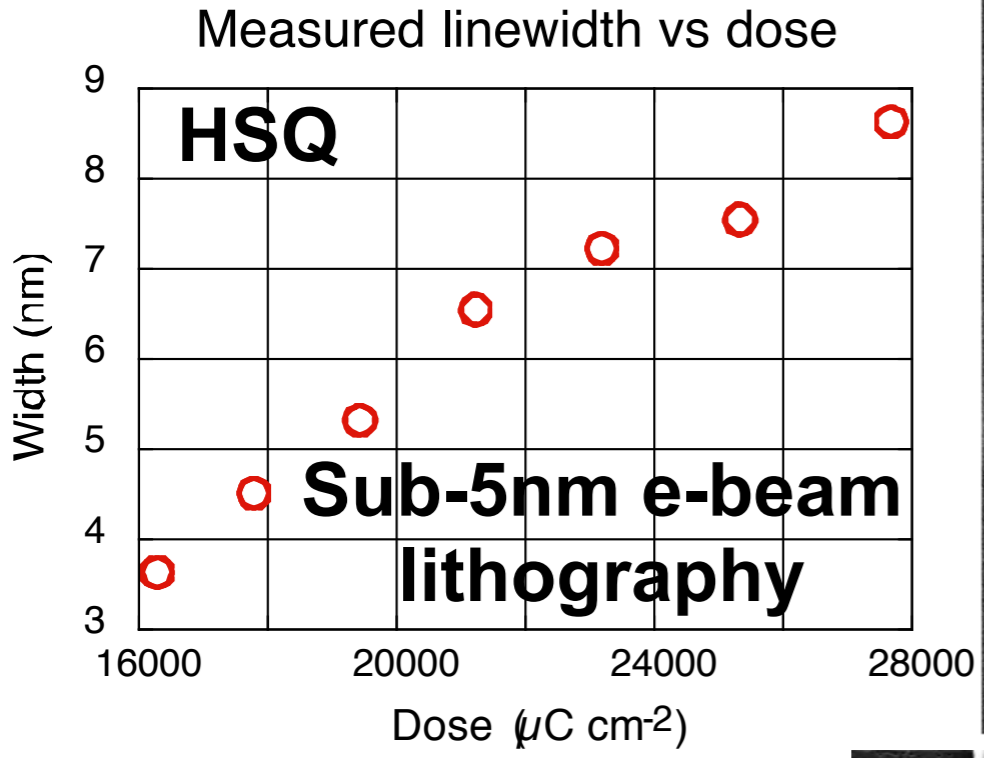
Veeco: AFMs



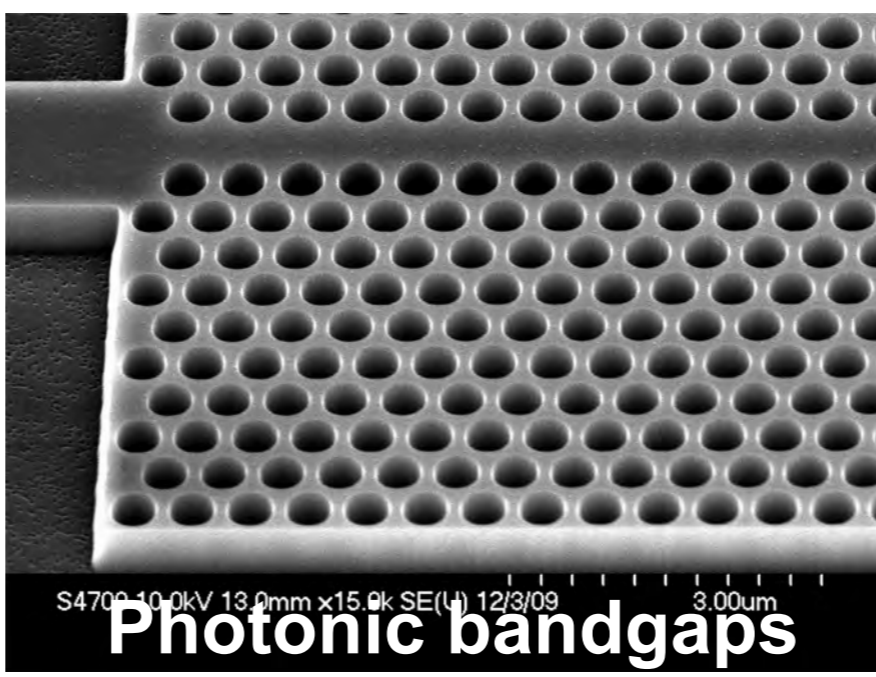
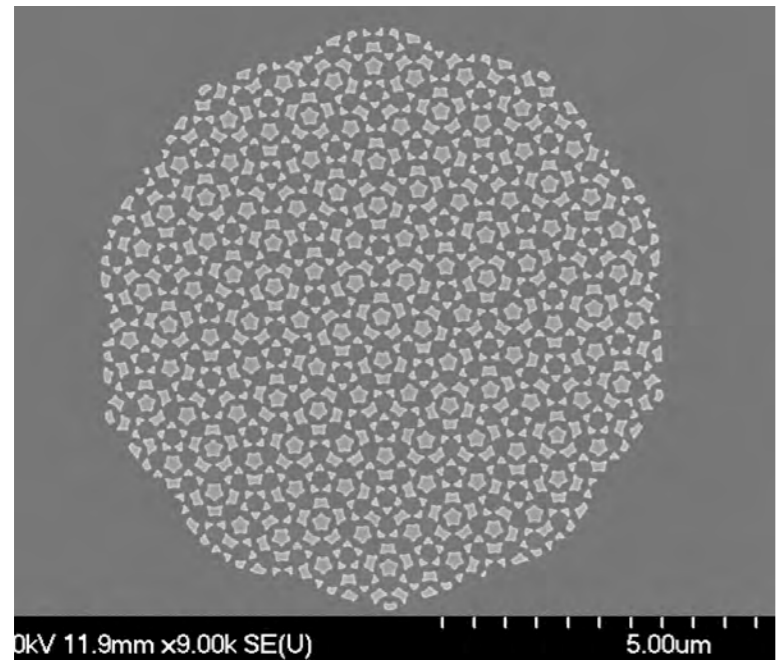
- **In School of Engineering**
- **£53M active research grant portfolio (£14M pa, industry ~£1M)**
- **2nd highest cited E&EE Department in UK after Cambridge**

World Bests:

- **Smallest electron-beam lithography pattern – 3 nm**
- **Best layer-to-layer alignment accuracy (0.42 nm rms)**
- **Smallest diamond transistor (50 nm gate length)**
- **Lowest loss silicon optical waveguide (< 0.9 dB/cm)**
- **Fastest mode locked laser (2.1 THz)**
- **Highest Q silicon nanowire cavity (Q = 177,000)**

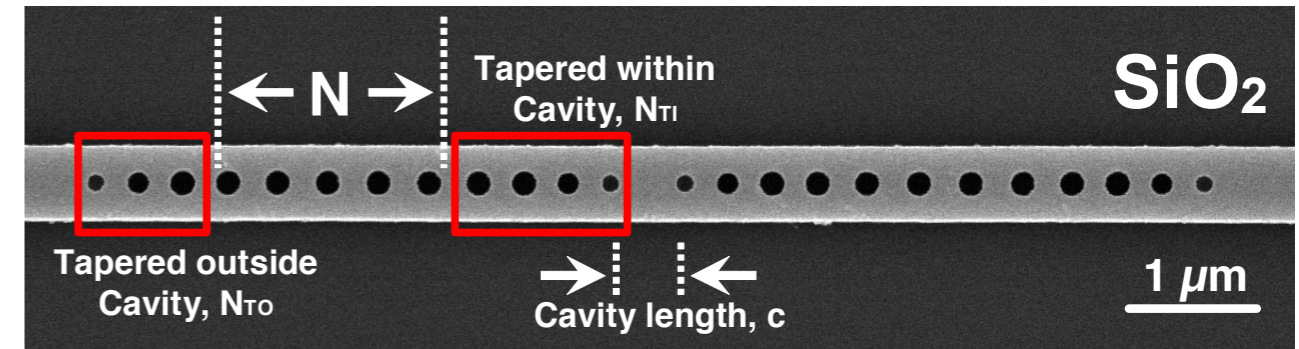


Penrose tile:
0.46 nm rms alignment



22 nm T-gate HEMTs

Si nanowire cavity
Q = 177,000



Thermoelectrics

- **History: Seebeck effect 1822**
- **heat → electric current**
- **Peltier (1834): current → cooling**
- **Physics: Thomson (Lord Kelvin) 1850s**
- **Ioffe: physics (1950s), first devices 1950s - 1960s, commercial modules 1960s**



Present applications:

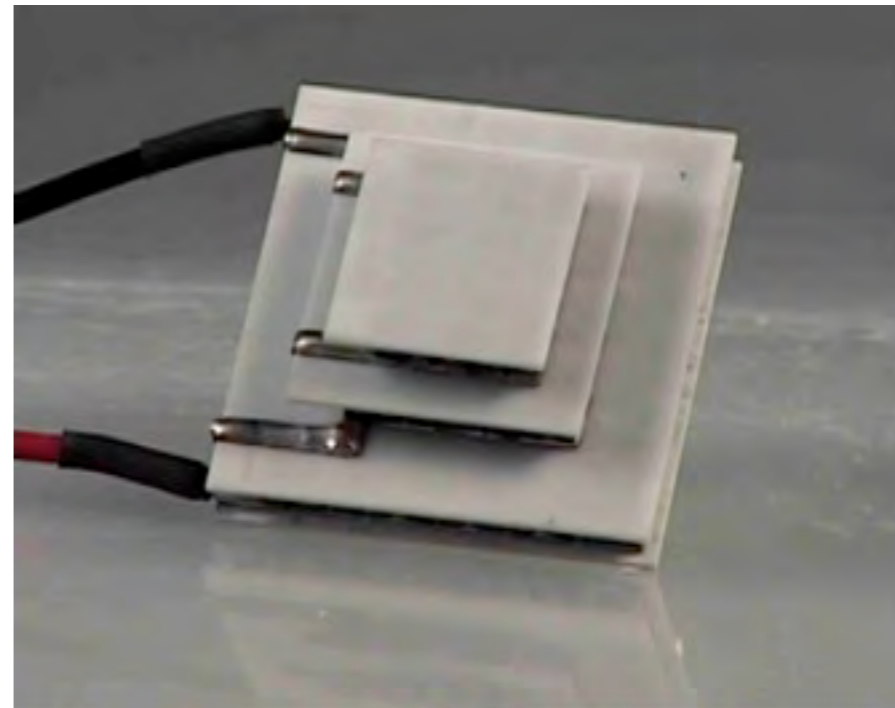
- **Peltier coolers (telecoms lasers, rf / mm-wave electronics, beer! etc...)**
- **Thermoelectric generators – some industrial energy harvesting**

As renewable energy interest increases, renewed interest in thermoelectrics

Why Use Thermoelectrics?

- No moving parts → no maintenance
- Peltier Coolers: fast feedback control mechanisms → $\Delta T < 0.1 \text{ }^\circ\text{C}$
- Scalable to the nanoscale → physics still works (some enhancements) but **power** \propto **area**
- Most losses result in heat
- Most heat sources are “static”
- Waste heat from many systems could be harvested

home, industry, background



Background Physics

Fourier thermal transport

$$Q = -\kappa A \nabla T$$

Q = heat (power i.e energy / time)

E_F = chemical potential

V = voltage

A = area

q = electron charge

g(E) = density of states

k_B = Boltzmann's constant

Joule heating

$$Q = I^2 R$$

R = resistance

I = current (**J** = I/A)

κ = thermal conductivity

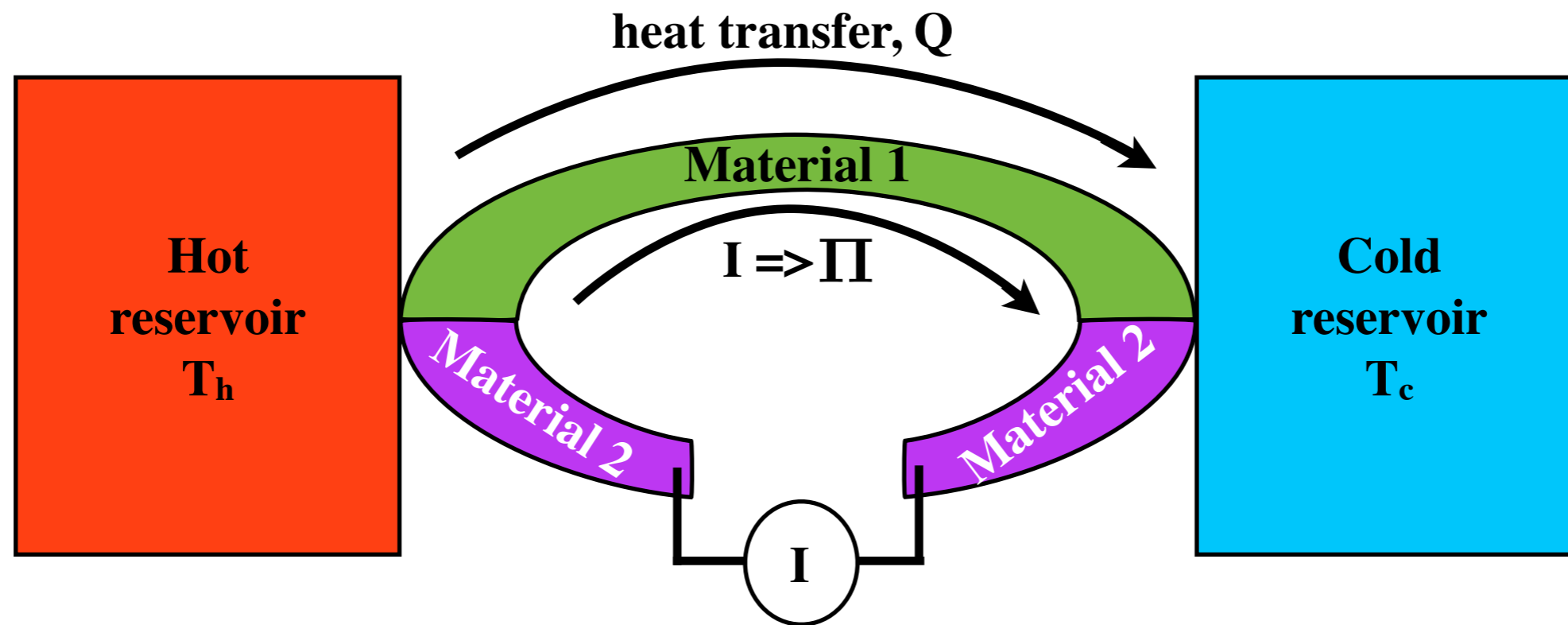
σ = electrical conductivity

α = Seebeck coefficient

f(E) = Fermi function

μ(E) = mobility

The Peltier Effect



Peltier coefficient, $\Pi = \frac{Q}{I}$

units: $W/A = V$

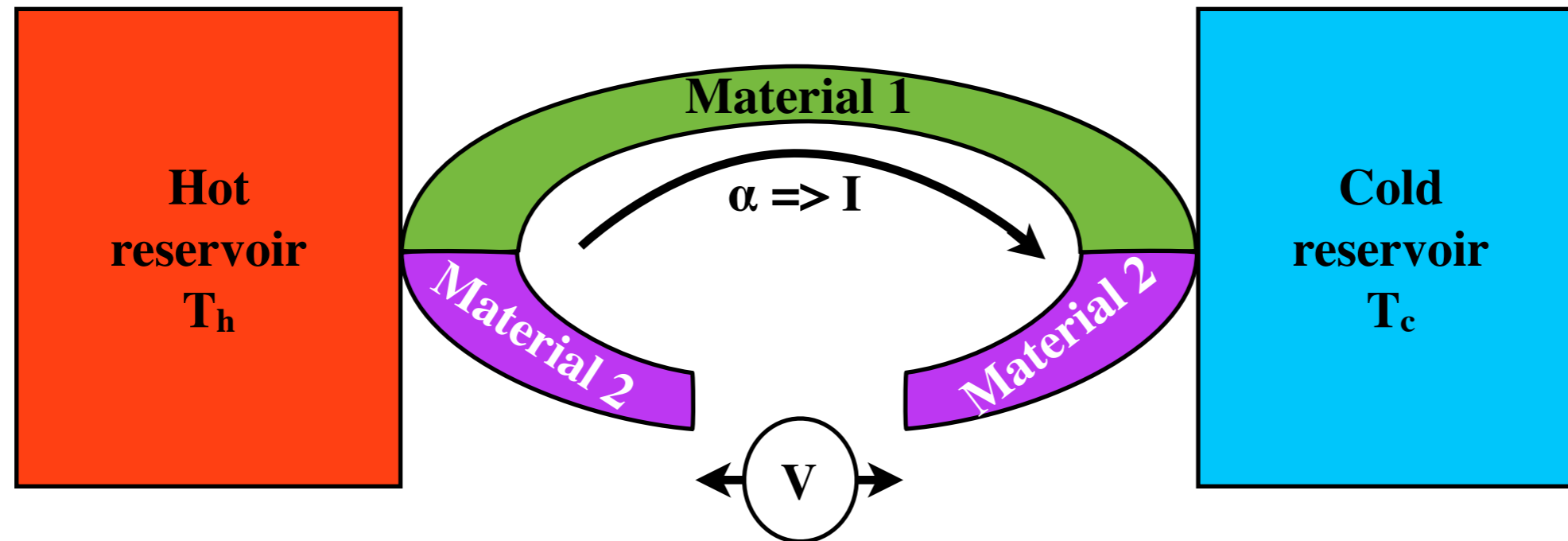
- Peltier coefficient is the energy carried by each electron per unit charge & time

The Peltier Coefficient

- Full derivation uses relaxation time approximation & Boltzmann equation
- $$\Pi = -\frac{1}{q} \int (\mathbf{E} - \mathbf{E}_F) \frac{\sigma(\mathbf{E})}{\sigma} d\mathbf{E}$$
- $$\sigma = \int \sigma(\mathbf{E}) d\mathbf{E} = q \int g(\mathbf{E}) \mu(\mathbf{E}) f(\mathbf{E}) [1 - f(\mathbf{E})] d\mathbf{E}$$
- This derivation works well for high temperatures (> 100 K)
- At low temperatures phonon drag effects must be added

see H. Fritzsche, Solid State Comm. 9, 1813 (1971)

The Seebeck Effect

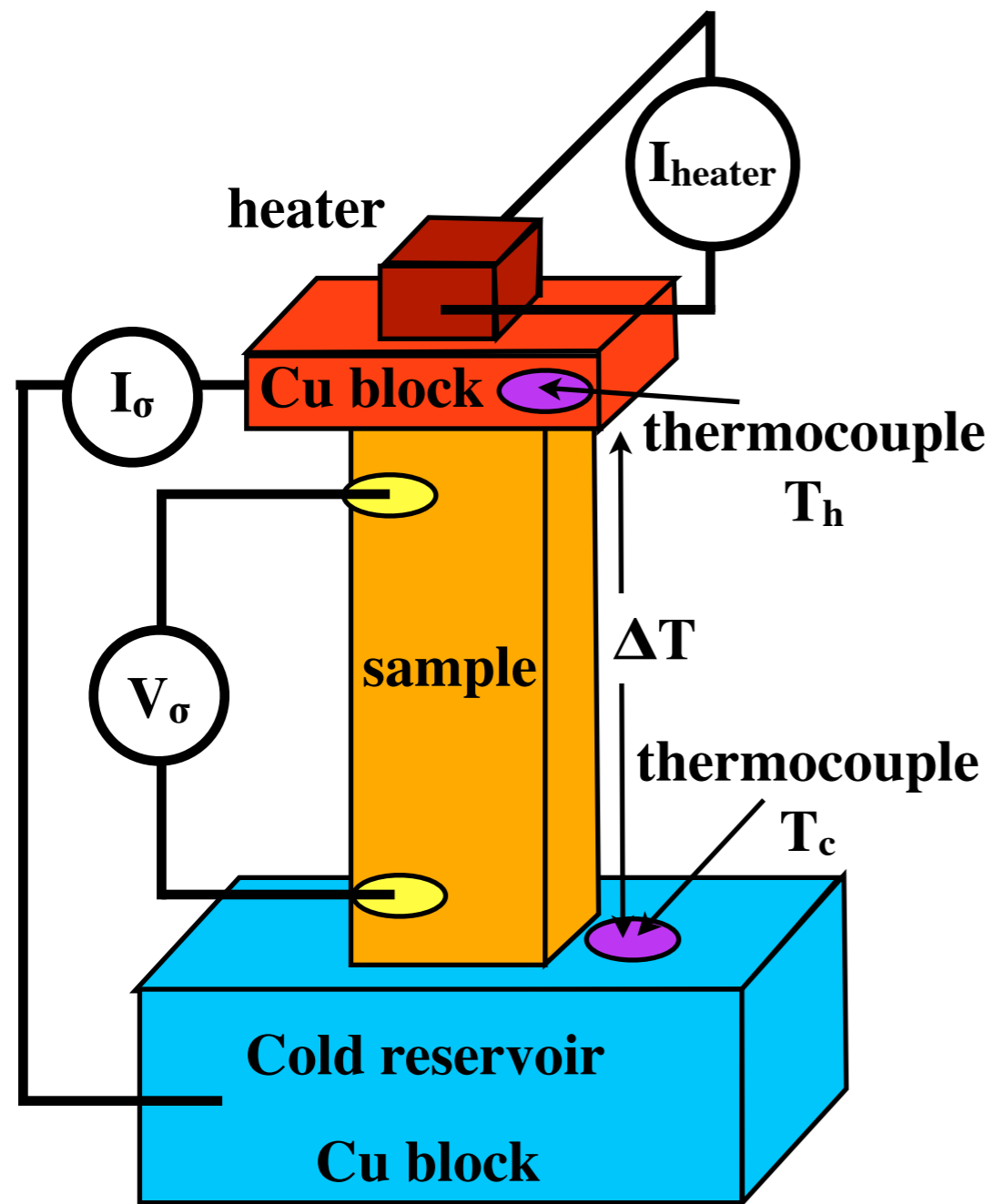


● Open circuit voltage, $V = \alpha (T_h - T_c) = \alpha \Delta T$

Seebeck coefficient, $\alpha = \frac{dV}{dT}$ units: V/K

● Seebeck coefficient = $\frac{1}{q}$ x entropy $\left(\frac{Q}{T}\right)$ transported with charge carrier

Measuring Seebeck Coefficient



- Physically heat one side of sample
- Cold sink at the other side of sample
- Thermocouples top and bottom to measure ΔT
- 4 terminal electrical measurements

The Seebeck Coefficient

- Full derivation uses relaxation time approximation, Boltzmann equation

- $$\alpha = -\frac{k_B}{q} \int (\mathbf{E} - \mathbf{E}_F) \frac{\sigma(\mathbf{E})}{\sigma} d\mathbf{E}$$

$$\sigma = \int \sigma(\mathbf{E}) d\mathbf{E} = q \int g(\mathbf{E}) \mu(\mathbf{E}) f(\mathbf{E}) [1 - f(\mathbf{E})] d\mathbf{E}$$

For electrons in the conduction band, E_c of a semiconductor

- $$\alpha = -\frac{k_B}{q} \left[\frac{E_c - E_F}{k_B T} + \frac{\int_0^\infty \frac{(E - E_c)}{k_B T} \sigma(E) dE}{\int_0^\infty \sigma(E) dE} \right] \quad \text{for } E > E_c$$

see H. Fritzsche, Solid State Comm. 9, 1813 (1971)

The Seebeck Coefficient for Metals

- $f(1 - f) = -k_B T \frac{df}{dE}$

- Expand $g(E)\mu(E)$ in Taylor's series at $E = E_F$

- $$\alpha = -\frac{\pi^2}{3} \frac{k_B}{q} k_B T \left[\frac{d \ln(\mu g)}{dE} \right]_{E_F} \quad \text{(Mott's formula)}$$

Mott and Jones, 1958

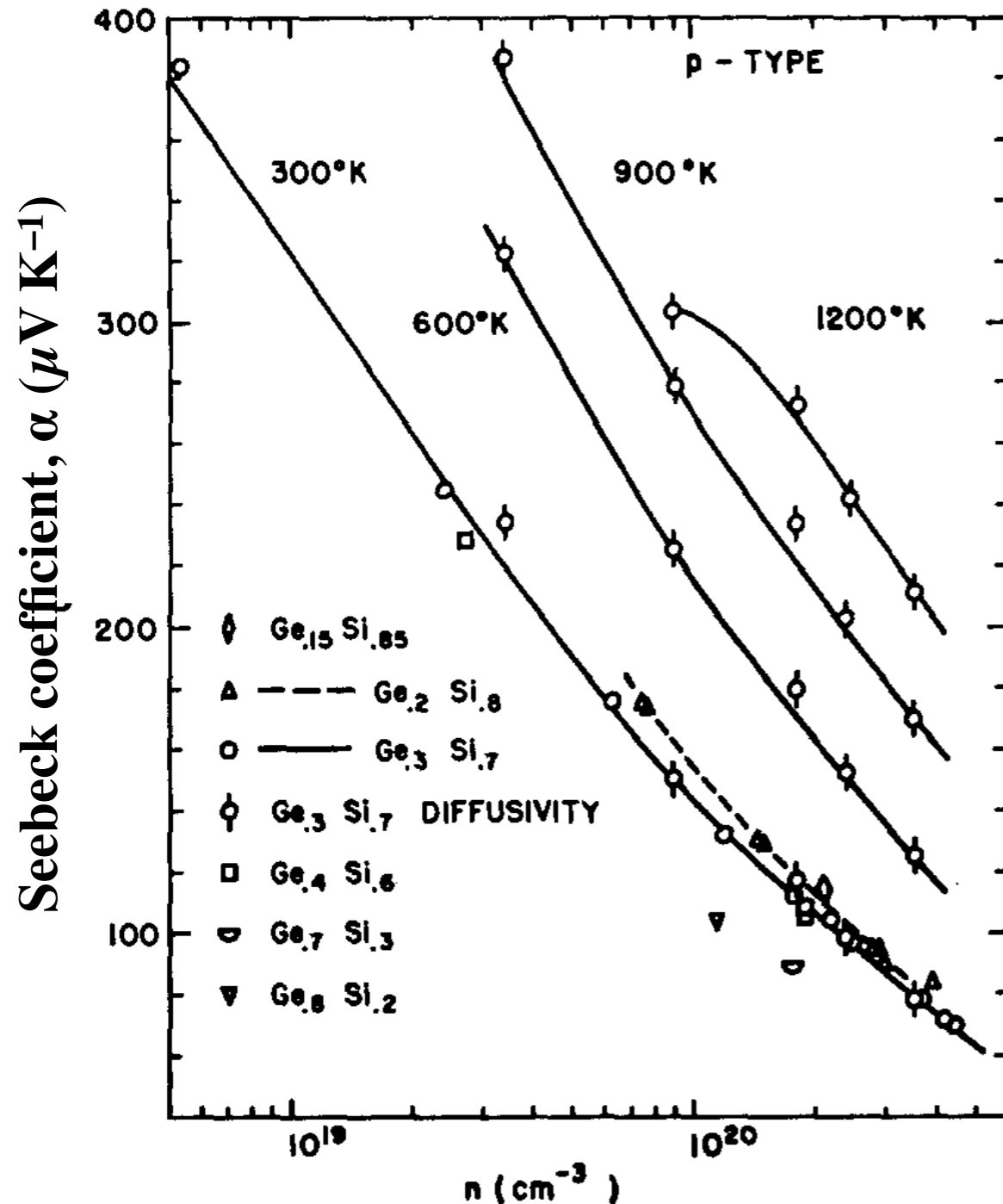
- i.e. Seebeck coefficient depends on the asymmetry of the current contributions above and below E_F

Using the energy-independent scattering approximation:

- $$\alpha = -\frac{8\pi^2 k_B^2}{3eh^2} m^* T \left(\frac{\pi}{3n} \right)^{\frac{2}{3}} \quad \text{n=carrier density}$$

M. Cutler et al., Phys. Rev. 133, A1143 (1964)

Semiconductor Example: SiGe Alloys

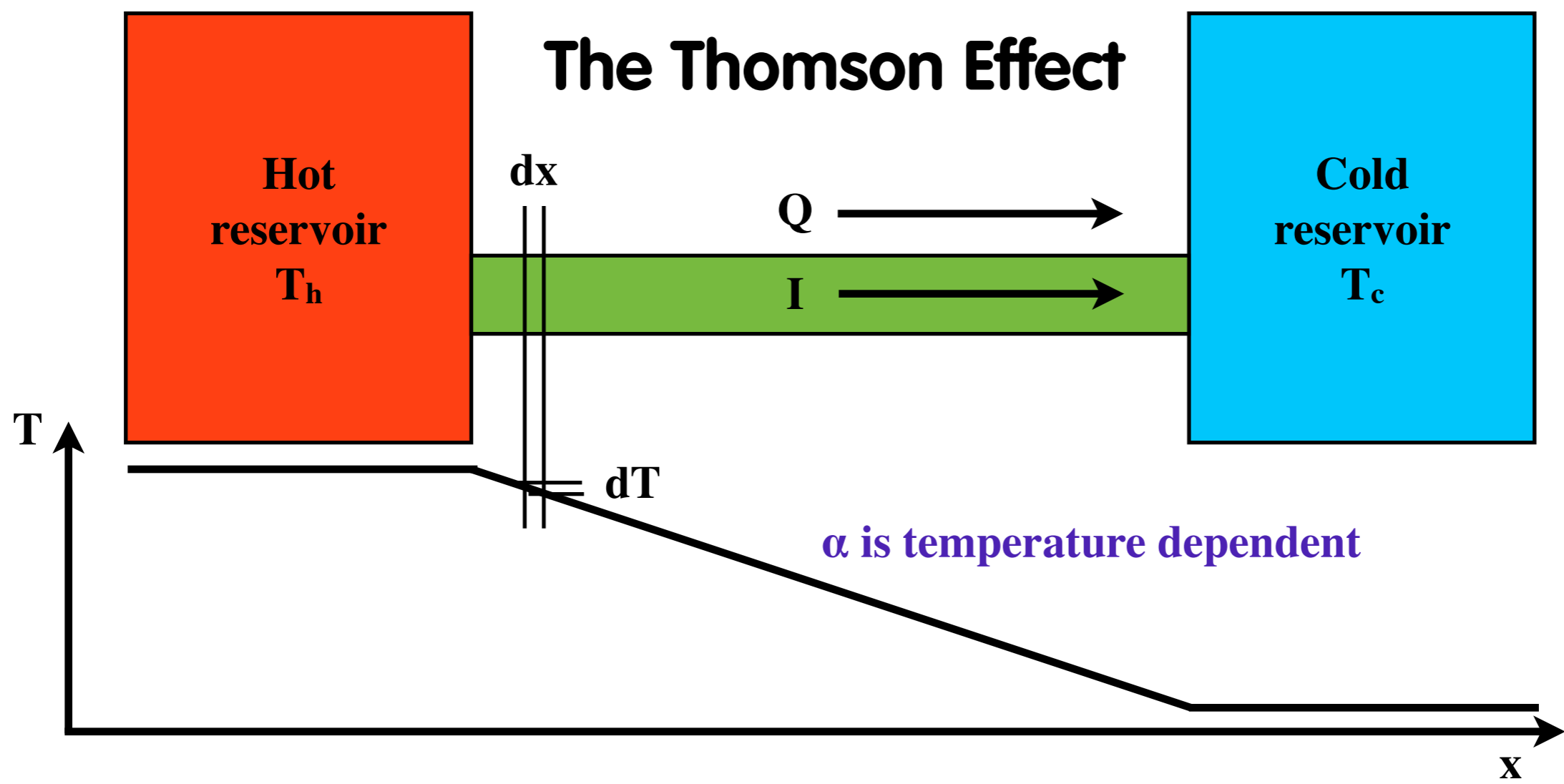


J.P. Dismukes et al., J. Appl. Phys. 35, 2899 (1964)

- Mott criteria $\sim 2 \times 10^{18} \text{ cm}^{-3}$
- Degenerately doped p- $\text{Si}_{0.7}\text{Ge}_{0.3}$
- α decreases for higher n
- For SiGe, α increases with T

$$\alpha = \frac{8\pi^2 k_B^2}{3eh^2} m^* T \left(\frac{\pi}{3n} \right)^{\frac{2}{3}}$$

The Thomson Effect



● $\frac{dQ}{dx} = \beta I \frac{dT}{dx}$

Thomson coefficient, β $dQ = \beta I dT$

units: V/K

The Kelvin Relationships

- Derived using irreversible thermodynamics

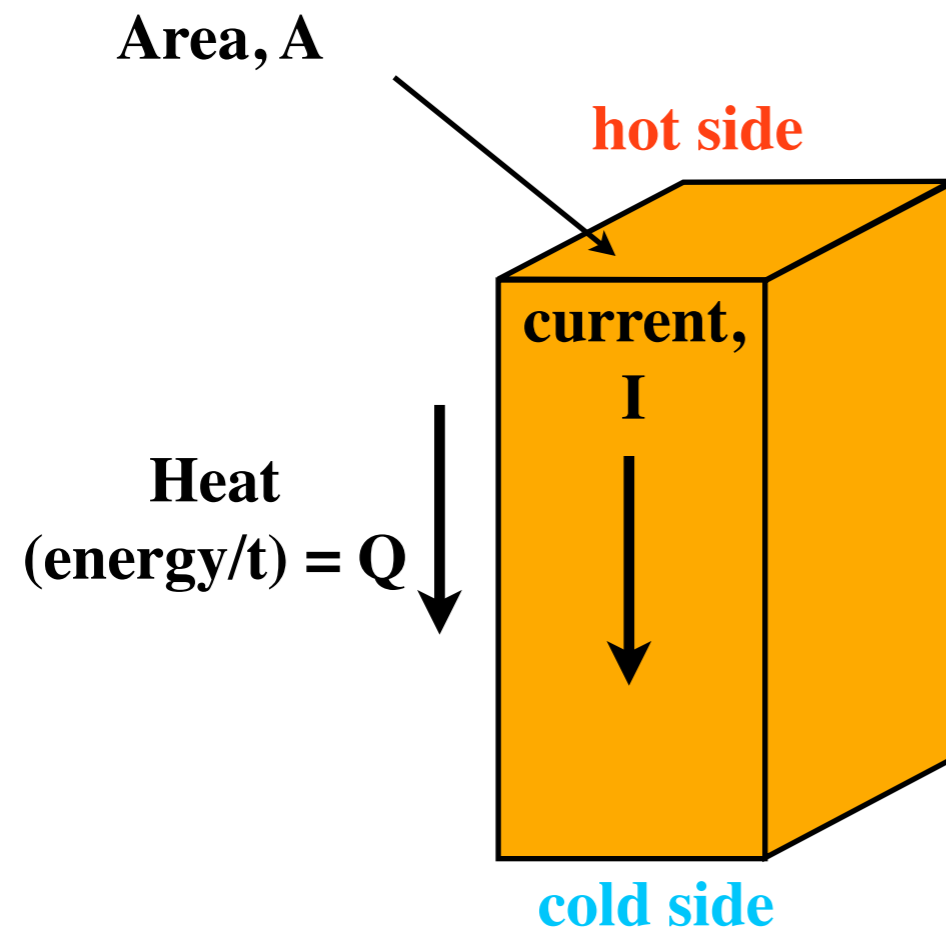
$$\Pi = \alpha T$$

$$\beta = T \frac{d\alpha}{dT}$$

- These relationships hold for all materials
- Seebeck, α is easy to measure experimentally
- Therefore measure α to obtain Π and β

Peltier Effect, Heat Flux and Temperature

- If a current of I flows through a thermoelectric material between hot and cold reservoirs:



- Heat flux per unit area =
(= Peltier + Fourier)

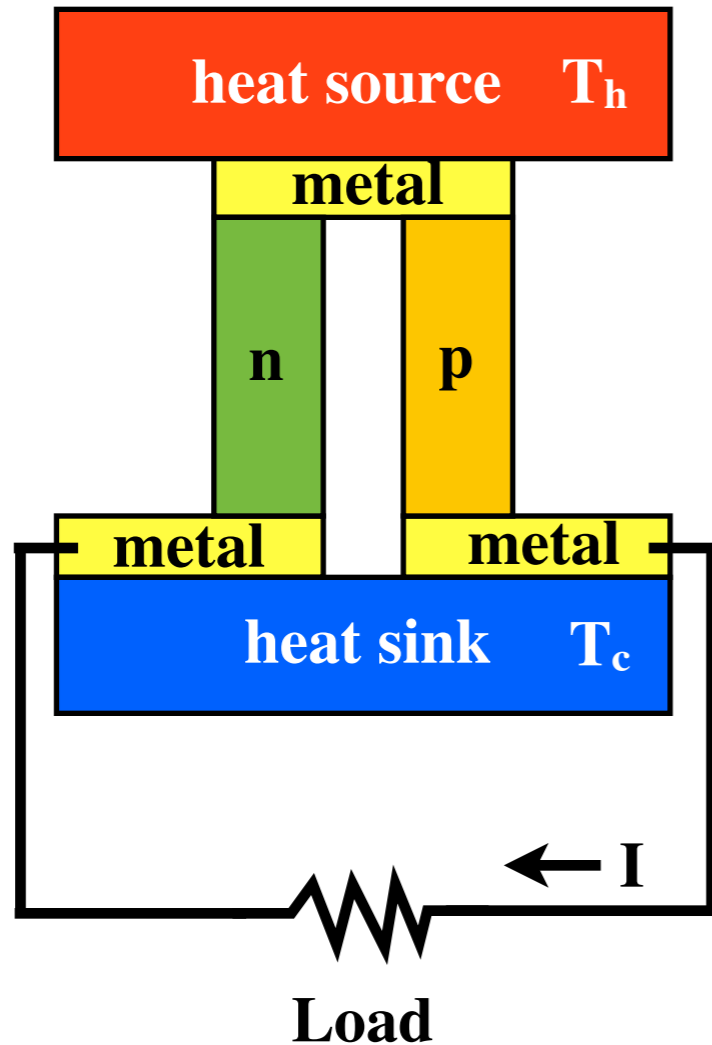
- $$\frac{Q}{A} = \Pi J - \kappa \nabla T$$

but $\Pi = \alpha T$ and $J = \frac{I}{A}$

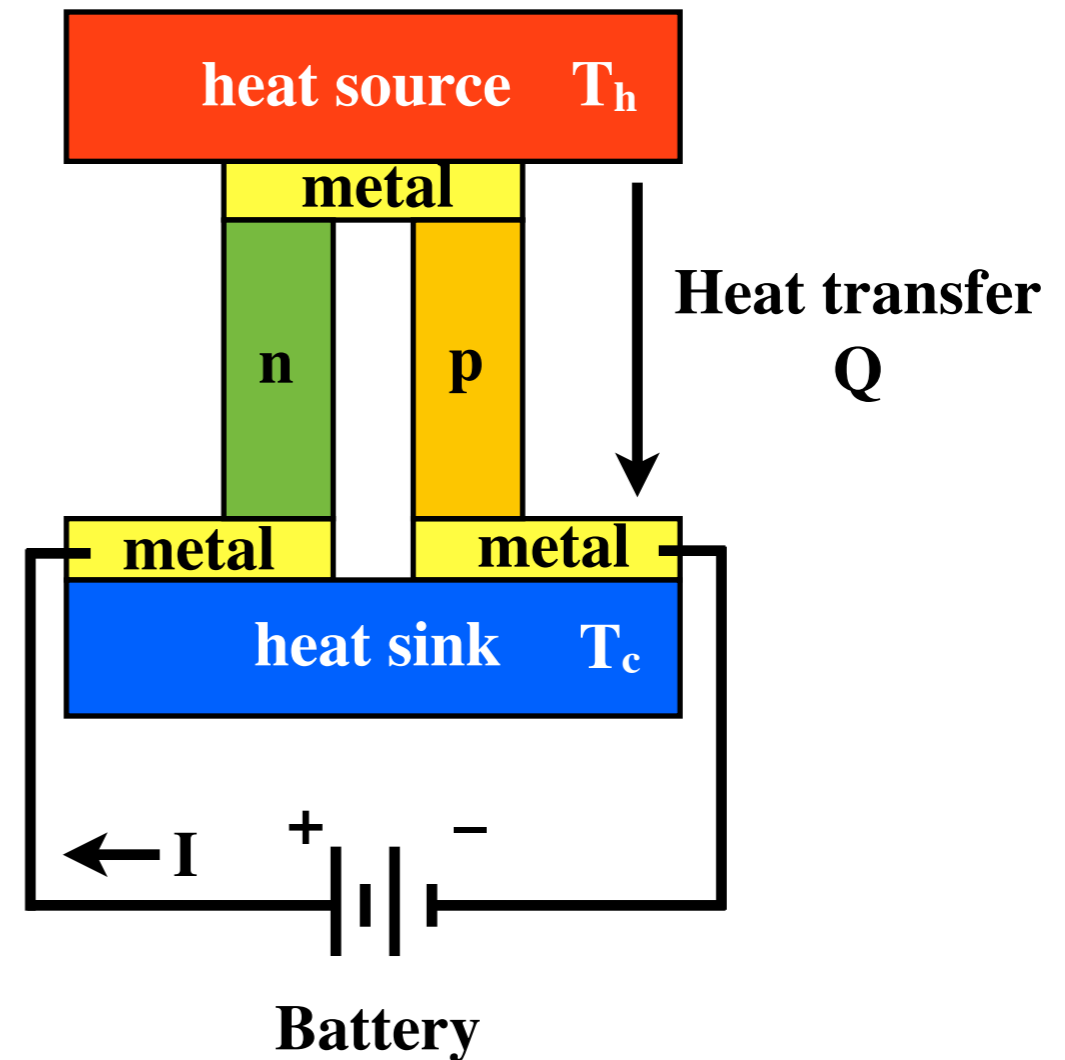
$$Q = \alpha IT - \kappa A \nabla T$$

Semiconductors and Thermoelectrics

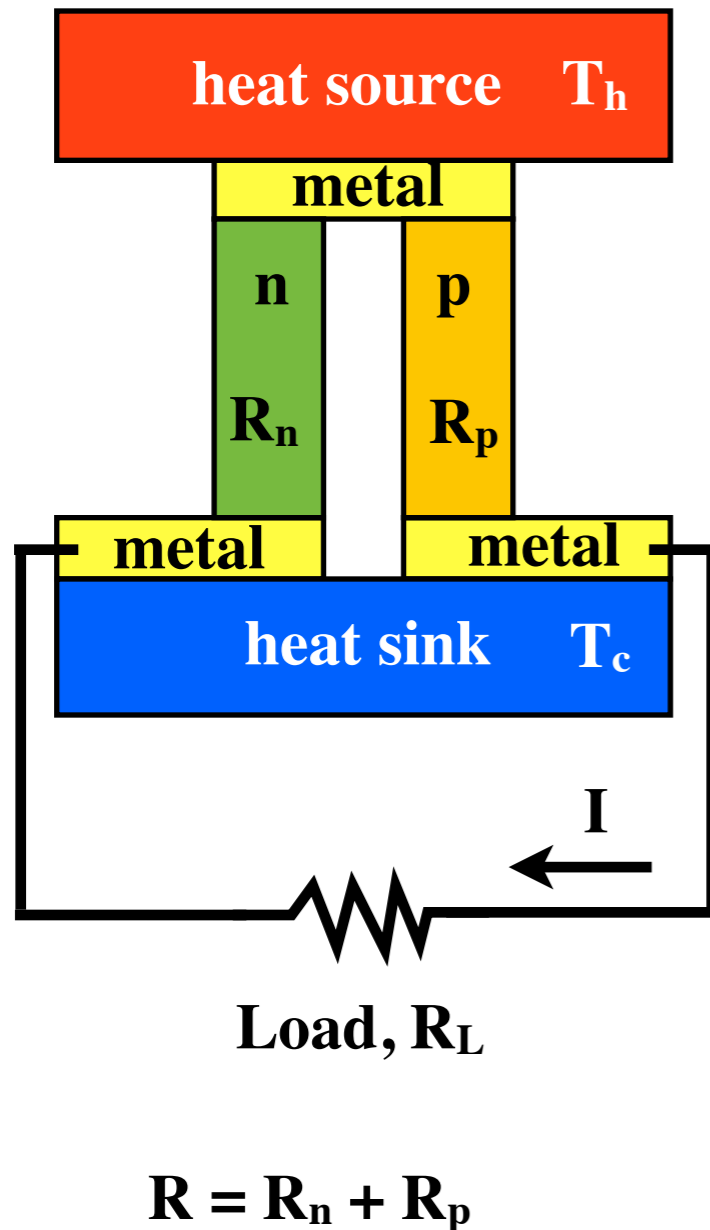
Seebeck effect:
electricity
generation



Peltier effect:
electrical
cooling



Conversion Efficiency

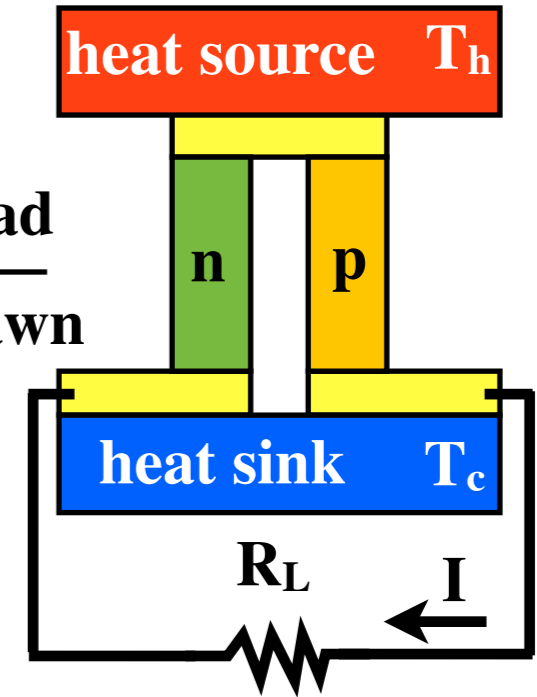


- $\eta = \frac{\text{power supplied to load}}{\text{heat absorbed at hot junction}}$
- Power to load (Joule heating) = $I^2 R_L$
- Heat absorbed at hot junction = Peltier heat + heat withdrawn from hot junction
- Peltier heat = $\Pi I = \alpha I T_h$
- $I = \frac{\alpha(T_h - T_c)}{R + R_L}$ (Ohms Law)
- Heat withdrawn from hot junction
 $= \kappa A (T_h - T_c) - \frac{1}{2} I^2 R$
↑
 NB half Joule heat returned to hot junction

Conversion Efficiency

$$\eta = \frac{\text{power supplied to load}}{\text{heat absorbed at hot junction}} = \frac{\text{power supplied to load}}{\text{Peltier} + \text{heat withdrawn}}$$

$$\eta = \frac{I^2 R_L}{\alpha I T_h + \kappa A (T_h - T_c) - \frac{1}{2} I^2 R}$$



For maximum value $\frac{d\eta}{d(\frac{R_L}{R})} = 0$

$$T = \frac{1}{2}(T_h + T_c)$$

$$\eta_{\max} = \frac{T_h - T_c}{T_h} \frac{\sqrt{1 + ZT} - 1}{\sqrt{1 + ZT} + \frac{T_c}{T_h}}$$

where $Z = \frac{\alpha^2}{R\kappa A} = \frac{\alpha^2 \sigma}{\kappa}$

= Carnot x Joule losses and irreversible processes

Thermoelectric Power Generating Efficiency

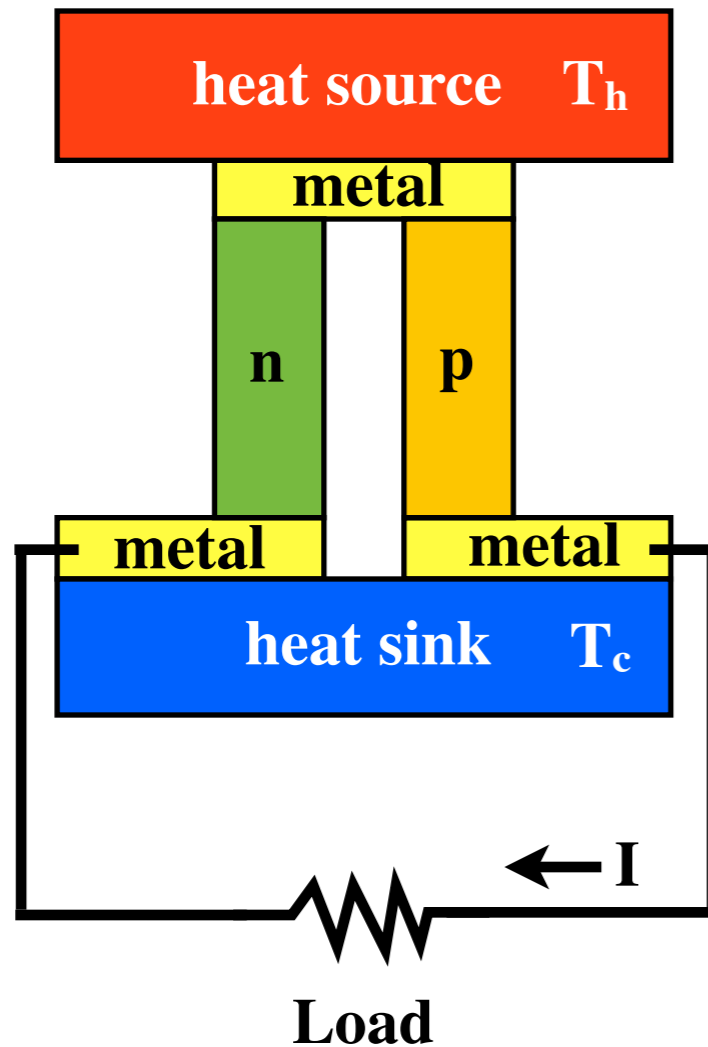
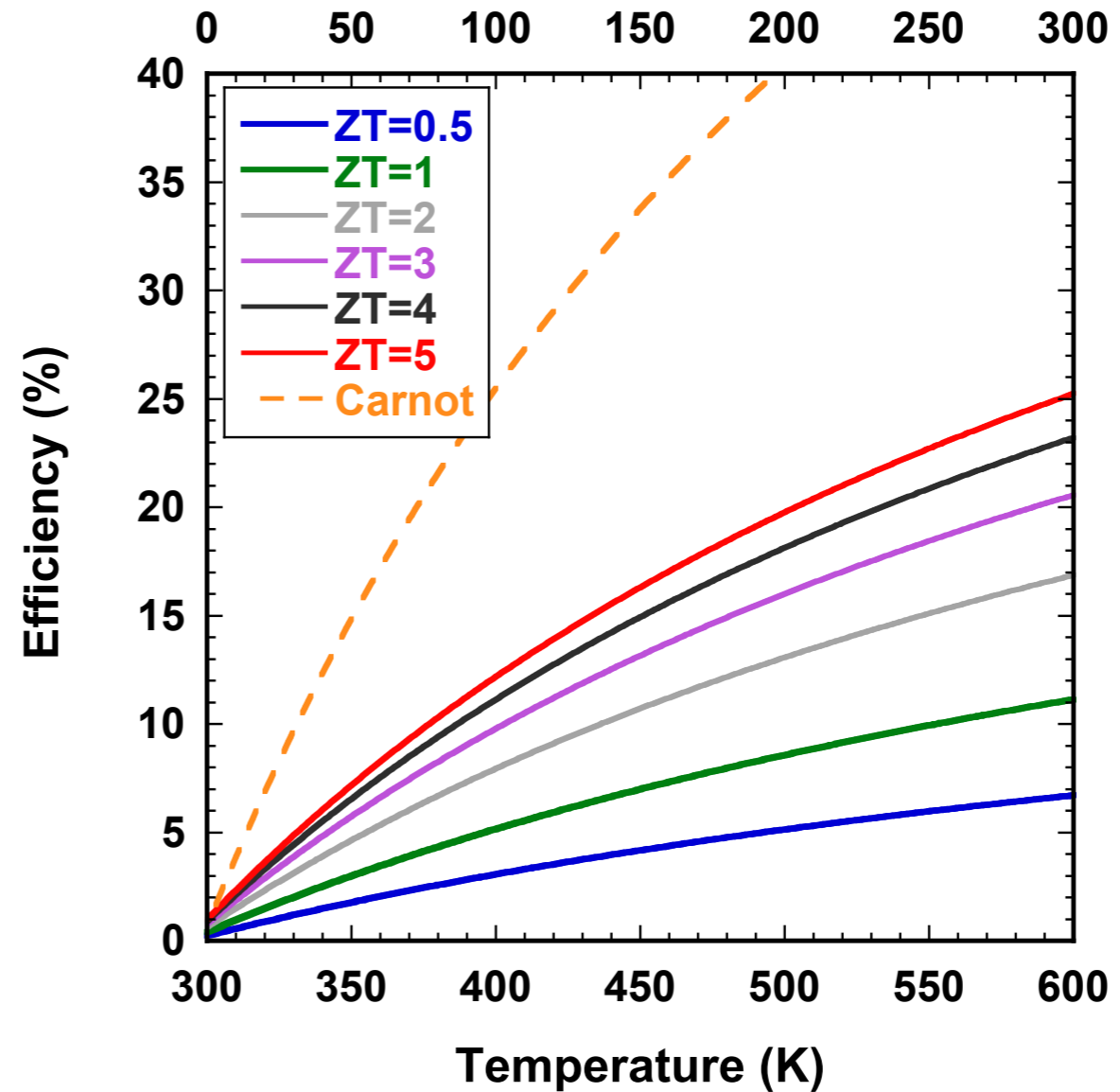


Figure of merit

$$ZT = \frac{\alpha^2 \sigma T}{\kappa}$$

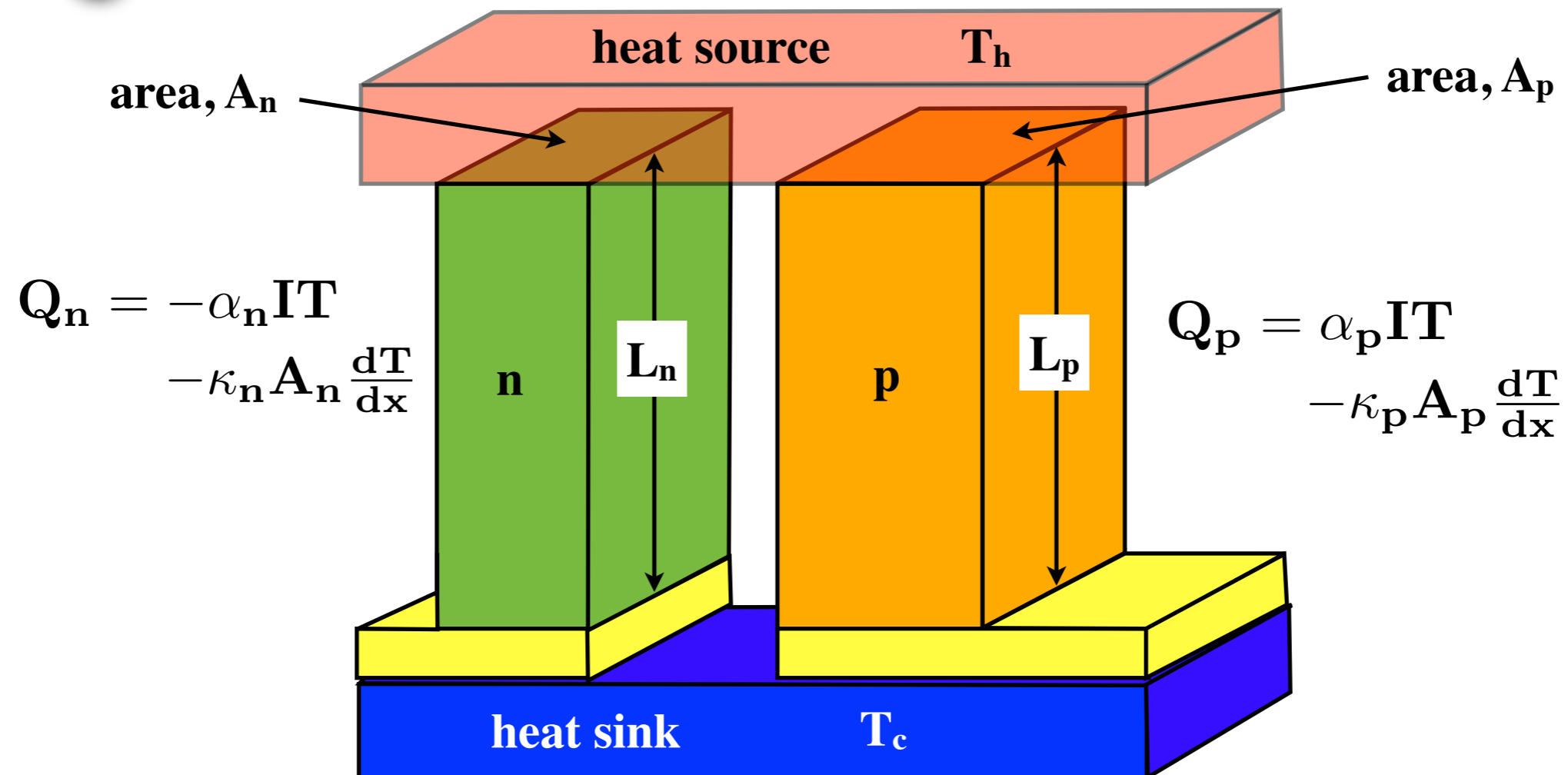
$$\eta = \frac{\Delta T}{T_h} \frac{\sqrt{1+ZT}-1}{\sqrt{1+ZT} + \frac{T_c}{T_h}}$$

Temperature difference, ΔT ($^{\circ}\text{C}$)



Heat Transfer in Thermoelectric Element

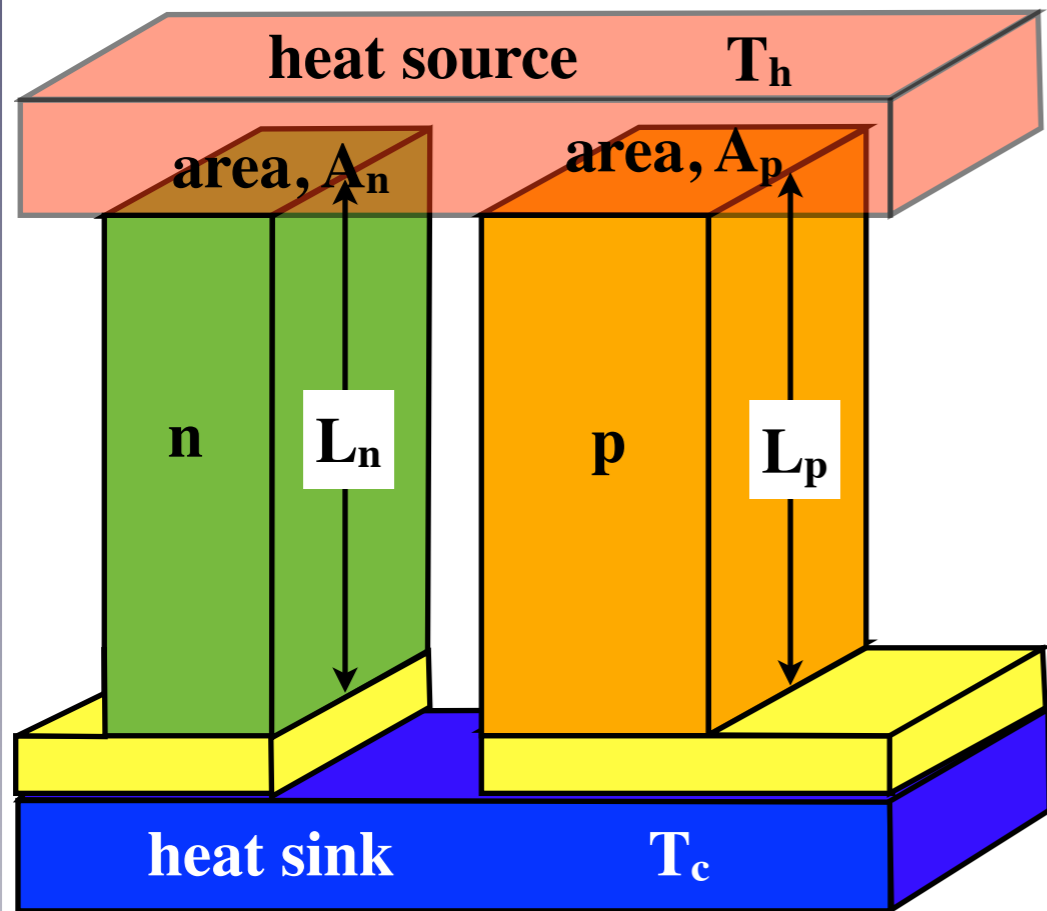
- But n-type and p-type materials are seldom identical



- Z for a couple depends on relative dimensions

- Z is maximum for $\frac{L_n A_p}{L_p A_n} = \sqrt{\frac{\sigma_n \kappa_n}{\sigma_p \kappa_p}}$

Maximising ZT for an Unbalanced Couple



$$\frac{L_n A_p}{L_p A_n} = \sqrt{\frac{\sigma_n \kappa_n}{\sigma_p \kappa_p}}$$

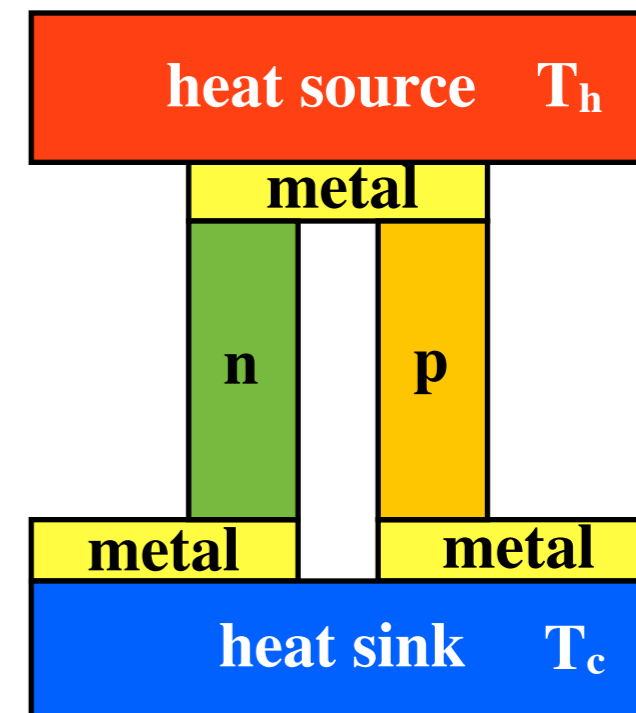
$$ZT = \frac{(\alpha_p - \alpha_n)^2 T}{\left[\sqrt{\frac{\kappa_p}{\sigma_p}} + \sqrt{\frac{\kappa_n}{\sigma_n}} \right]}$$



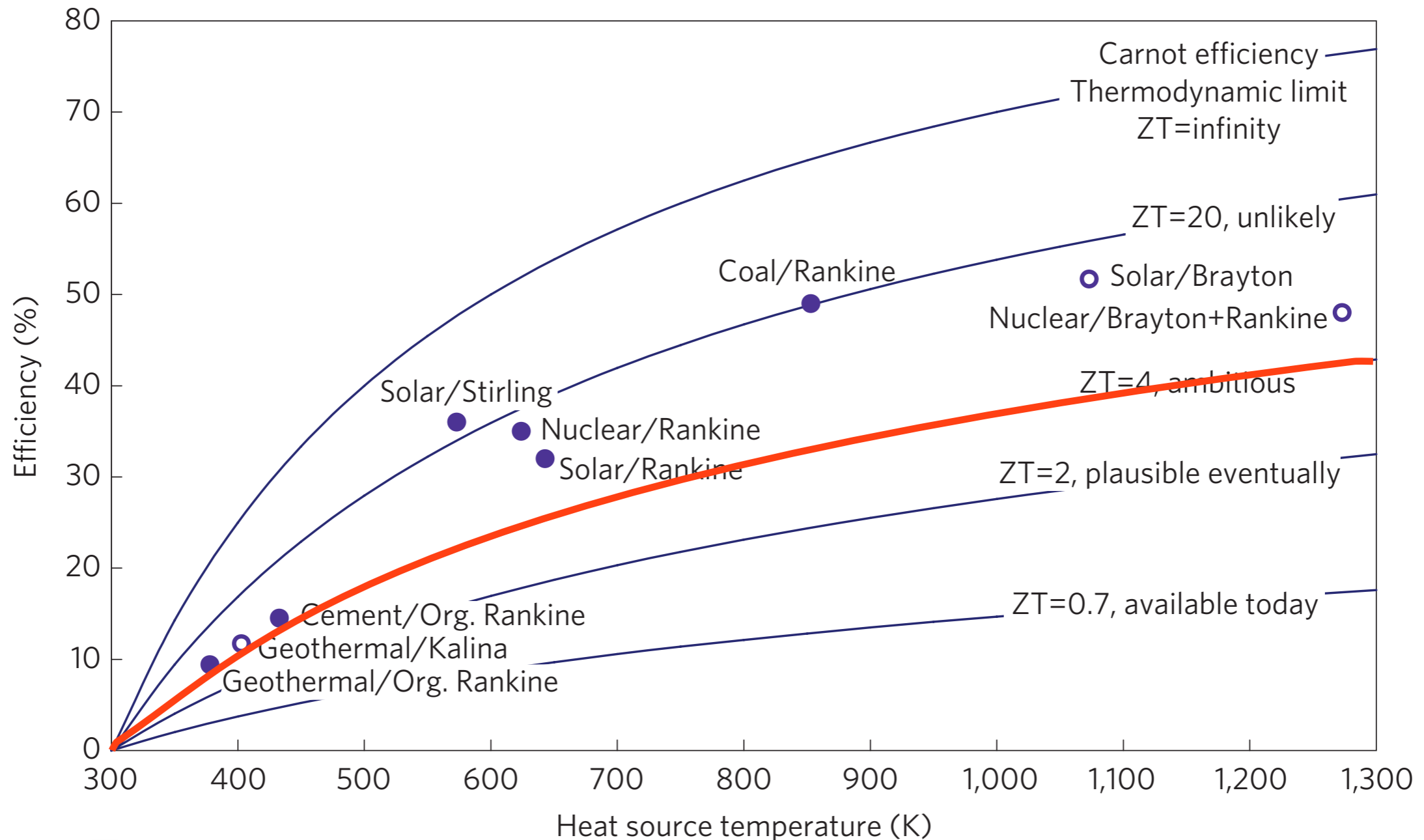
We need good ZT for both n- and p-type semiconductors

Maximum Temperature Drop

- As the system has thermal conductivity κ a maximum ΔT which can be sustained across a module is limited due to heat transport
- $$\Delta T_{\max} = \frac{1}{2} Z T_c^2$$
- The efficiency cannot be increased indefinitely by increasing T_h
- The thermal conductivity also limits maximum ΔT in Peltier coolers
- Higher ΔT_{\max} requires better Z materials



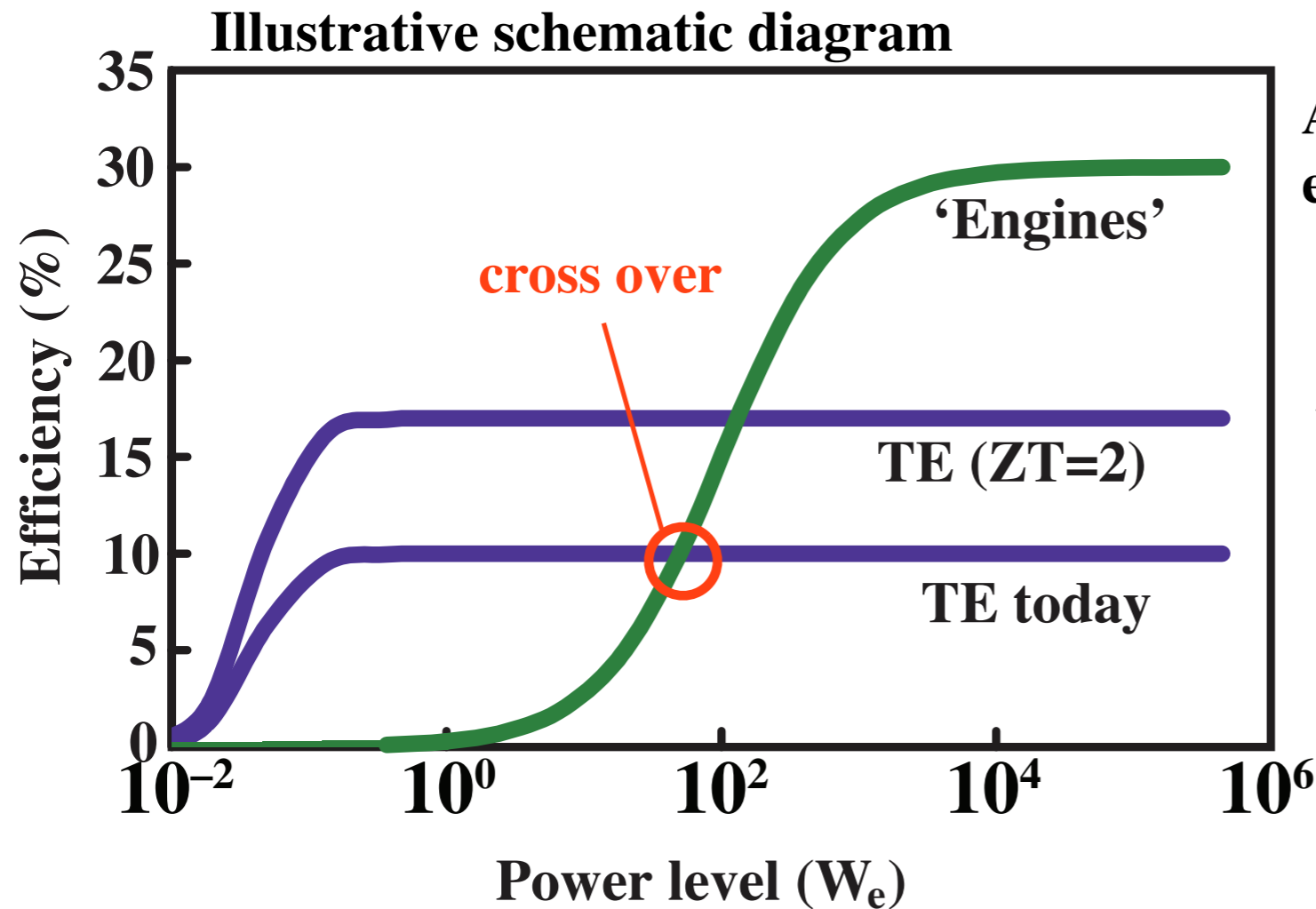
Thermodynamic Efficiency: The Competition



ZT of 4 start to become seriously competitive

C.B. Vining, Nature Mat. 8, 83 (2009)

Power Generation From Macro to Micro



At large scale, thermodynamic engines more efficient than TE

ZT average for both n and p over all temperature range

Diagram assumes high T



At the mm and μm scale with powers $\ll 1\text{W}$, thermoelectrics are more efficient than thermodynamic engines (Reynolds no. etc..)

C.B. Vining, Nature Mat. 8, 83 (2009)

Thermal Conductivity of Bulk Materials

- Both the lattice and electron current can contribute to heat transfer

thermal conductivity = electron contribution + phonon contribution
= (electrical conductivity) + (lattice contributions)

$$\kappa = \kappa_{el} + \kappa_{ph}$$

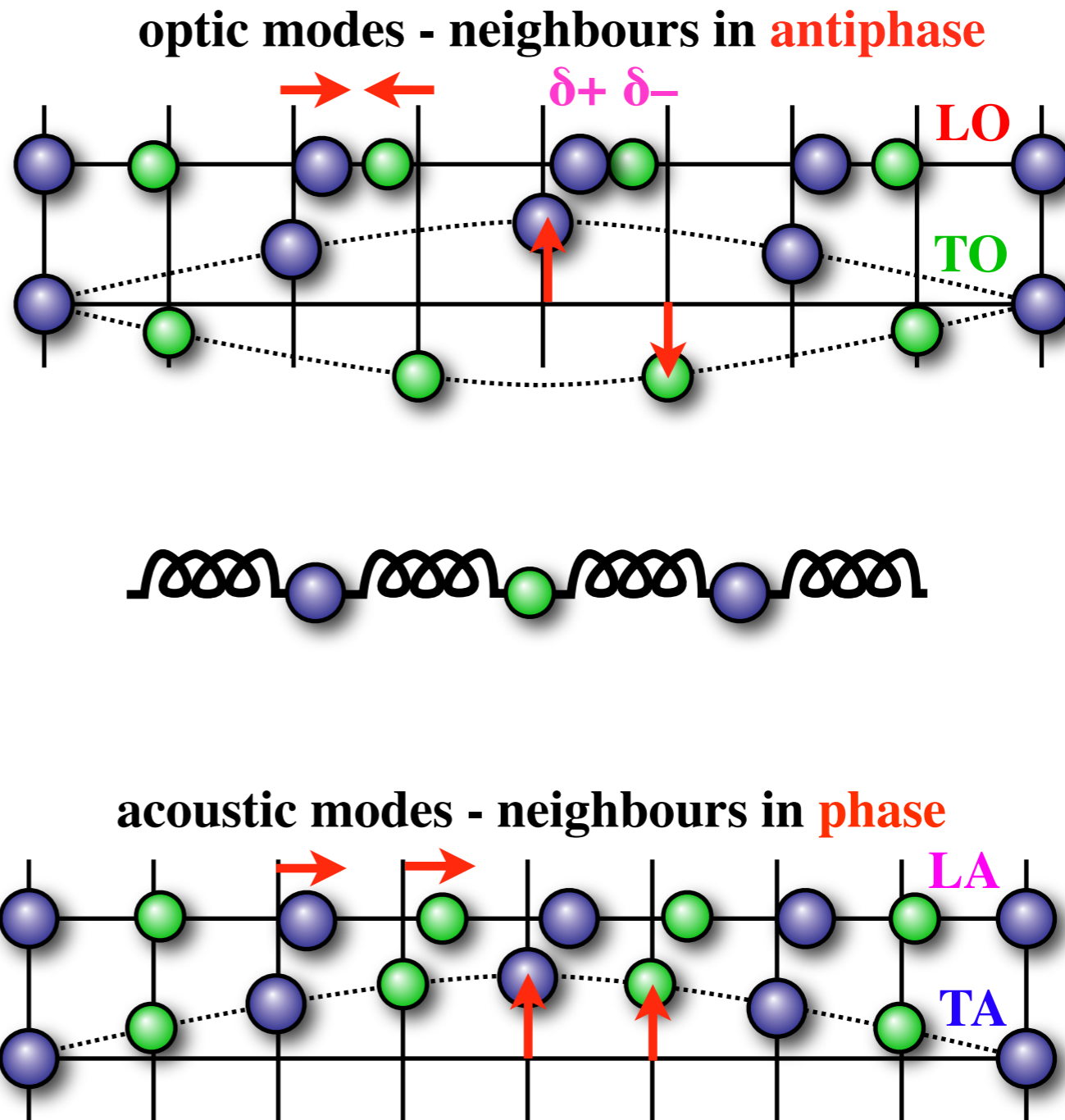
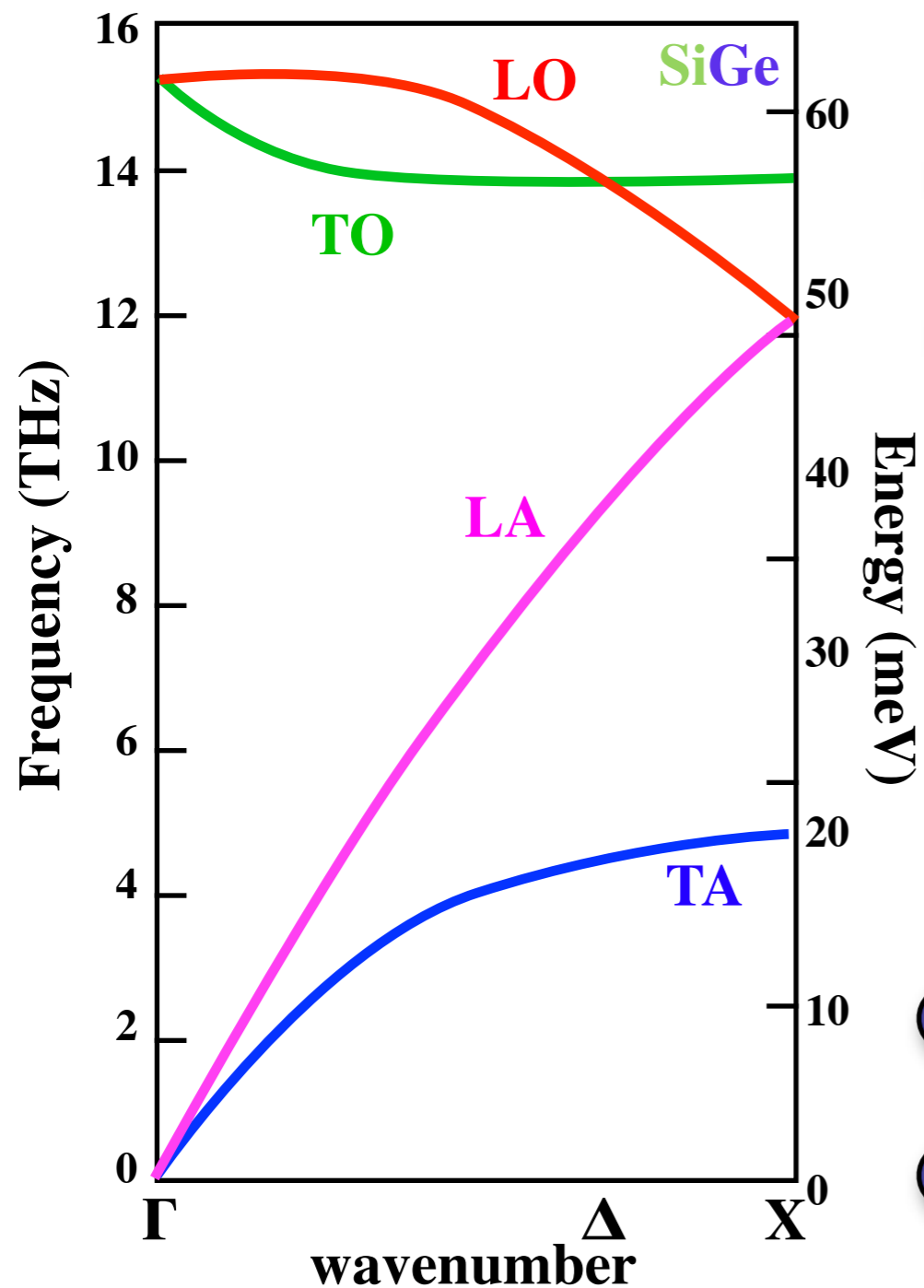
- For low carrier densities in semiconductors (non-degenerate) $\kappa_{el} \ll \kappa_{ph}$

- For high carrier densities in semiconductors (degenerate) $\kappa_{el} \gg \kappa_{ph}$

- Good thermoelectric materials should ideally have $\kappa_{el} \ll \kappa_{ph}$

i.e. electrical and thermal conductivities are largely decoupled

Phonons: Lattice Vibration Heat Transfer



Wiedemann-Franz Law

- Empirical law from experimental observation that $\frac{\kappa}{\sigma T} = \text{constant}$ for metals
- Drude model's great success was an explanation of Wiedemann-Franz
- Drude model assumes bulk of thermal transport by conduction electrons in metals
- Success fortuitous: two factors of 100 cancel to produce the empirical result from the Drude theory
- Incorrect assumption: classical gas laws cannot be applied to electron gas

Wiedemann-Franz Law for Metals

- In metals, the thermal conductivity is dominated by κ_{el}

$$\therefore \frac{\sigma T}{\kappa} = \frac{3}{\pi^2} \left(\frac{q}{k_B} \right)^2 = \frac{1}{L}$$

$$L = \text{Lorentz number} \\ = 2.45 \times 10^{-8} \text{ W}\cdot\Omega\text{K}^{-2}$$

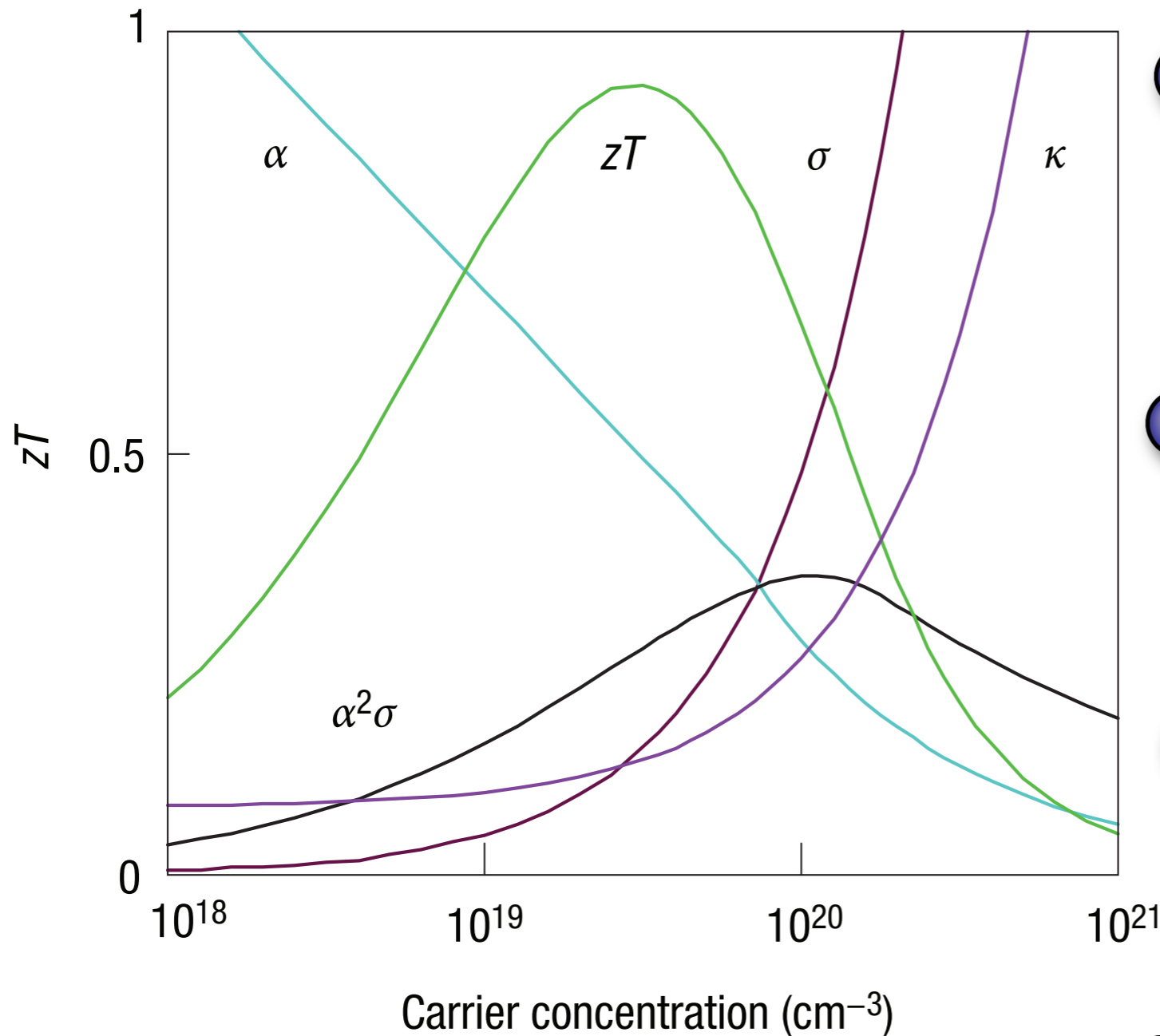
$$ZT = \frac{3}{\pi^2} \left(\frac{q\alpha}{k_B} \right)^2 = 4.09 \times 10^7 \alpha^2$$

$$\text{for } \kappa_{el} \gg \kappa_{ph}$$

Exceptions:

- most exceptions systems with $\kappa_{el} \ll \kappa_{ph}$
- some pure metals at low temperatures
- certain alloys where small κ_{el} results in significant κ_{ph} contribution
- certain low dimensional structures where κ_{ph} can dominate

Bi₂Te₃ ZT Optimisation Through Doping



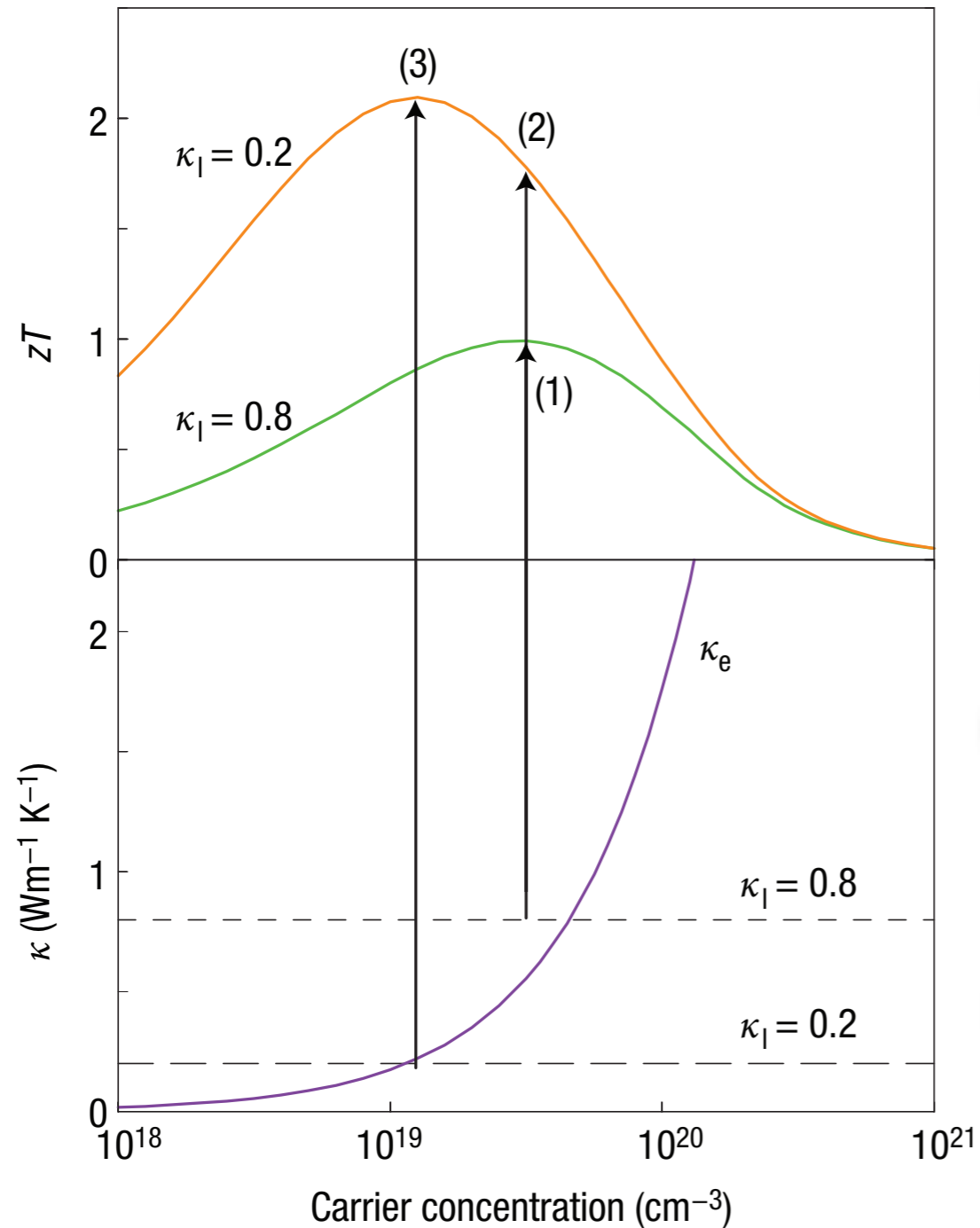
● Maximum ZT requires compromises with α , σ & κ

● Limited by Wiedemann-Franz Law

● Maximum ZT ~ 1 at $\sim 100^\circ\text{C}$

G.J. Snyder et al., Nature Mat. 7, 105 (2008)

Optimising ZT in Bulk by Reducing κ_{ph}



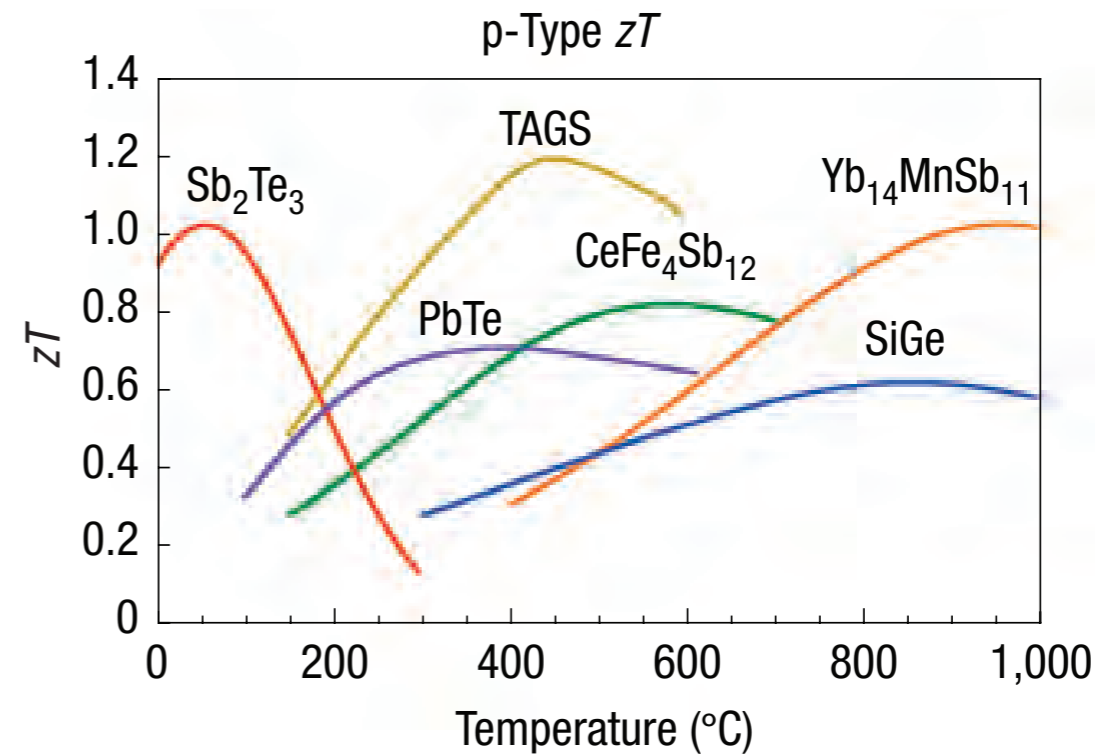
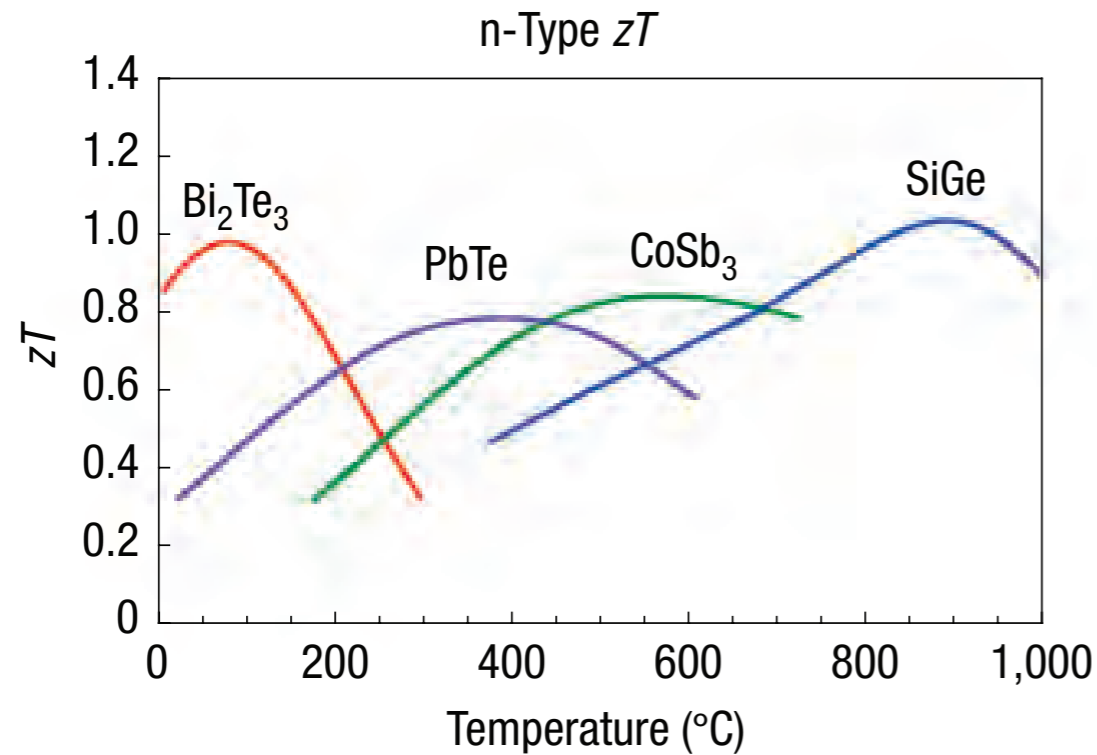
- Example for Bi_2Te_3 where κ_{ph} is theoretically reduced by x 4
- Polycrystalline or defects can be used to reduce κ_{ph} faster than σ

$$ZT = \frac{\alpha^2}{L \left(1 + \frac{\kappa_{ph}}{\kappa_{el}} \right)}$$

- “Phonon glasses” search to improve ZT

G.J. Snyder et al., Nature Mat. 7, 105 (2008)

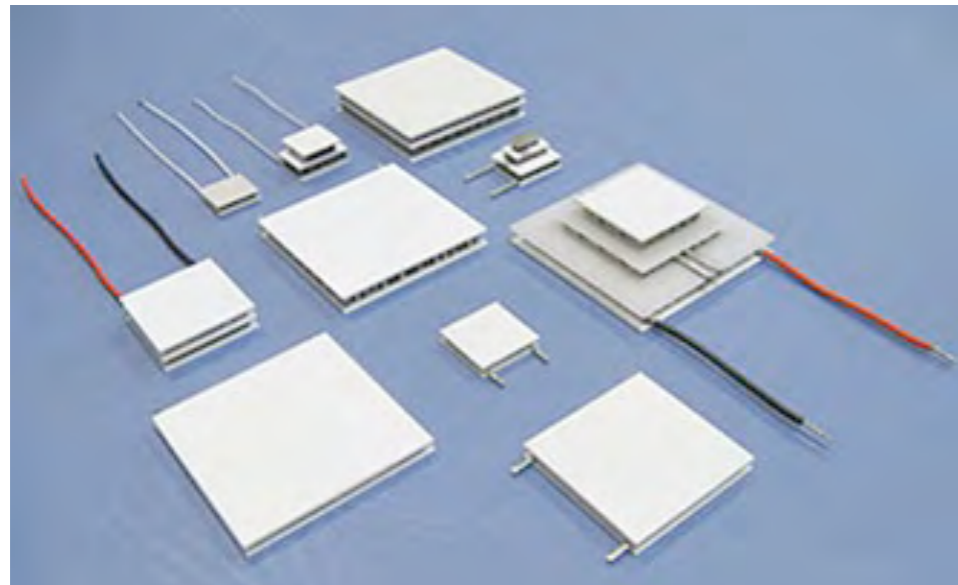
Bulk Thermoelectric Materials Performance



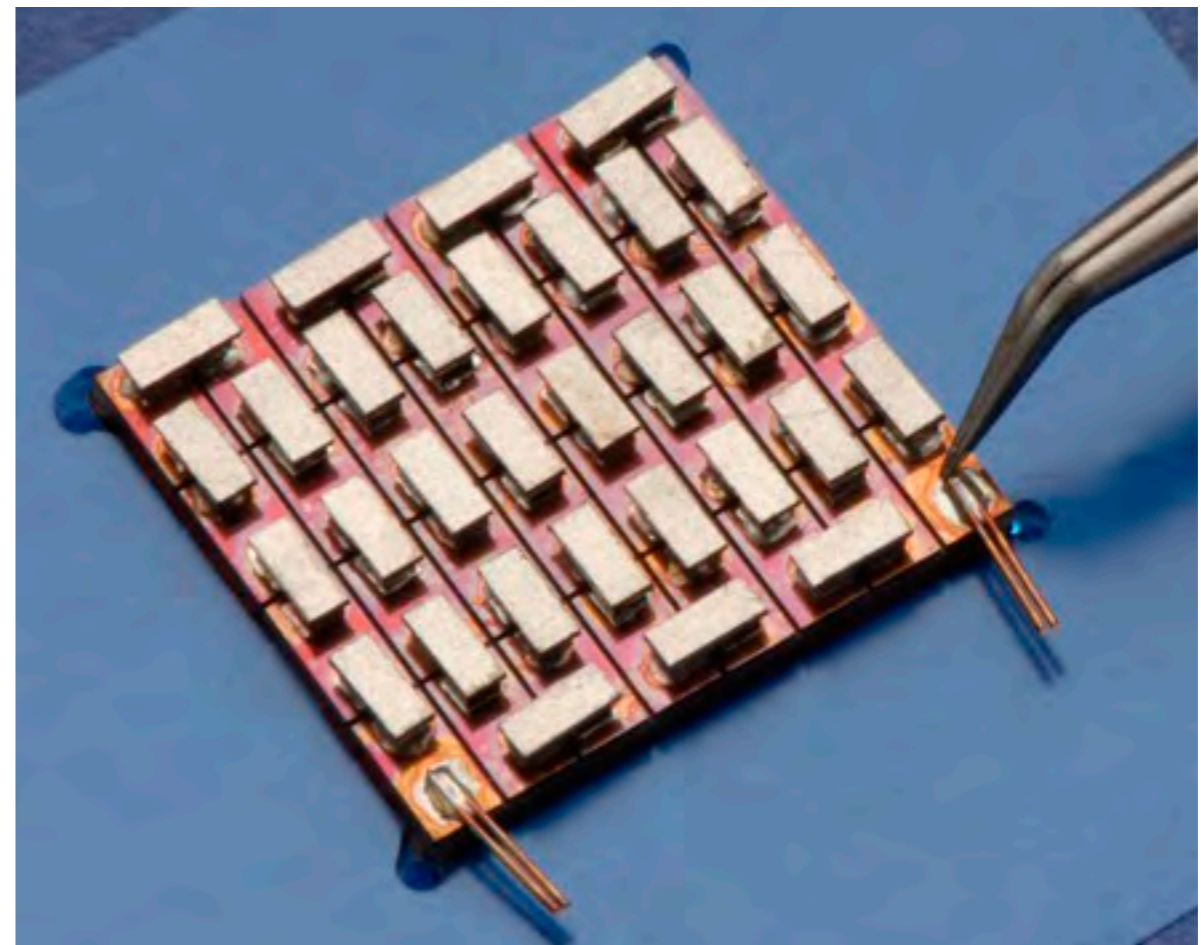
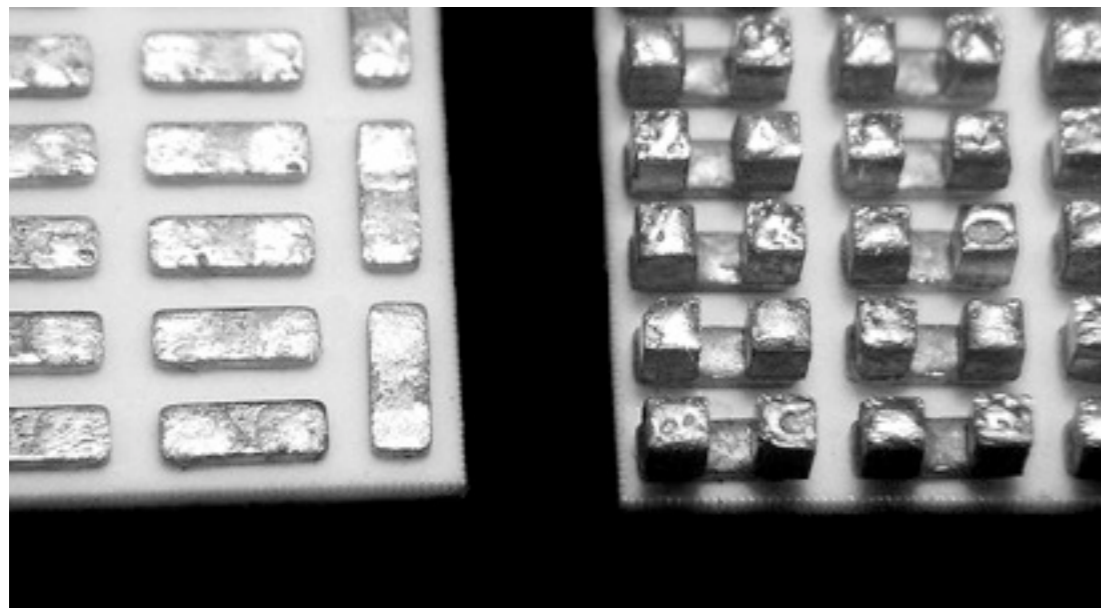
Nature Materials 7, 105 (2008)

- **Bulk n- Bi_2Te_3 and p- Sb_2Te_3 used in most commercial Peltier coolers**
- **Bulk $Si_{1-x}Ge_x$ ($x \sim 0.2$ to 0.3) used for high temperature satellite applications**

Thermoelectric Generators / Peltier Coolers



Bulk n-Bi₂Te₃ and p-Sb₂Te₃ devices

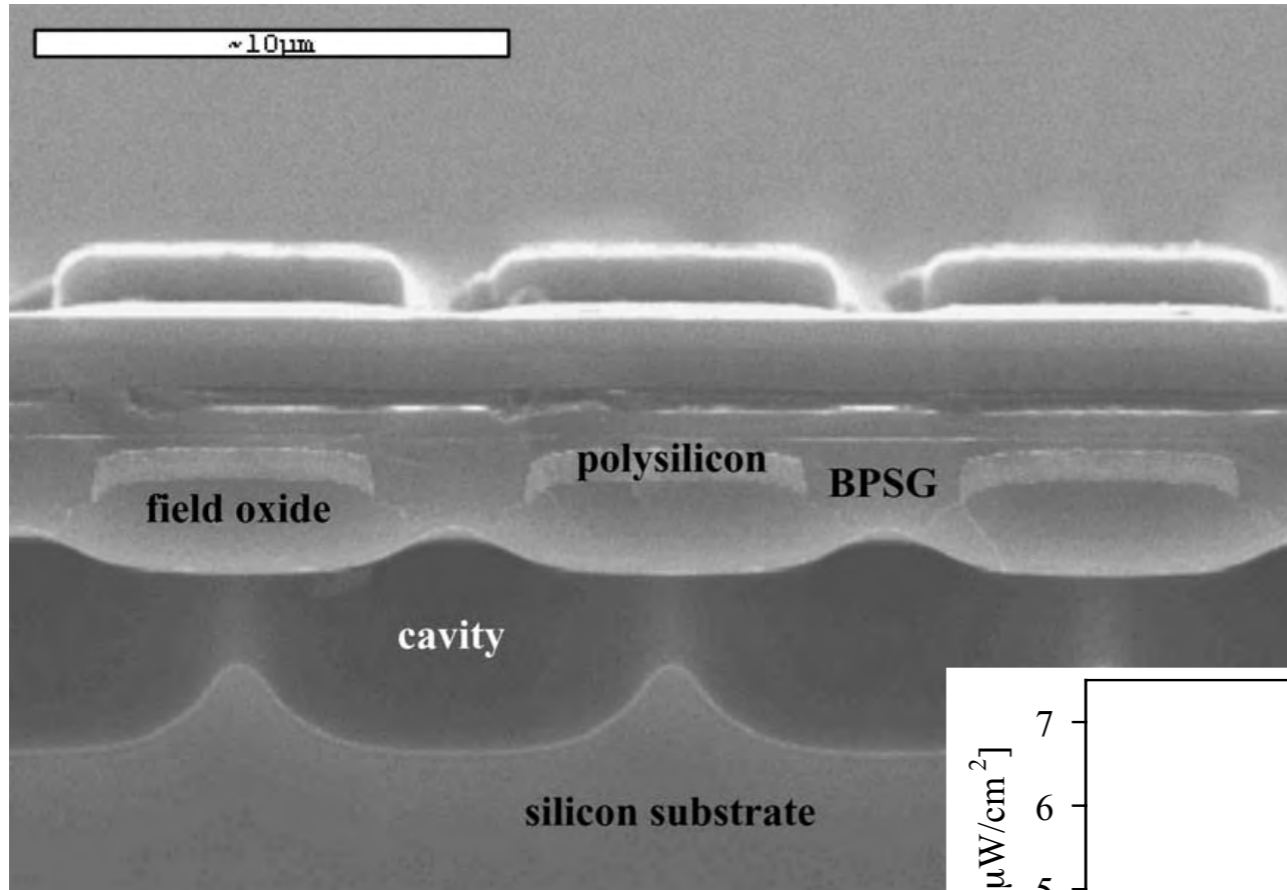


D.J. Paul
School of Engineering



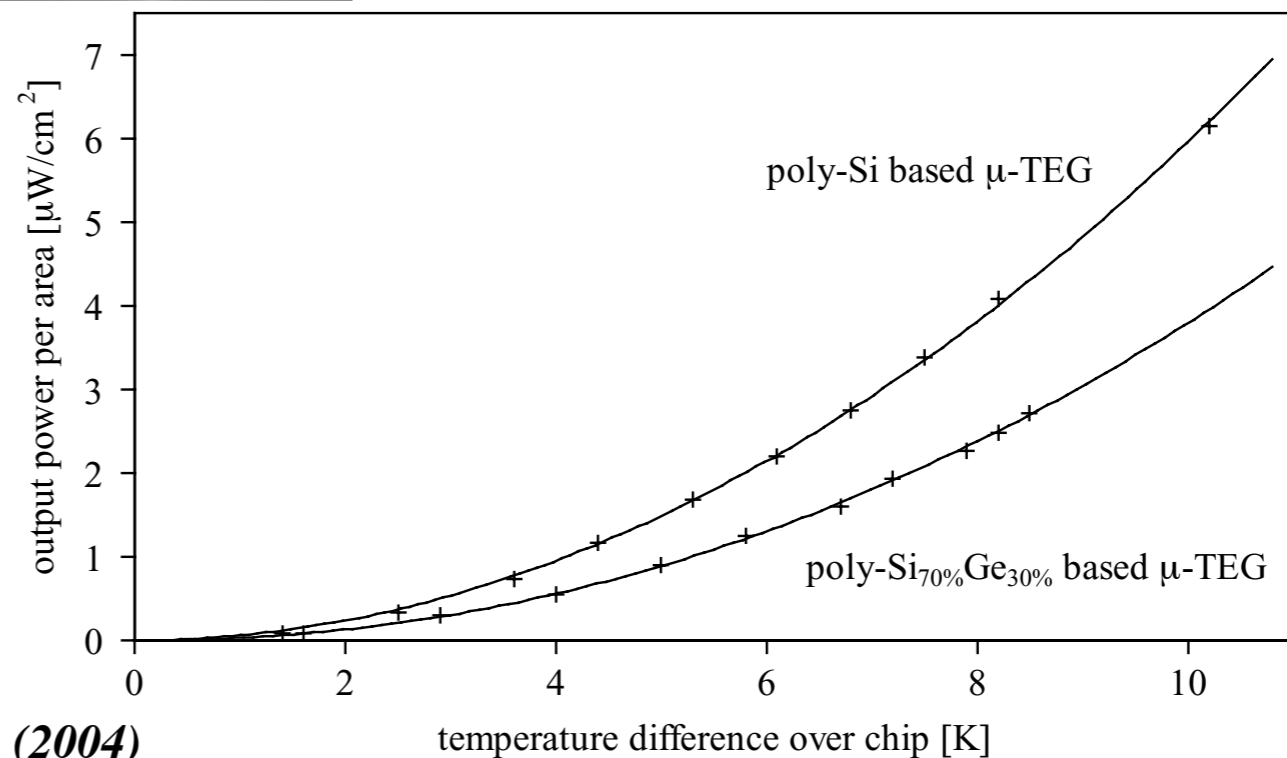
University
of Glasgow

Small Scale Microfabricated Energy Harvesting



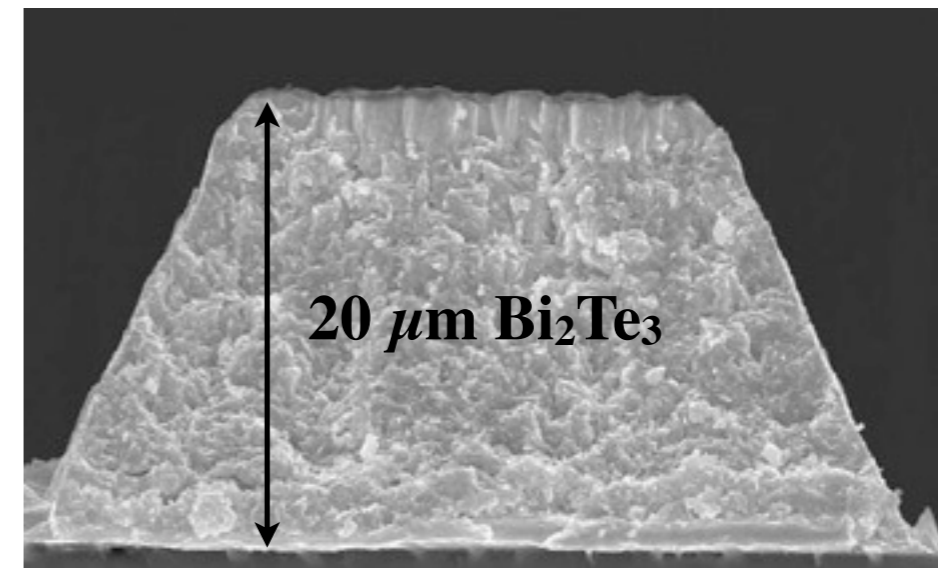
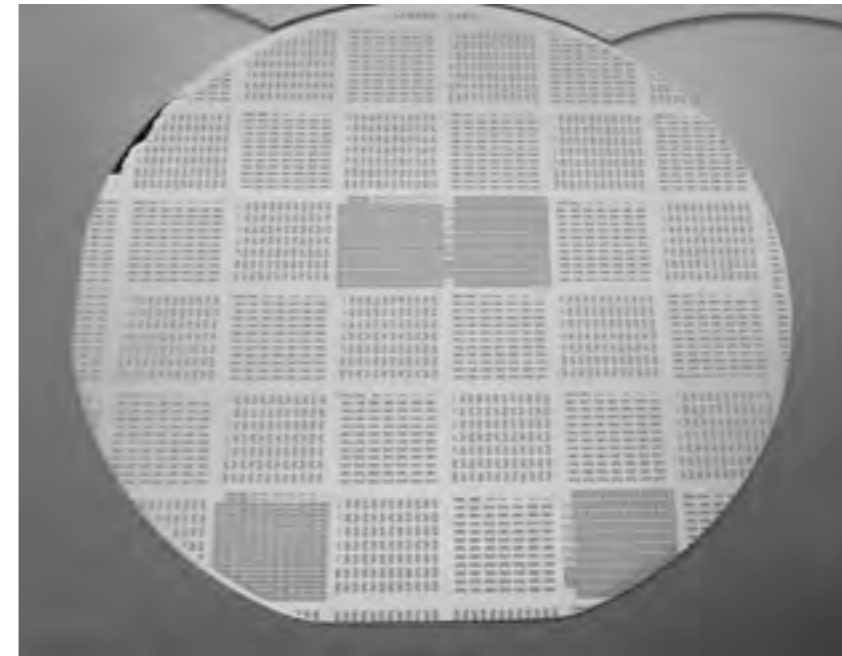
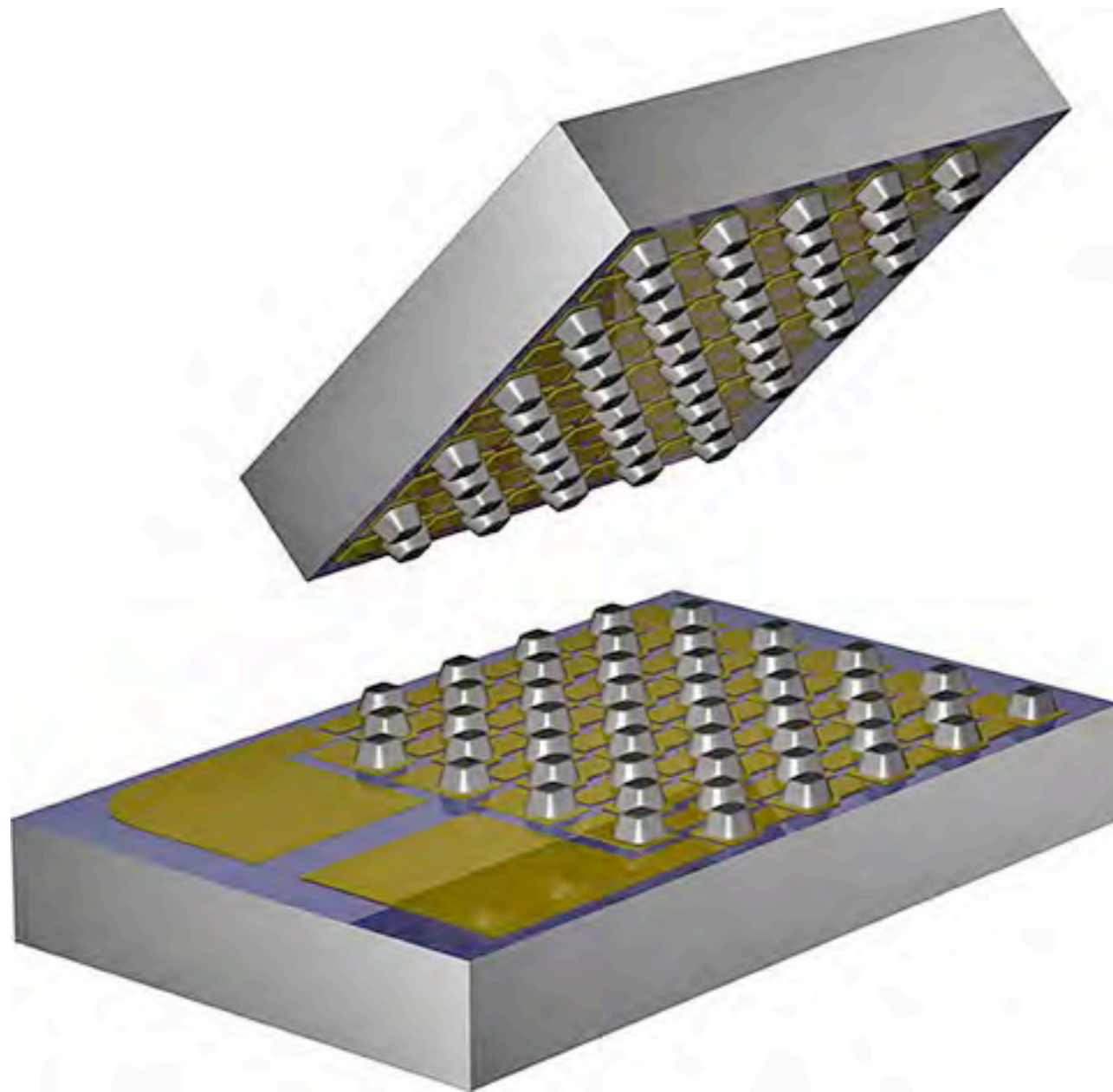
- Si process: poly-Si
- $\alpha_{n+p} = 160 \mu\text{V/K}$
- $\kappa = 31.4 \text{ Wm}^{-1}\text{K}^{-1}$
- $\rho = 1.5 \text{ m}\Omega\text{-cm}$

$\Delta T = 5 \text{ K} \rightarrow 5 \text{ V}$ and $1 \mu\text{W}$



M. Strasser et al., Sensors Actuators A 114, 362 (2004)

Micropelt: Microfabricated Bi_2Te_3 Technology



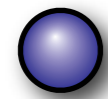
<http://www.micropelt.com/>

D.J. Paul
School of Engineering

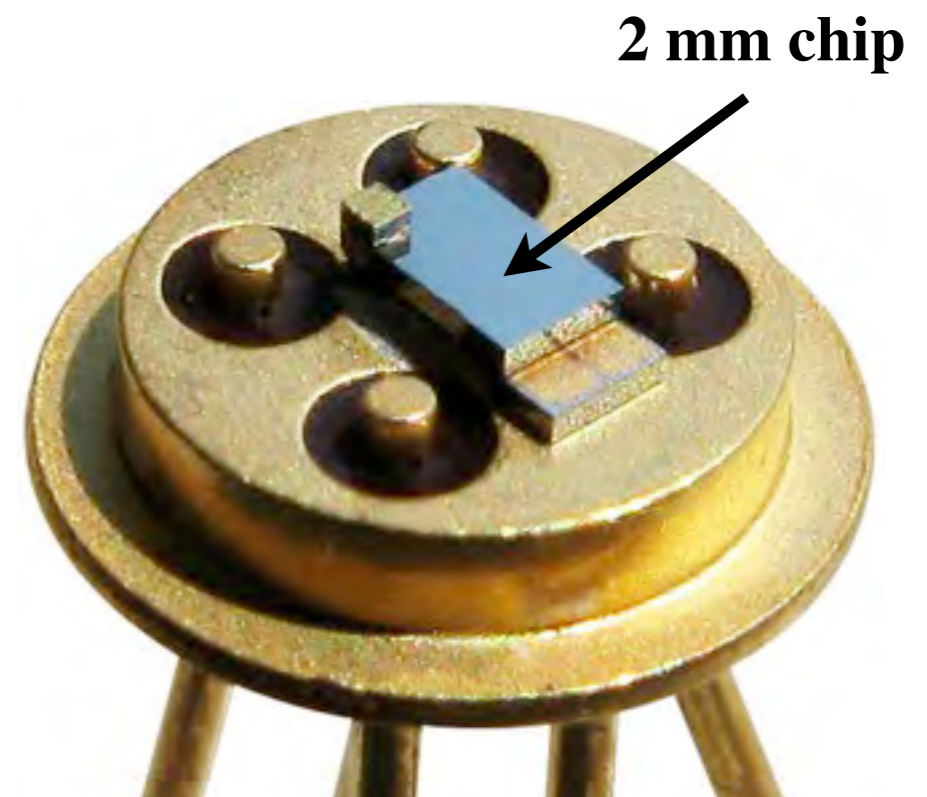
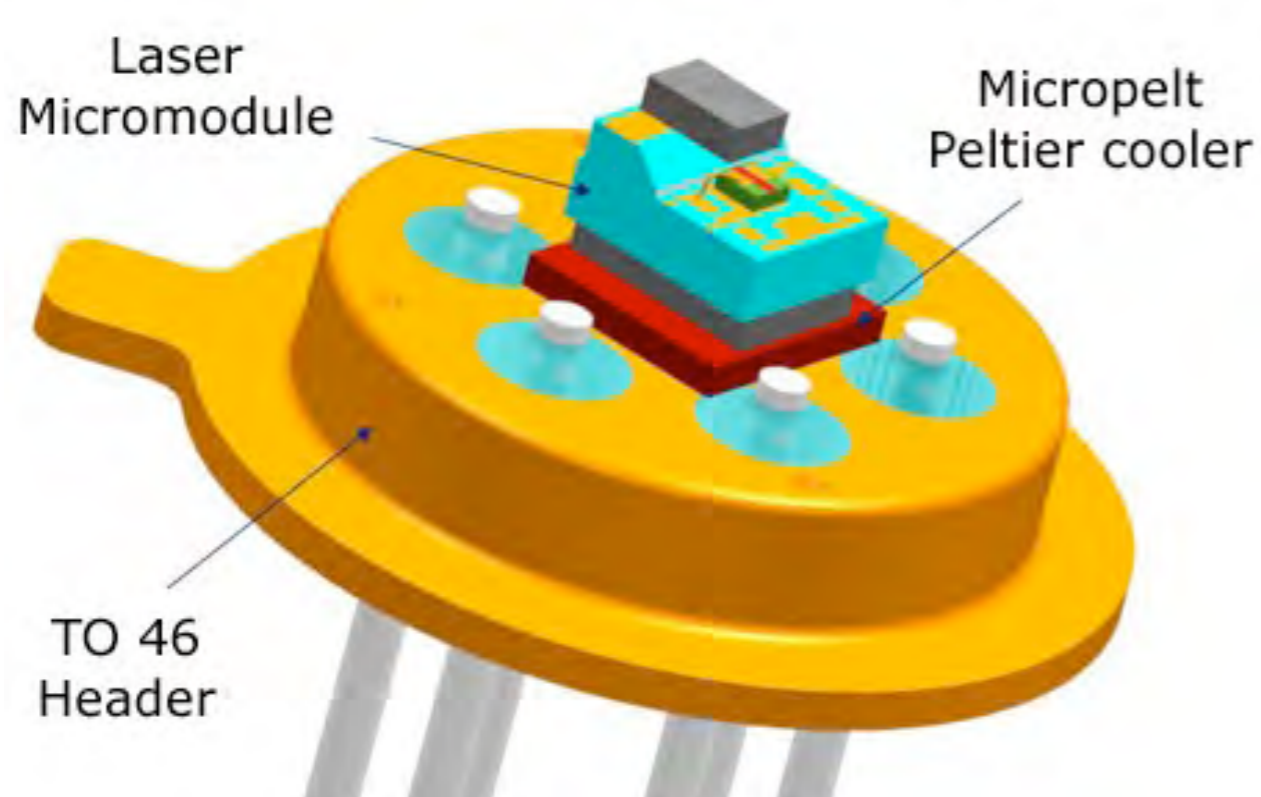


University
of Glasgow

Micropelt Peltier Coolers for Lasers

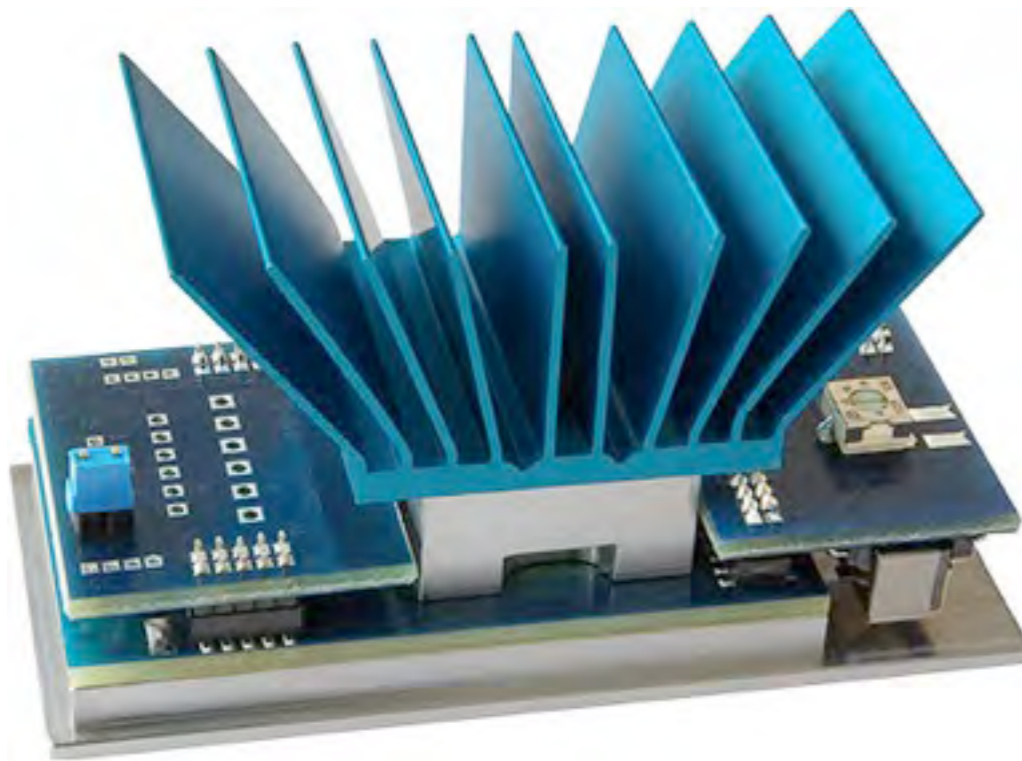


Microfabricated Bi_2Te_3 thermoelectric devices

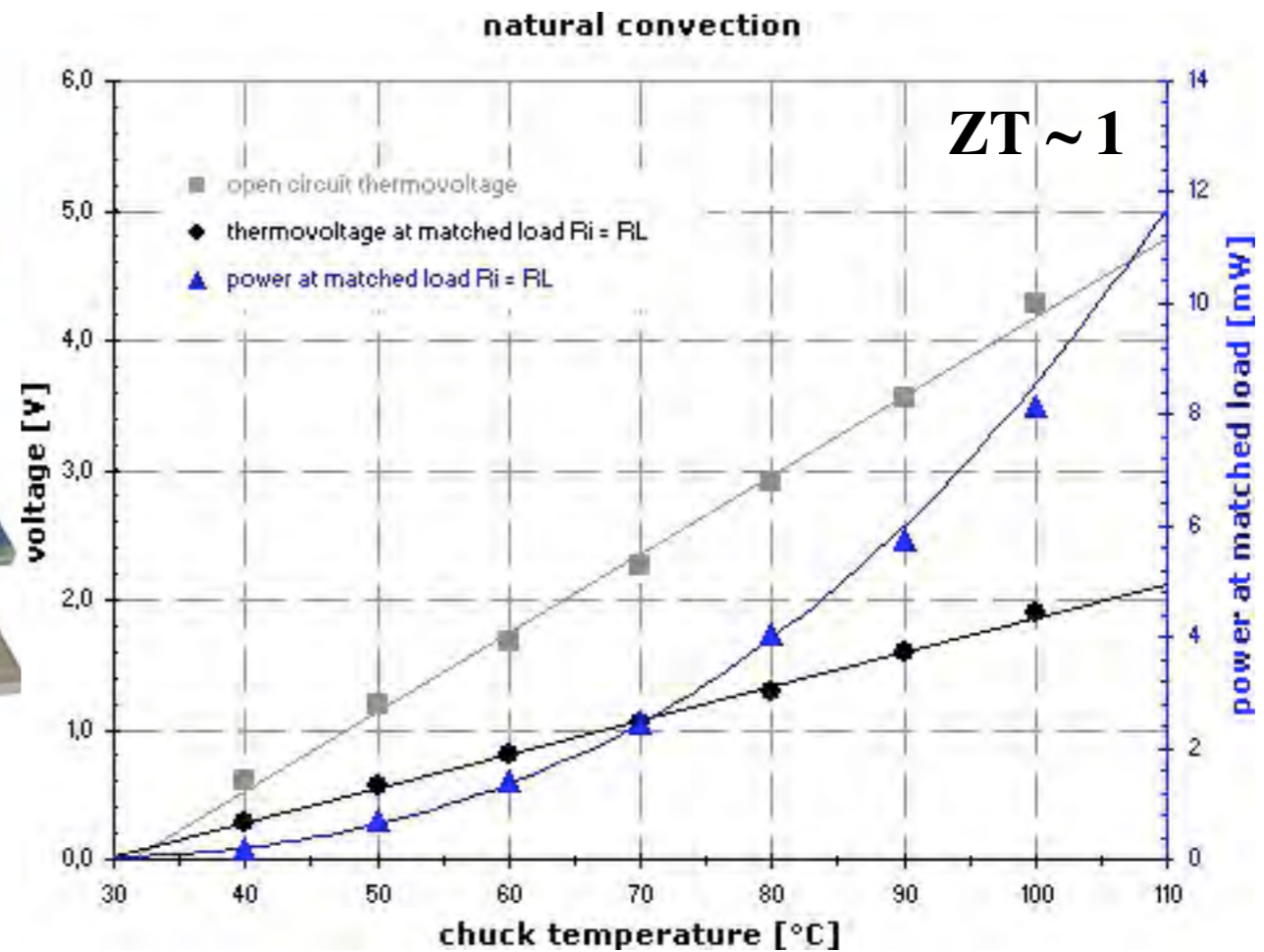


<http://www.micropelt.com/>

Micropelt Bi₂Te₃ Thermoelectric Energy Harvester



3.4 mm x 3.4 mm
thermoelectric chip



<http://www.micropelt.com/>

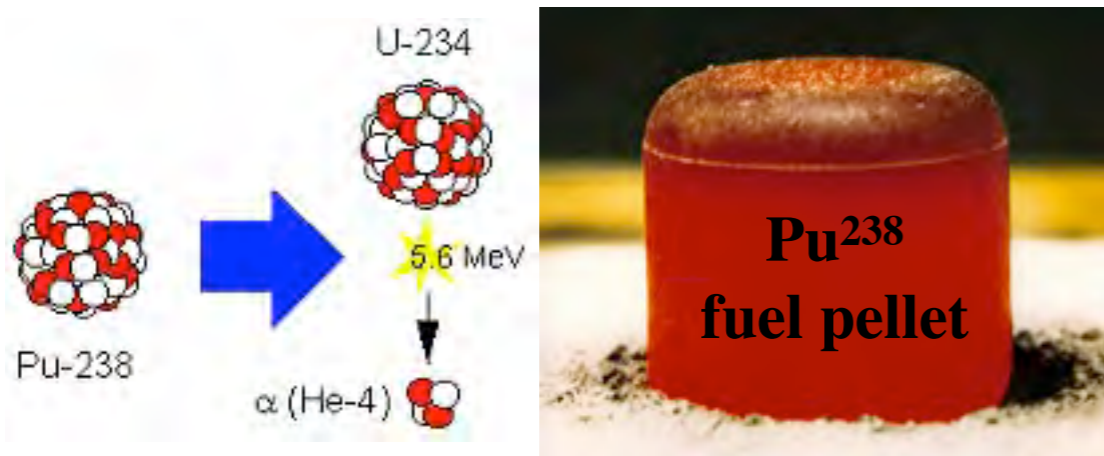
Present Thermoelectric Energy Harvesting



- **VW and BMW announced TE on exhaust in 2008: 24 Bi_2Te_3 modules**
- **600 W under motorway driving \rightarrow 30% of car's electrical requirement**
- **5% reduction in fuel consumption through removing alternator**

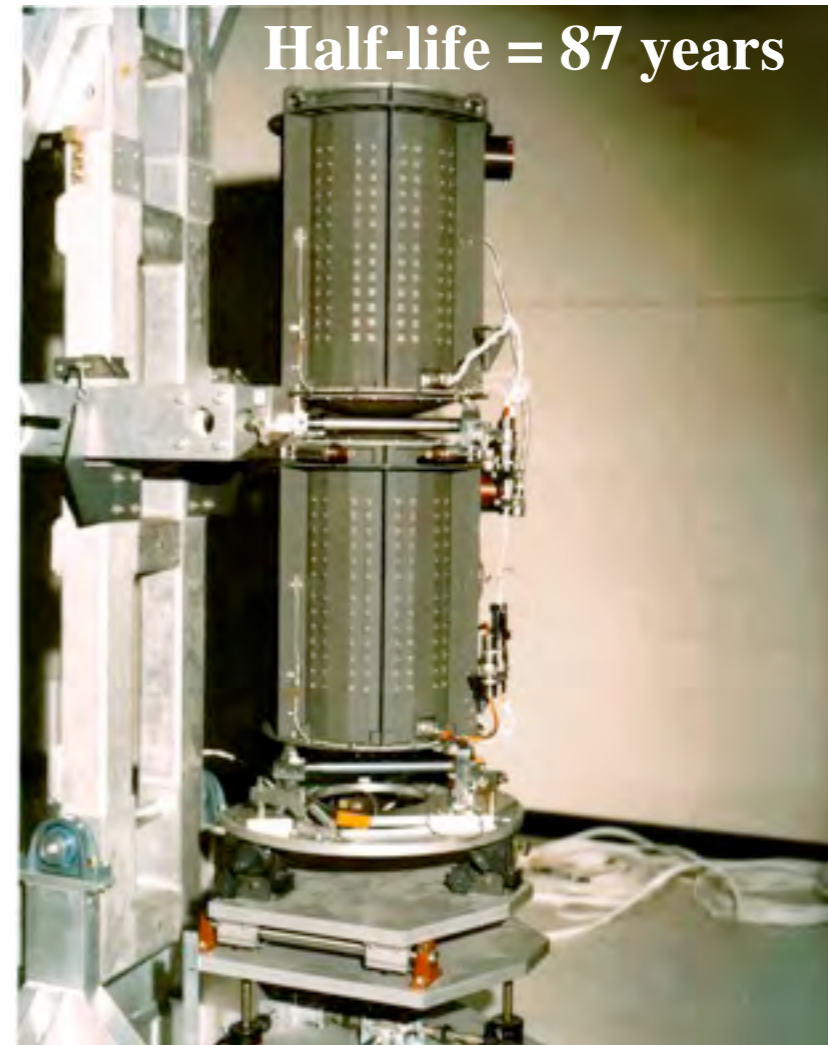
NASA Radioisotope Thermoelectric Generator

Radioisotope heater → thermoelectric generator → electricity

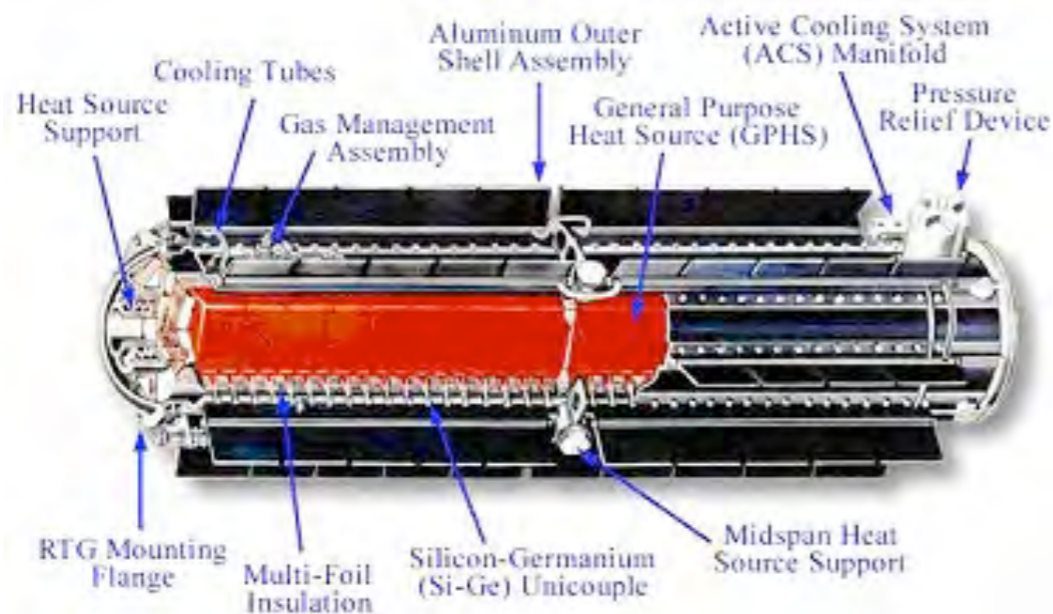


Voyager – Pu²³⁸

Half-life = 87 years



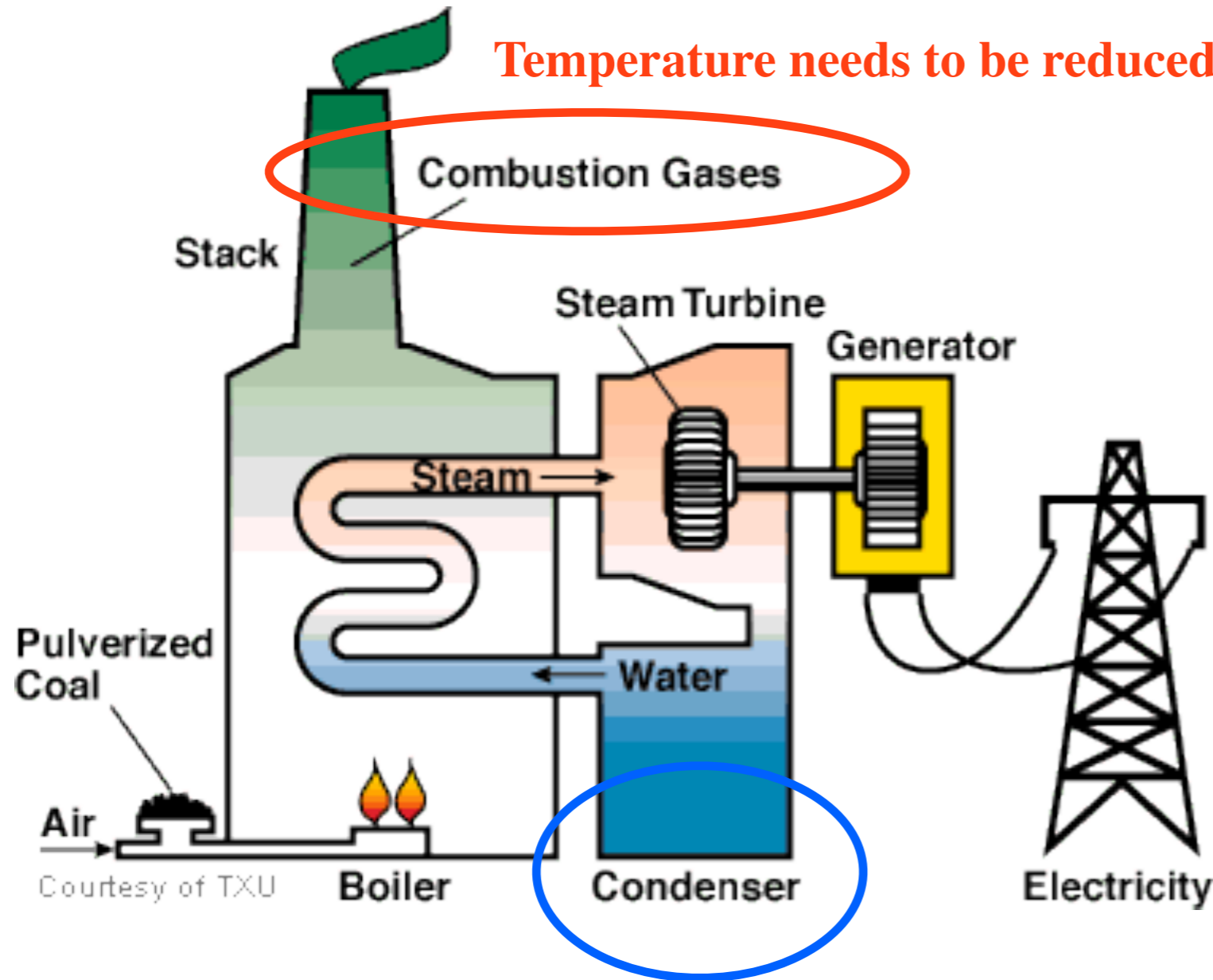
GPHS-RTG



● 470 W @ 30 V on launch, after 33 years power = $470 \times 2^{-\frac{33}{87}} = 361 \text{ W}$

Energy Conversion: Electricity: The Rankine Cycle

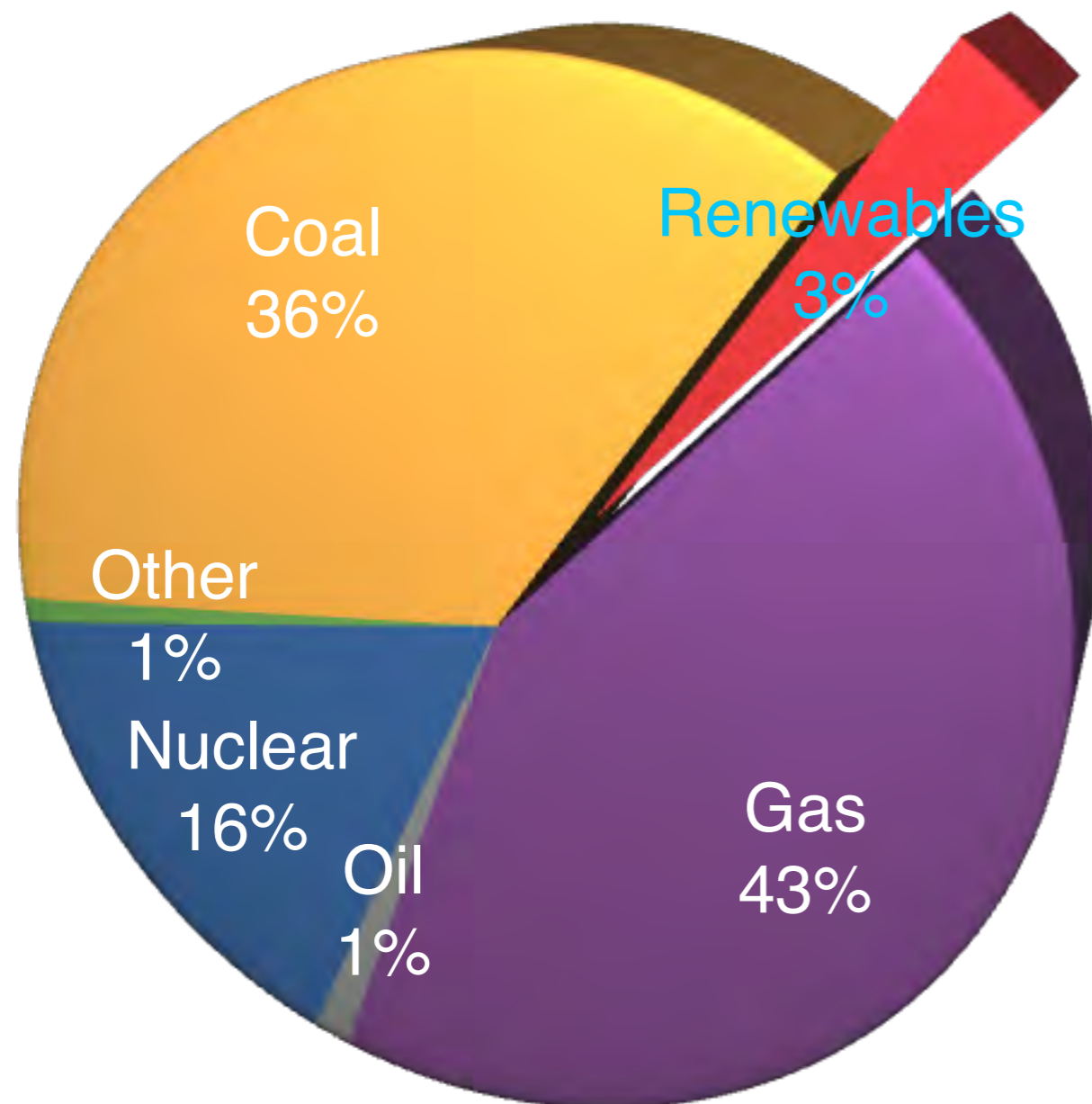
Temperature needs to be reduced by 80 °C for carbon capture



Cooling towers → throw heat away → added losses

Energy stored in fuel → heat → kinetic energy → electric energy

U.K. Electricity Generation 2007



- Nuclear
- Other
- Coal
- Renewables
- Gas
- Oil

80% generate CO₂

97% use the Rankine Cycle

<http://www.berr.gov.uk/energy/statistics/>

Main Strategies for Optimising ZT

Reducing thermal conductivity faster than electrical conductivity:

- e.g. skutterudite structure: filling voids with heavy atoms

Low-dimensional structures:

- Increase α through enhanced DOS $(\alpha = -\frac{\pi^2}{3} \frac{k_B}{q} k_B T \left[\frac{d \ln(\mu g)}{dE} \right]_{E_F})$
- Make α and σ almost independent
- Reduce κ through numerous interfaces to increase phonon scattering

Energy filtering:

- $$\alpha = -\frac{k_B}{q} \left[\frac{E_c - E_F}{k_B T} + \frac{\int_0^\infty \frac{(E - E_c)}{k_B T} \sigma(E) dE}{\int_0^\infty \sigma(E) dE} \right]$$
 enhance $Y.I. Ravich et al., Phys. Stat. Sol. (b)$
43, 453 (1971)

Carrier Pocket Engineering – strain & band structure engineering

Length Scales: Mean Free Paths

3D electron mean free path $\ell = v_F \tau_m = \frac{\hbar}{m^*} (3\pi^2 n)^{\frac{1}{3}} \frac{\mu m^*}{q}$

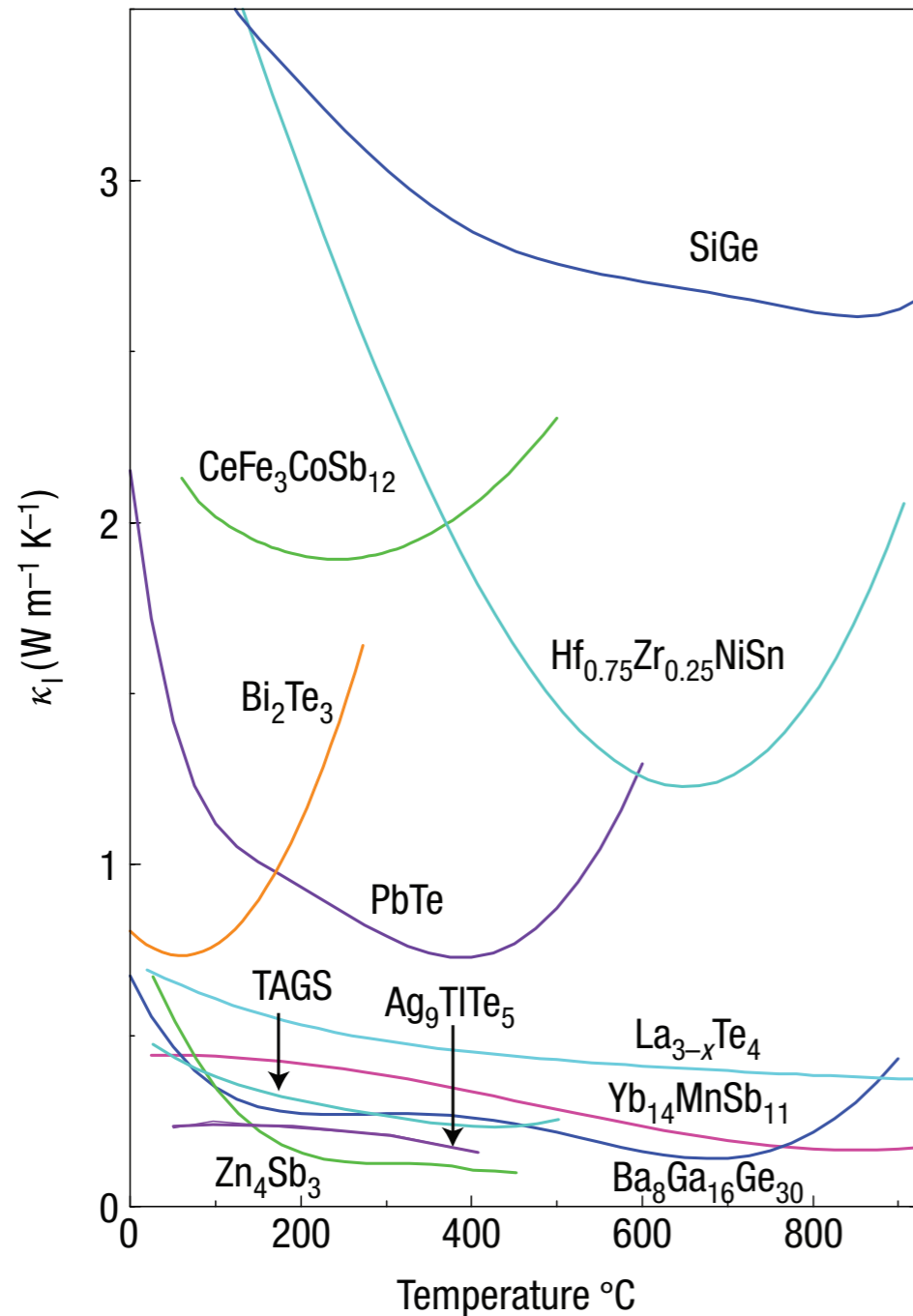
$$\ell = \frac{\hbar \mu}{q} (3\pi^2 n)^{\frac{1}{3}}$$

3D phonon mean free path

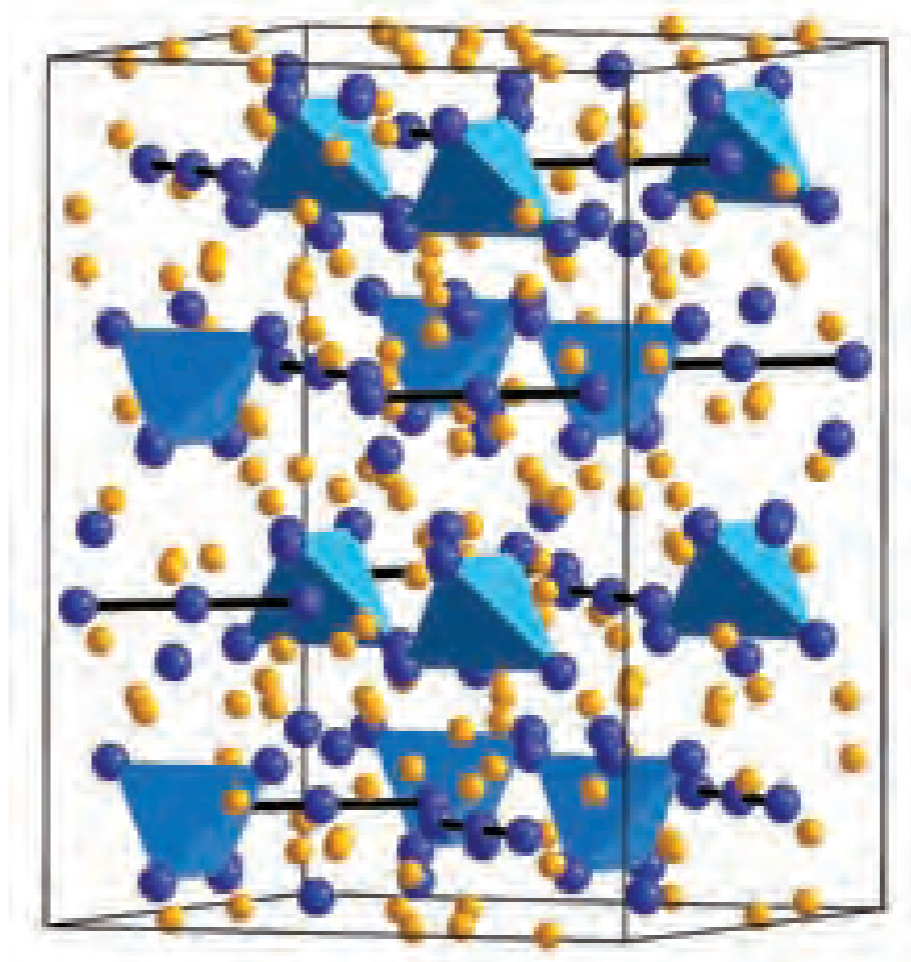
$$\Lambda_{\text{ph}} = \frac{3\kappa_{\text{ph}}}{C_v \langle v_t \rangle \rho}$$

- C_v = specific heat capacity
 - $\langle v_t \rangle$ = average phonon velocity
 - ρ = density of phonons
- A structure may be 2D or 3D for electrons but 1 D for phonons (or vice versa!)

Complex Crystal Structures: Reducing κ_{ph}



Skutterudite structure: filling voids with heavy atoms

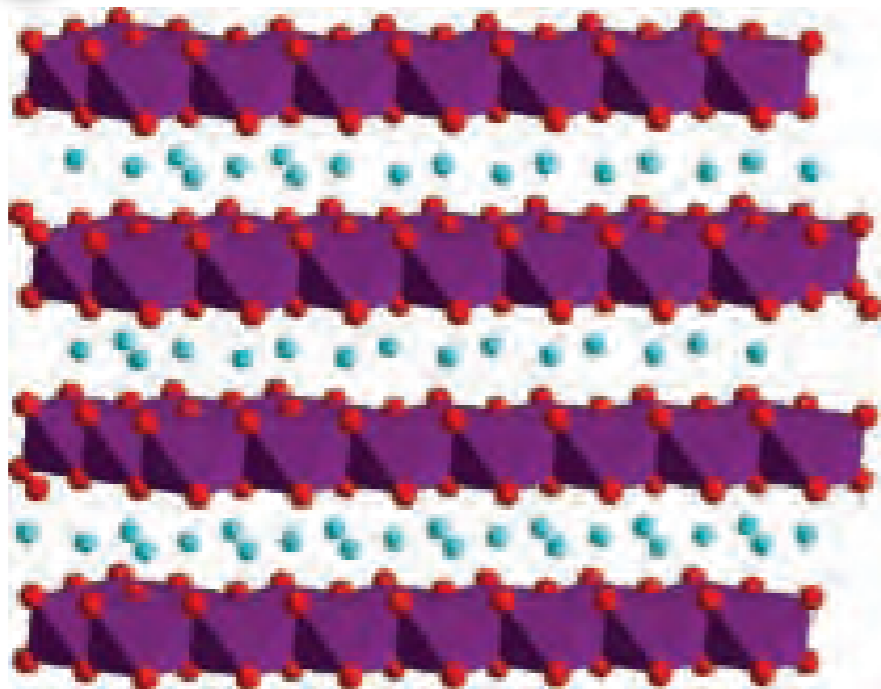


p-Yb₁₄MnSb₁₁ – ZT ~ 1 @ 900 $^\circ\text{C}$

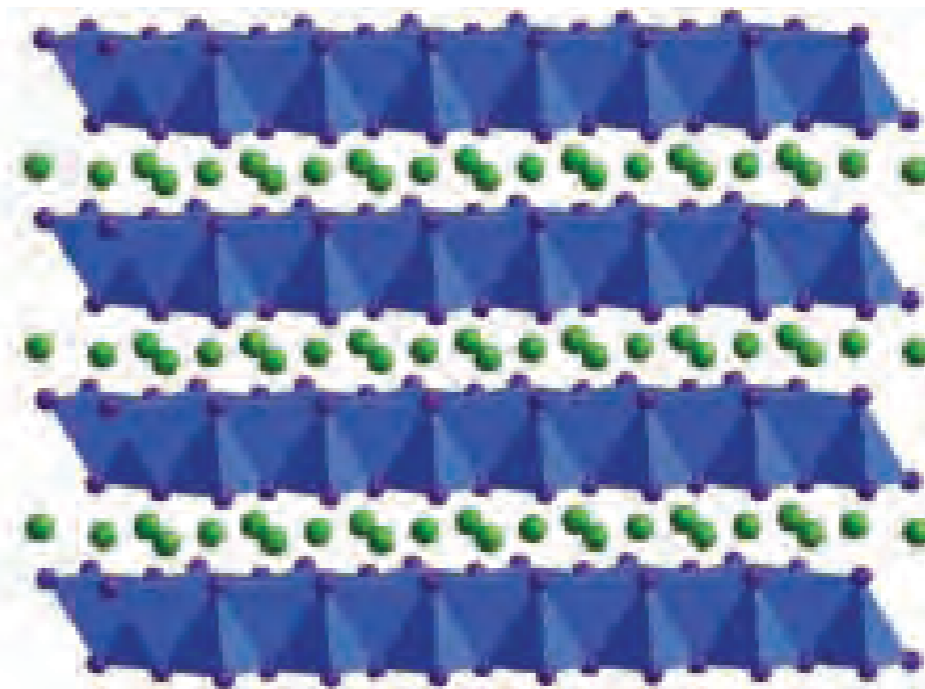
G.J. Snyder et al., Nat. Mat. 7, 105 (2008)

Electron Crystal – Phonon Glass Materials

- Principle: trying to copy “High T_c ” superconductor structures
- Heavy ion / atom layers for phonon scattering
- High mobility electron layers for high electrical conductivity



Na_xCoO_2

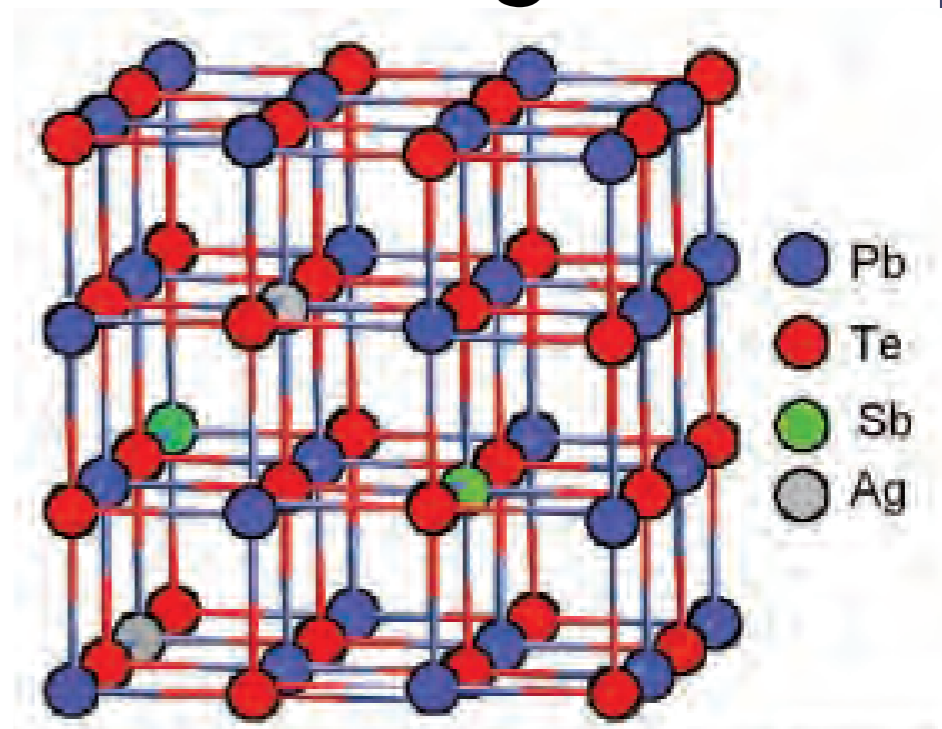
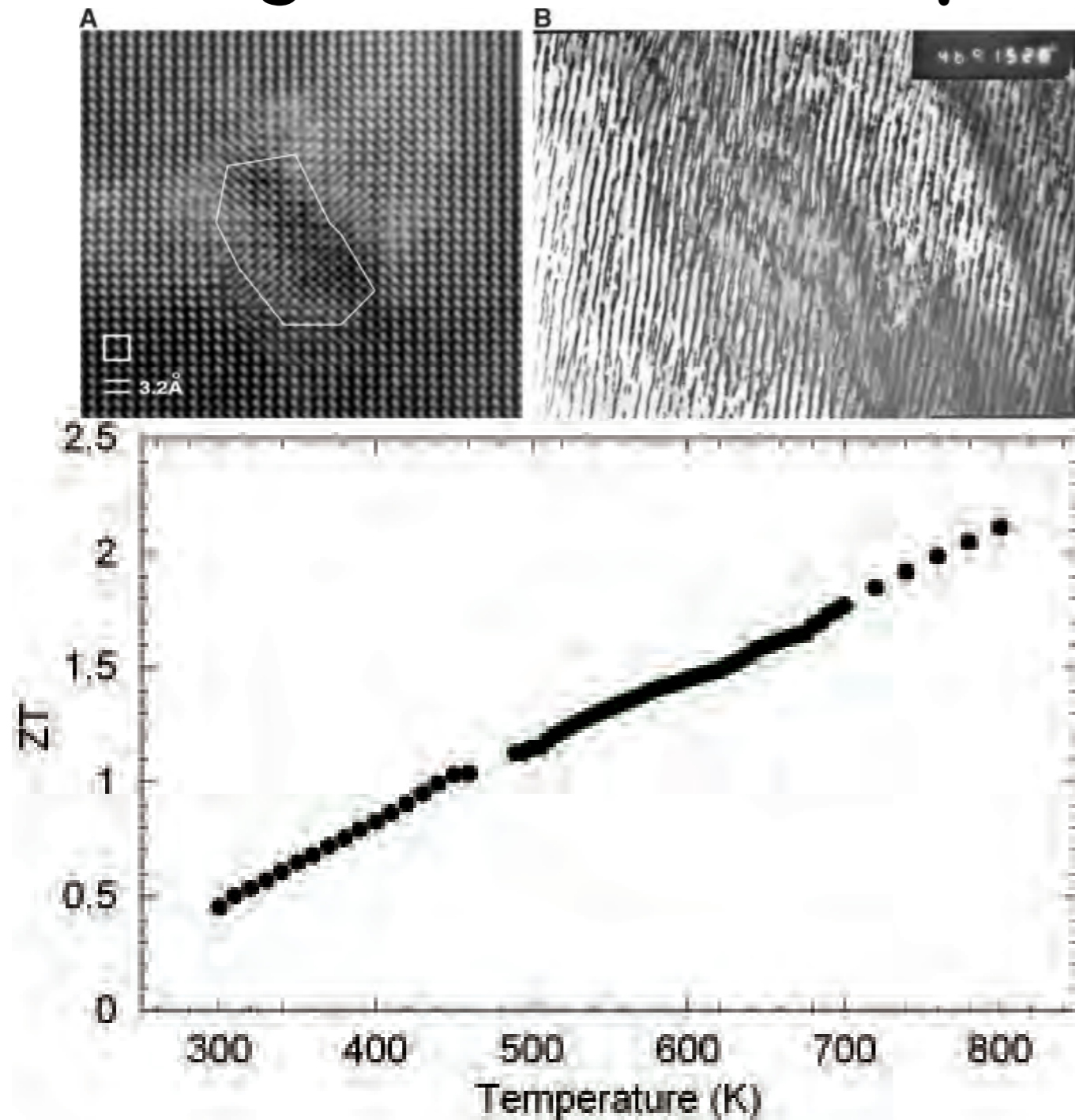


$\text{Ca}_x\text{Yb}_{1-x}\text{Zn}_2\text{Sb}_2$

- Only small improvements to ZT observed

G.J. Snyder et al., Nat. Mat. 7, 105 (2008)

AgPb₁₈SbTe₂₀ – Nanoparticle Scattering?



$$\alpha = -335 \mu\text{VK}^{-1}$$
$$\sigma = 30,000 \text{ S/m}$$
$$\kappa = 1.1 \text{ Wm}^{-1}\text{K}^{-1}$$

at 700 K

K.F. Hsu et al., Science 303, 818 (2004)

Low Dimensional Structures: 2D Superlattices

- Use of transport along superlattice quantum wells
- Higher α from the higher density of states
- Higher electron mobility in quantum well \rightarrow higher σ
- Lower κ_{ph} through additional phonon scattering from heterointerfaces
- Disadvantage: higher κ_{el} with higher σ (but layered structure can reduce this effect)
- Overall Z and ZT should increase

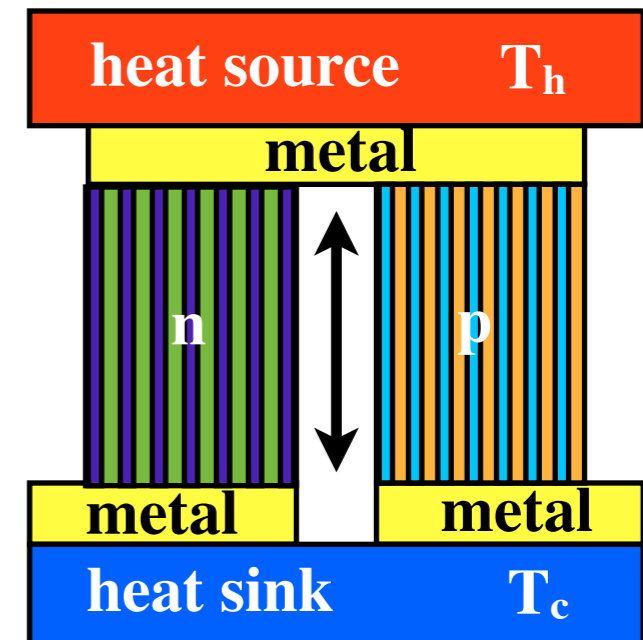


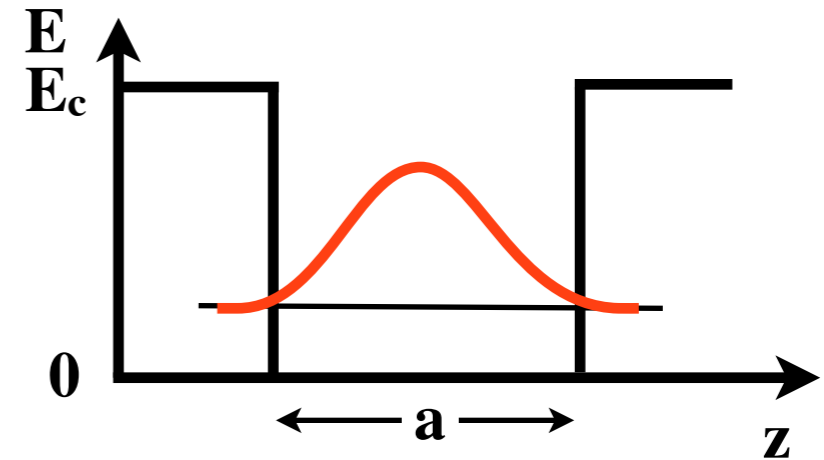
Figure of merit

$$ZT = \frac{\alpha^2 \sigma}{\kappa} T$$

L.D. Hicks and M.S. Dresselhaus, Phys. Rev. B 47, 12737 (1993)

2D Bi₂Te₃ Superlattices

- $E_{F2D} = E_{F3D} - \frac{\hbar^2 \pi^2}{2m_z^* a^2}$
- Both doping and quantum well width, a can now be used to engineer ZT



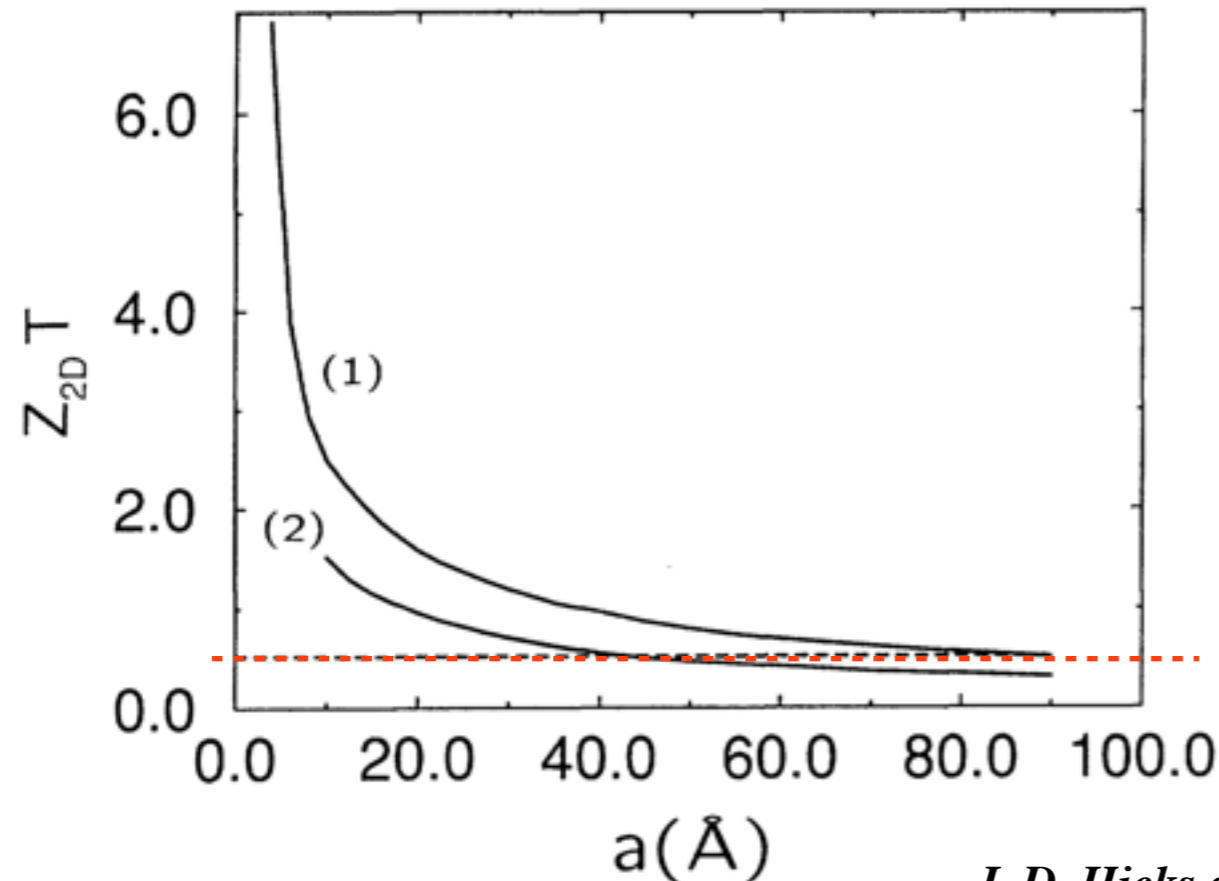
$$m_x = 0.021 m_0$$

$$m_y = 0.081 m_0$$

$$m_z = 0.32 m_0$$

$$\kappa_{ph} = 1.5 \text{ Wm}^{-1}\text{K}^{-1}$$

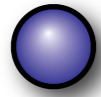
$$\mu_{a0} = 0.12 \text{ m}^2\text{V}^{-1}\text{s}^{-1}$$



ZT for 3D Bi₂Te₃

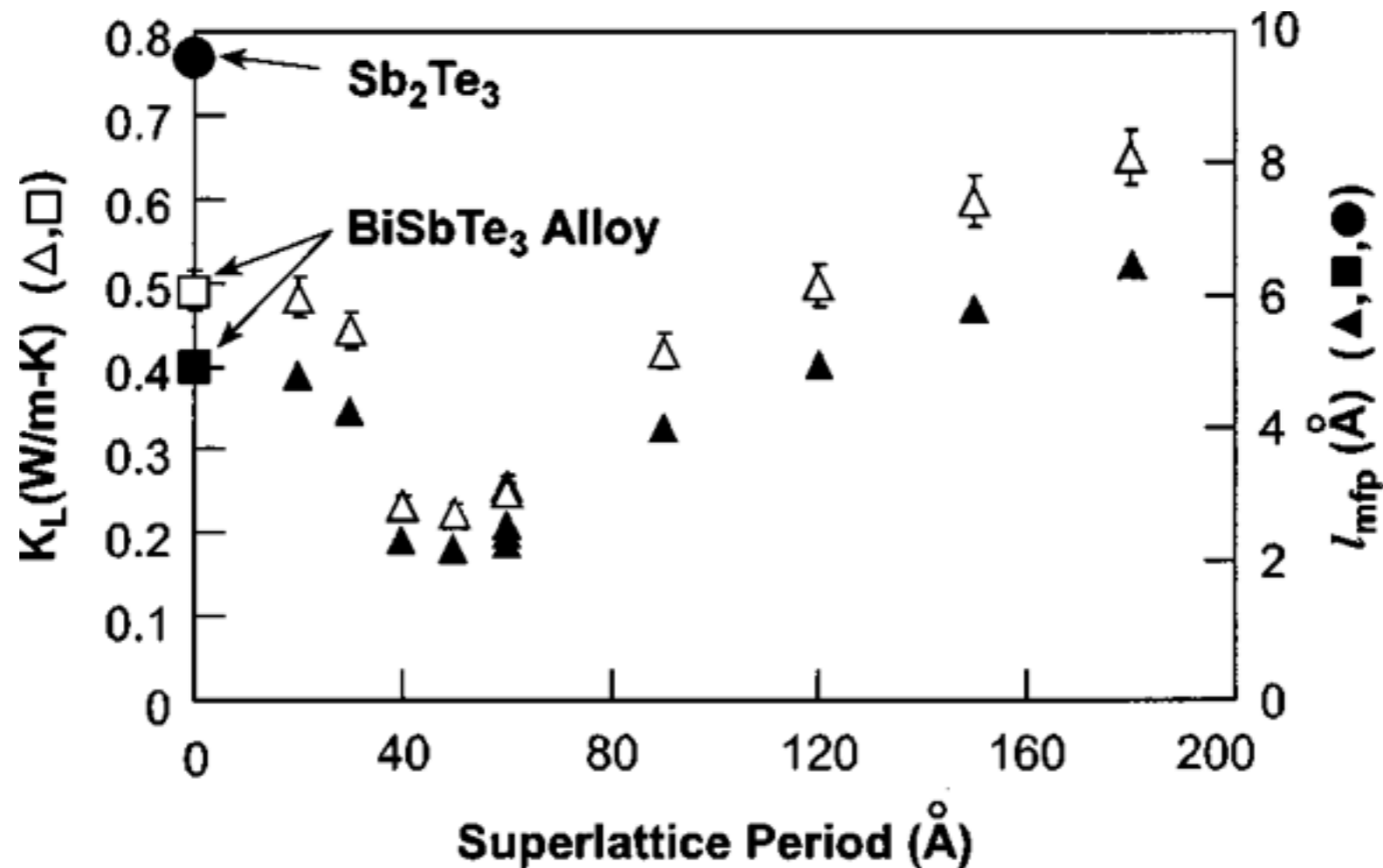
L.D. Hicks and M.S. Dresselhaus, Phys. Rev. B 47, 12737 (1993)

p-Bi₂Te₃ / Sb₂Te₃ Superlattices



Bi₂Te₃ $\kappa_{ph} = 1.05 \text{ Wm}^{-1}\text{K}^{-1}$

Lattice thermal conductivity



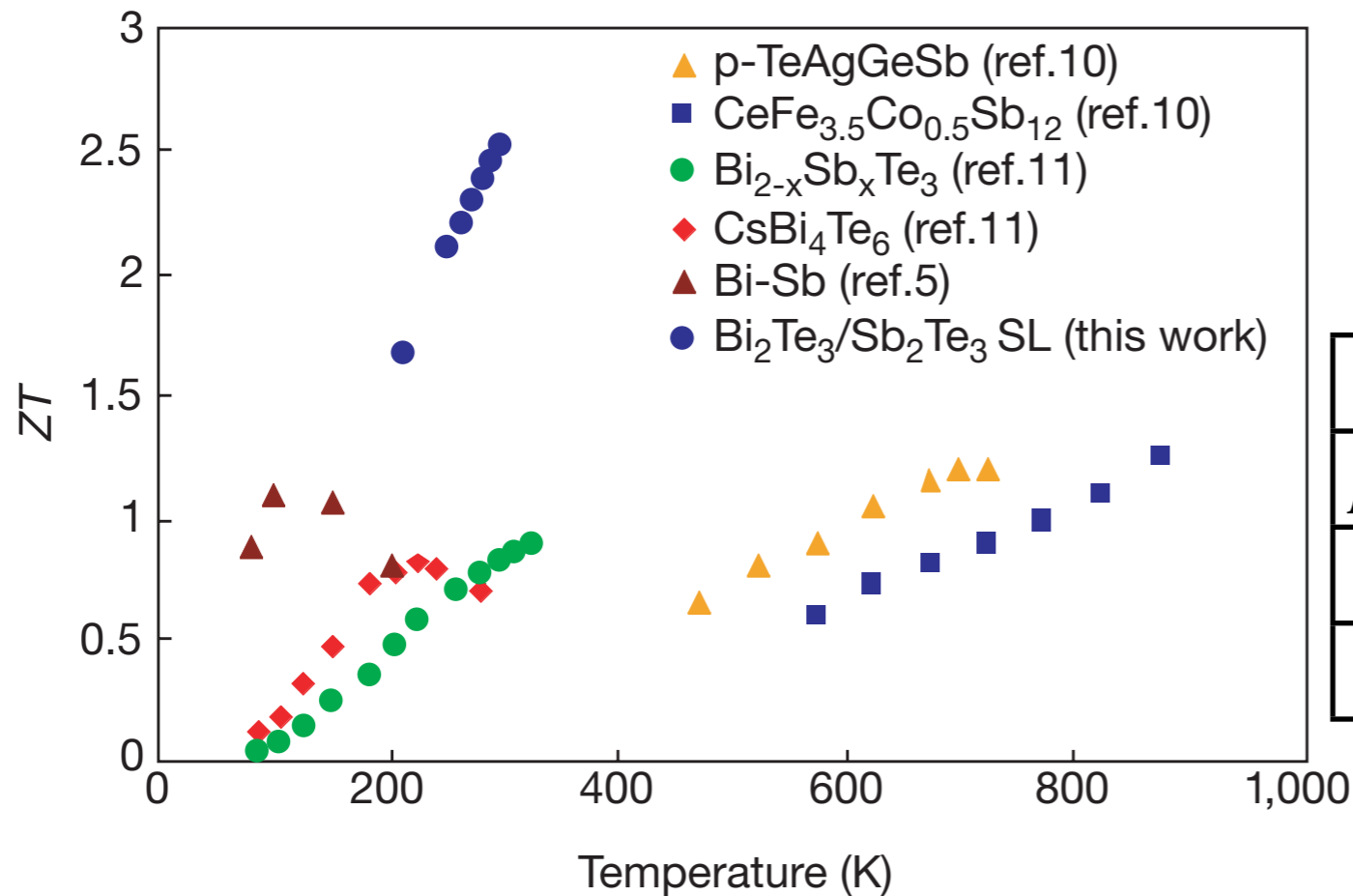
Phonon mean free path



3/3 nm, 1/5 nm, 2/4 nm Bi₂Te₃ / Sb₂Te₃ periods almost identical κ_{ph}

R. Venkatasubramaniam Phys. Rev. B 61, 3091 (2000)

p-Bi₂Te₃ / Sb₂Te₃ Superlattices

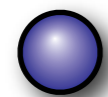


Bulk Bi₂Te₃ ZT ~ 1.0

Superlattice ZT = 2.6

Electrons	Phonons
$\mu = 383 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$	
$l = 11.4 \text{ nm}$	$\Lambda_{\text{ph}} = 3 \text{ nm}$
$k_{\text{el}}l \sim 7.6$	$k_{\text{ph}}\Lambda \sim 0.5$

=> Phonon blocking



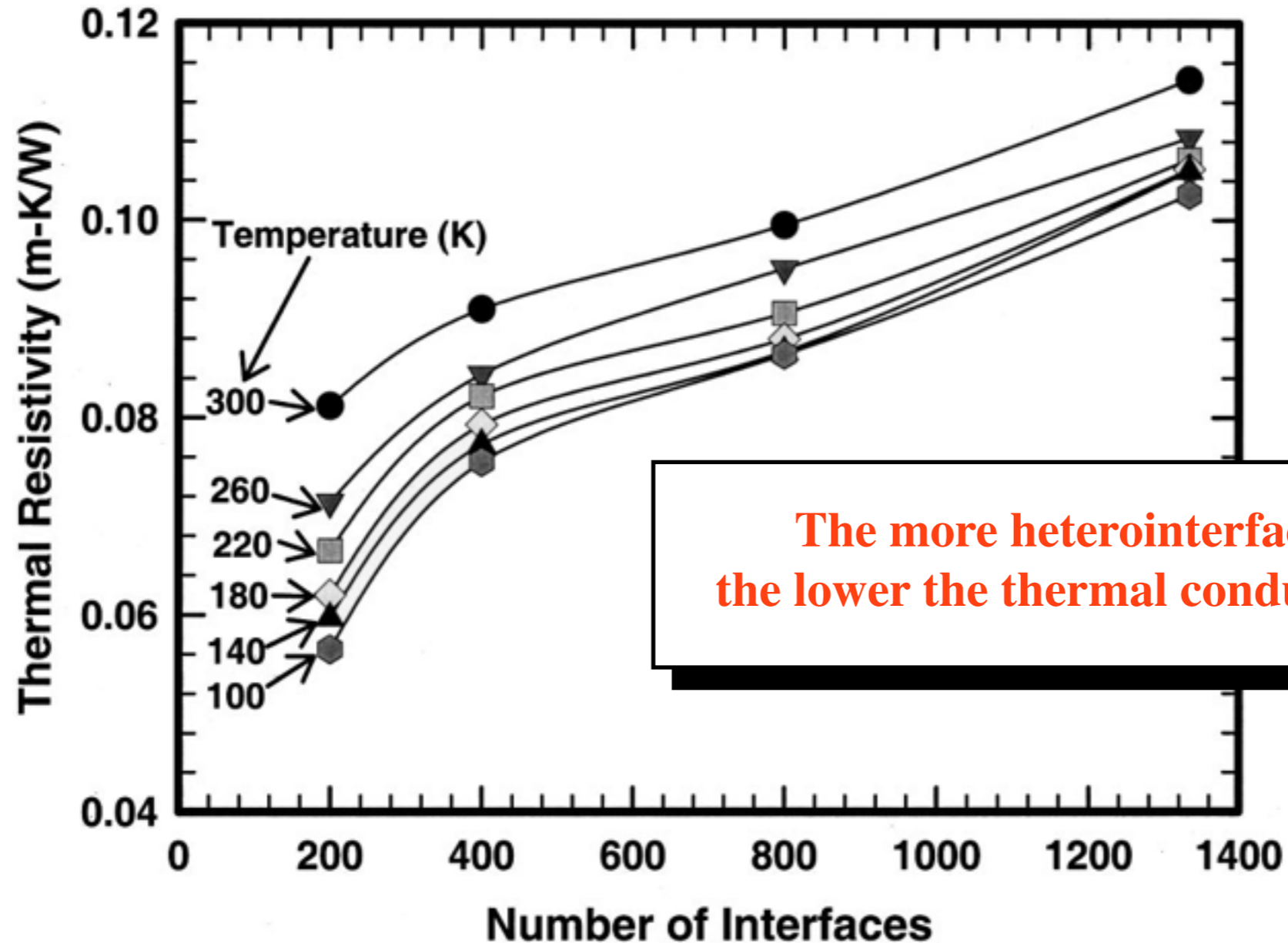
1 nm: 5 nm p-Bi₂Te₃ QW / Sb₂Te₃ barrier superlattices



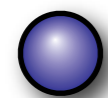
Thermal conductivity reduced more than electrical conductivity

R. Venkatasubramanian et al., Nature 413, 597 (2001)

Thermal Conductivity Si/Si_{0.7}Ge_{0.3} Superlattices



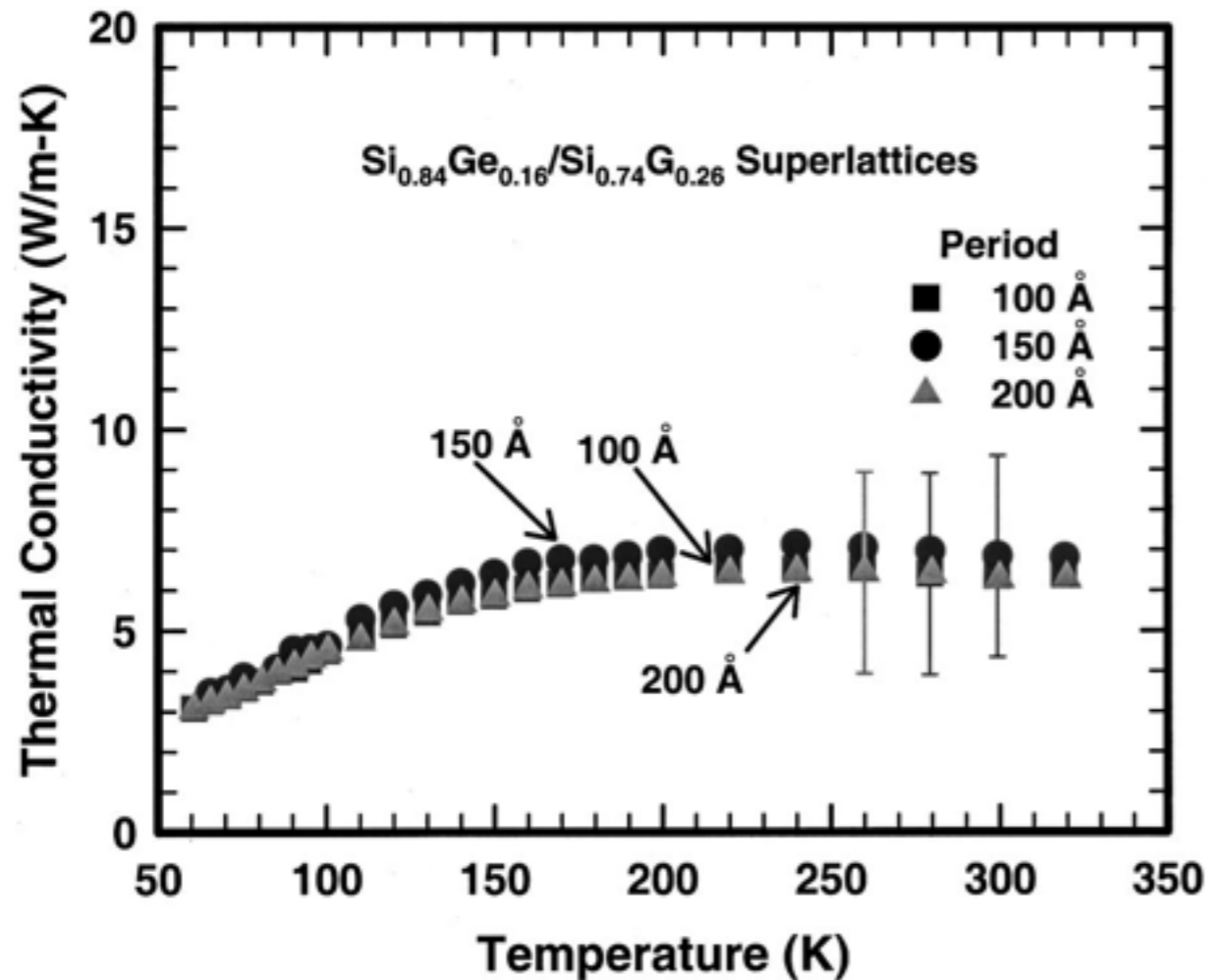
**The more heterointerfaces,
the lower the thermal conductivity**



Physically: more heterointerfaces → more phonon scattering

S. Huxtable et al., Appl. Phys. Lett. 80, 1737 (2002)

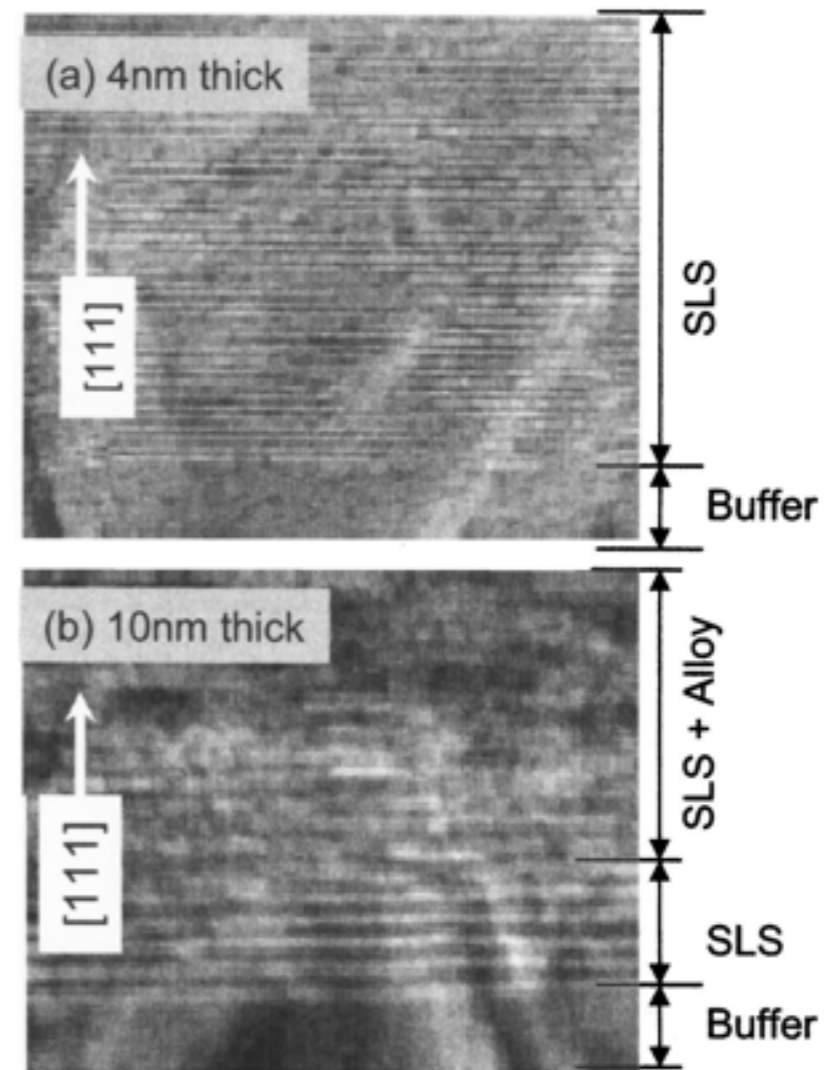
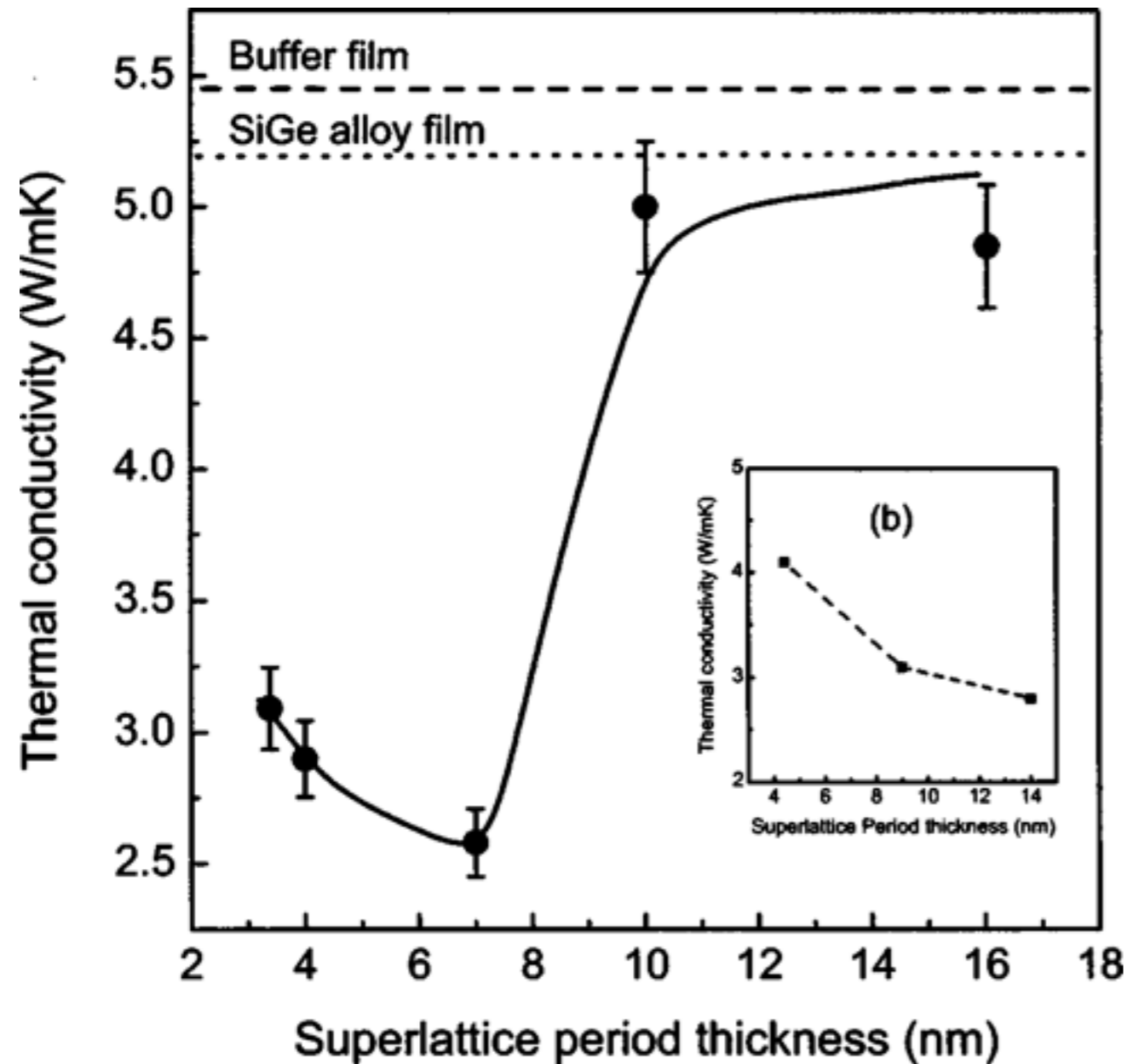
$\text{Si}_{0.84}\text{Ge}_{0.16}$ / $\text{Si}_{0.74}\text{Ge}_{0.26}$ Superlattices



- $\text{Si}_{1-x}\text{Ge}_x$ is a random alloy
- No effect of superlattice with $x = 0.16$ and $x = 0.26$
- Results the same as the average alloy Ge content
- A significant atomic mass difference is required

S. Huxtable et al., Appl. Phys. Lett. 80, 1737 (2002)

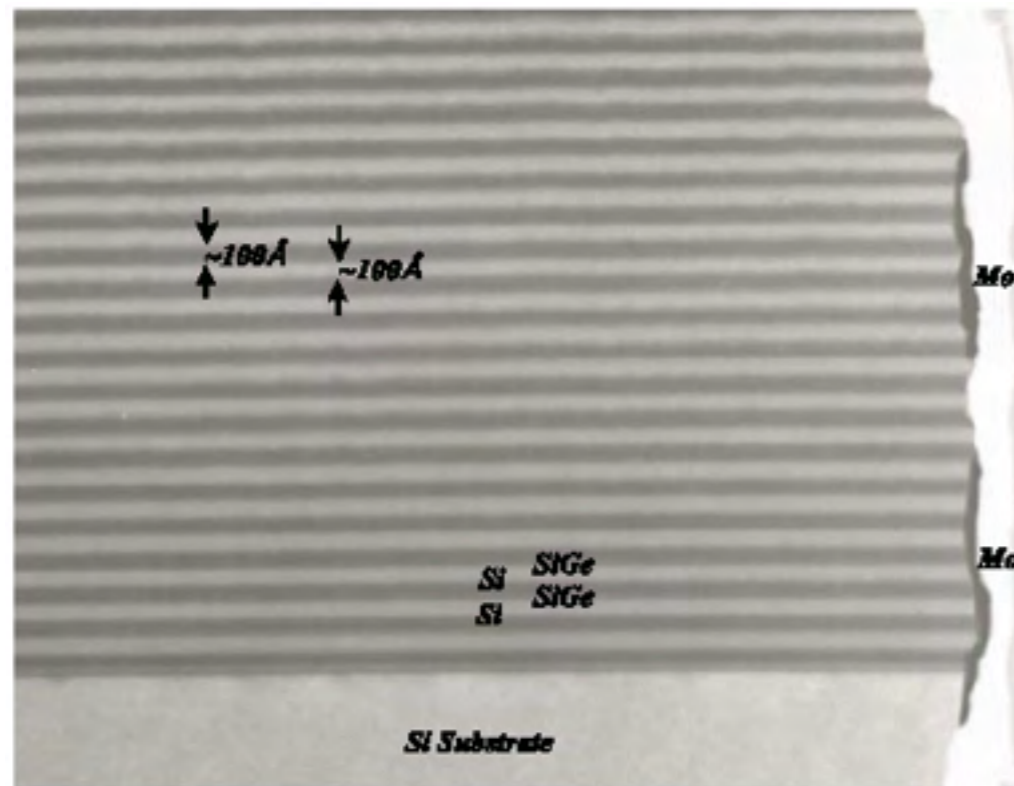
Si/Ge Superlattice Reduced Thermal Conductivity



$\text{Si}_{0.5}\text{Ge}_{0.5}$ buffer

S. Chakraborty et al., Appl. Phys. Lett. 83, 4184 (2003)

Hi-Z n-Si/SiGe and p-B4C/B9C Superlattice



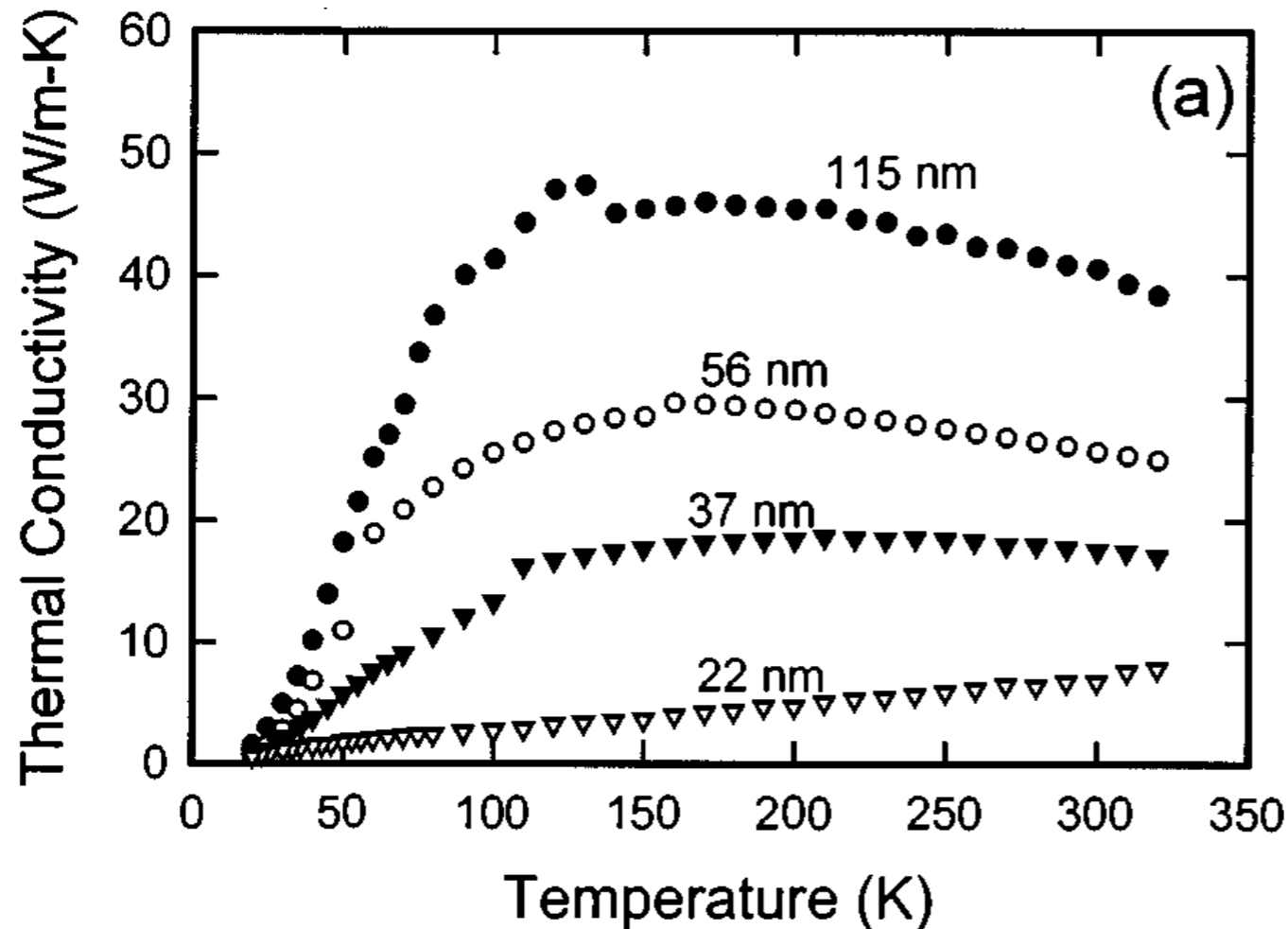
10 μm n-Si / $\text{Si}_{0.8}\text{Ge}_{0.2}$ superlattice

- $\alpha = -1260 \mu\text{VK}^{-1}$
- $\sigma = 95,200 \text{ 1}/(\Omega\text{-m})$
- $\kappa = 14.6 \text{ Wm}^{-1}\text{K}^{-1}$
- $ZT = 3.1$ at 300 K

- p-B4C/B9C superlattice with $ZT = 4.0$
- Claim of NIST and UCSD confirming measurements
- Insufficient data in paper to check if true result
- 15% TE module demonstrated with $\Delta T = 200 \text{ }^\circ\text{C} \Rightarrow ZT_{\text{module}} \sim 3$

S. Ghamaty & N.B. Elsner, Int. Symp. Nano-Thermoelectrics, June 11-12 (2007) Osaka, Japan

Thermal Conductivity of Silicon Nanowires



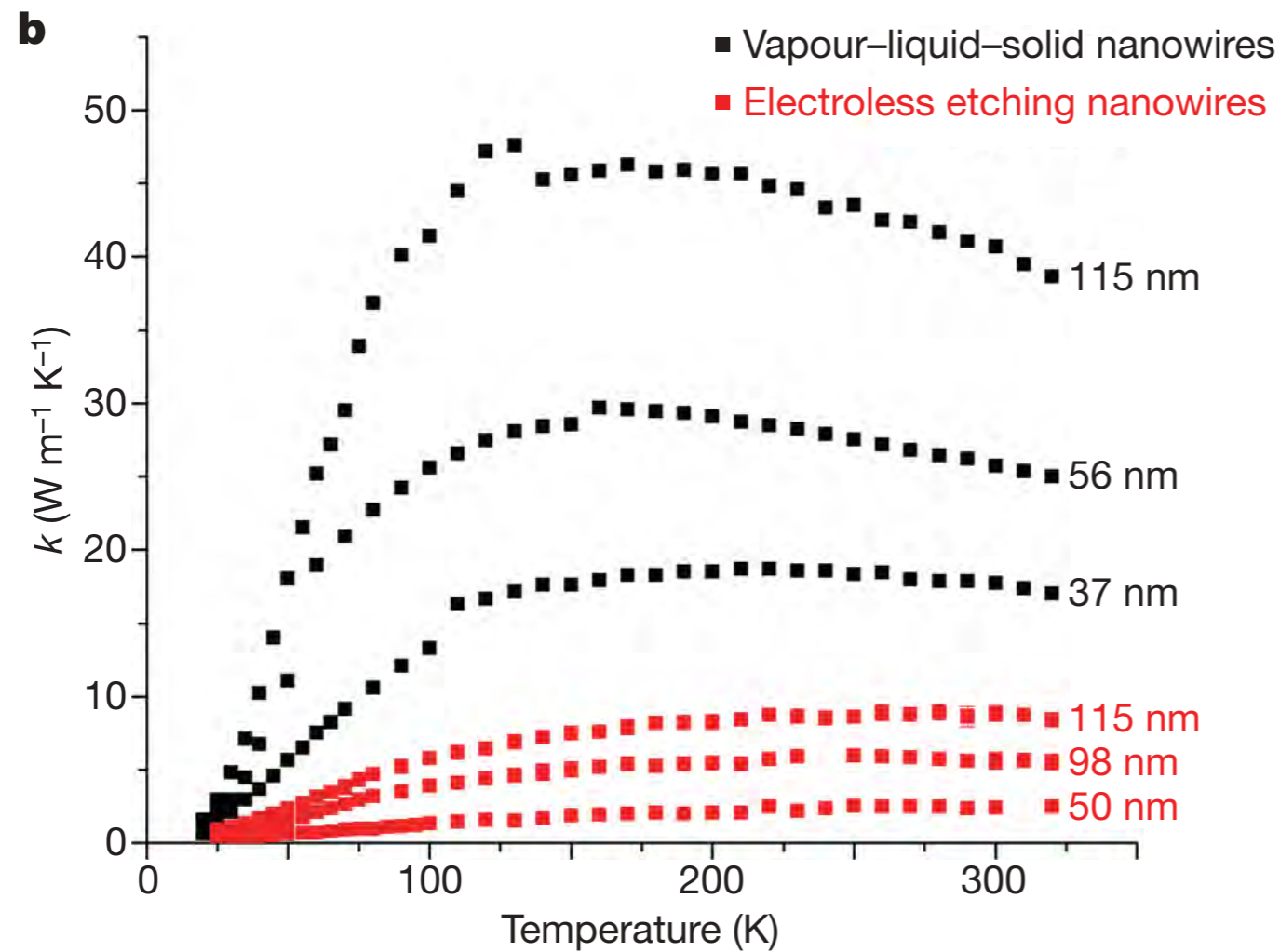
● For bulk Si
 $\kappa \sim 149 \text{ Wm}^{-1}\text{K}^{-1}$
 at 300 K

● For bulk Si
 $\Lambda_{\text{ph}} = \frac{3\kappa_{\text{ph}}}{C_v \langle v_t \rangle \rho}$
 $\sim 300 \text{ nm}$

● Phonon scattering at boundaries increases for smaller dia. wires

D.Y. Li et al. Appl. Phys. Lett. 83, 2934 (2003)

Thermal Conductivity of 1D Silicon Nanowires



Red data from nanowires with rough boundaries

$\Lambda_{\text{ph}} = \frac{3\kappa_{\text{ph}}}{C_v \langle v_t \rangle \rho}$
 $\sim 300 \text{ nm}$

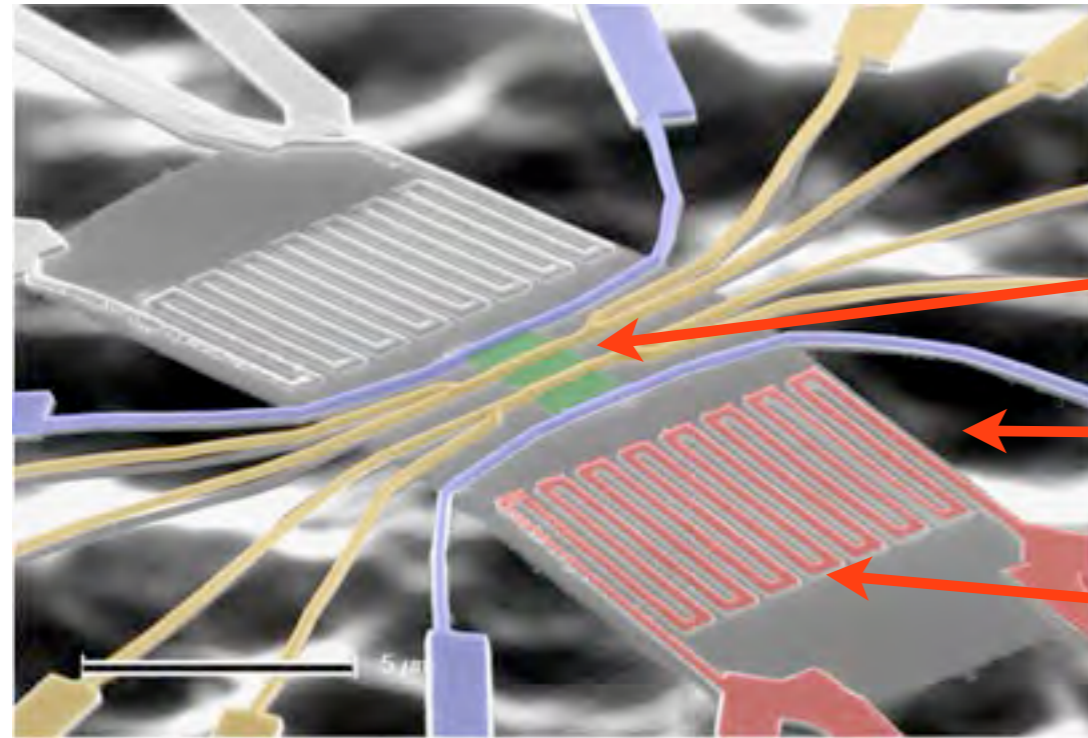
$\ell = 110 \text{ nm}$

Phonon scattering \gg electron scattering

reduces faster than σ

A.I. Hochbaum et al., Nature 451, 163 (2007)

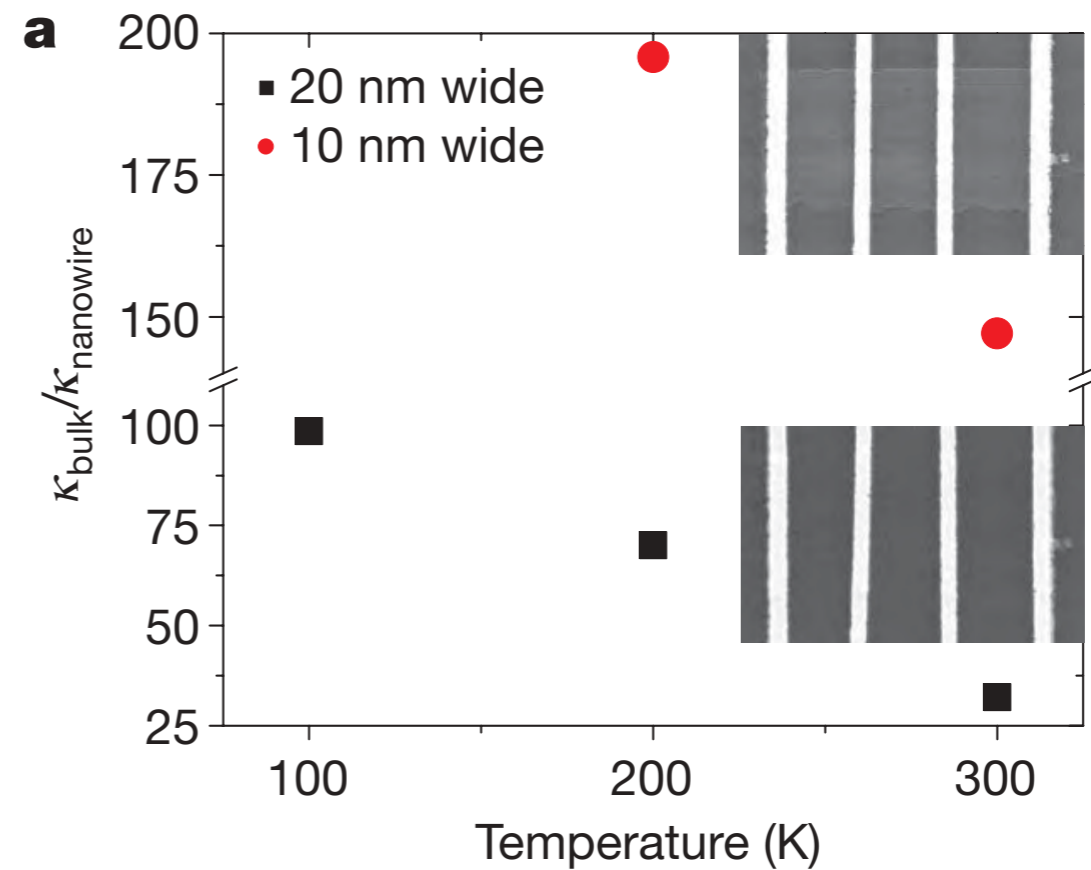
1D Nanowires



4 terminal Si nanowires

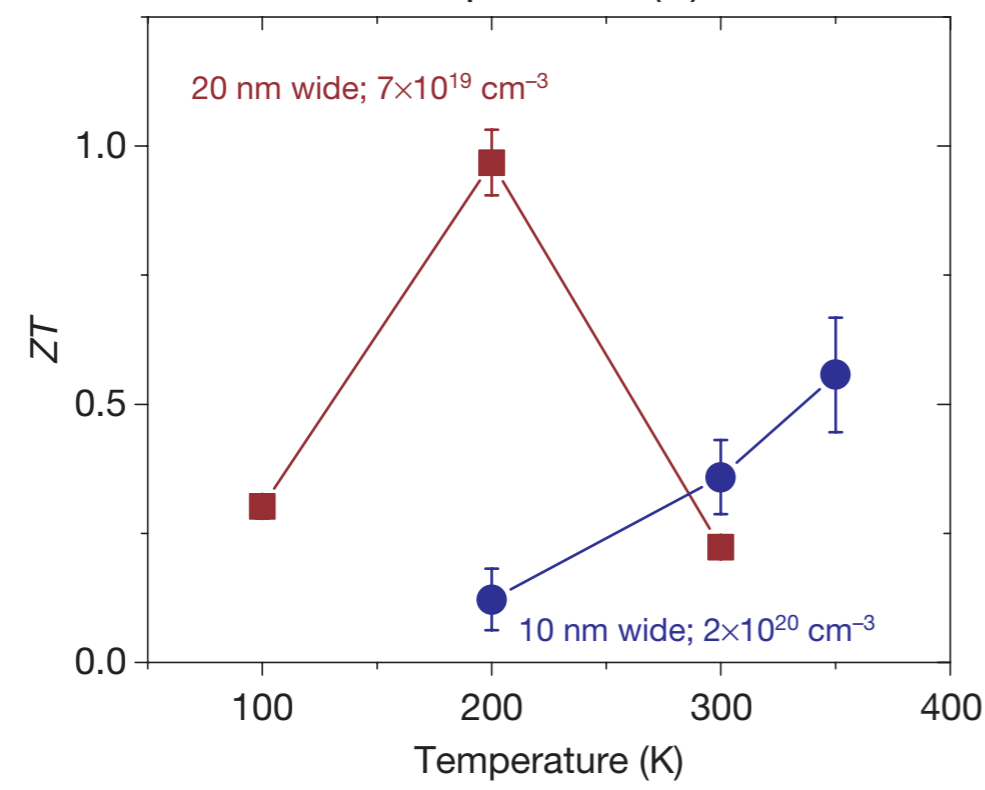
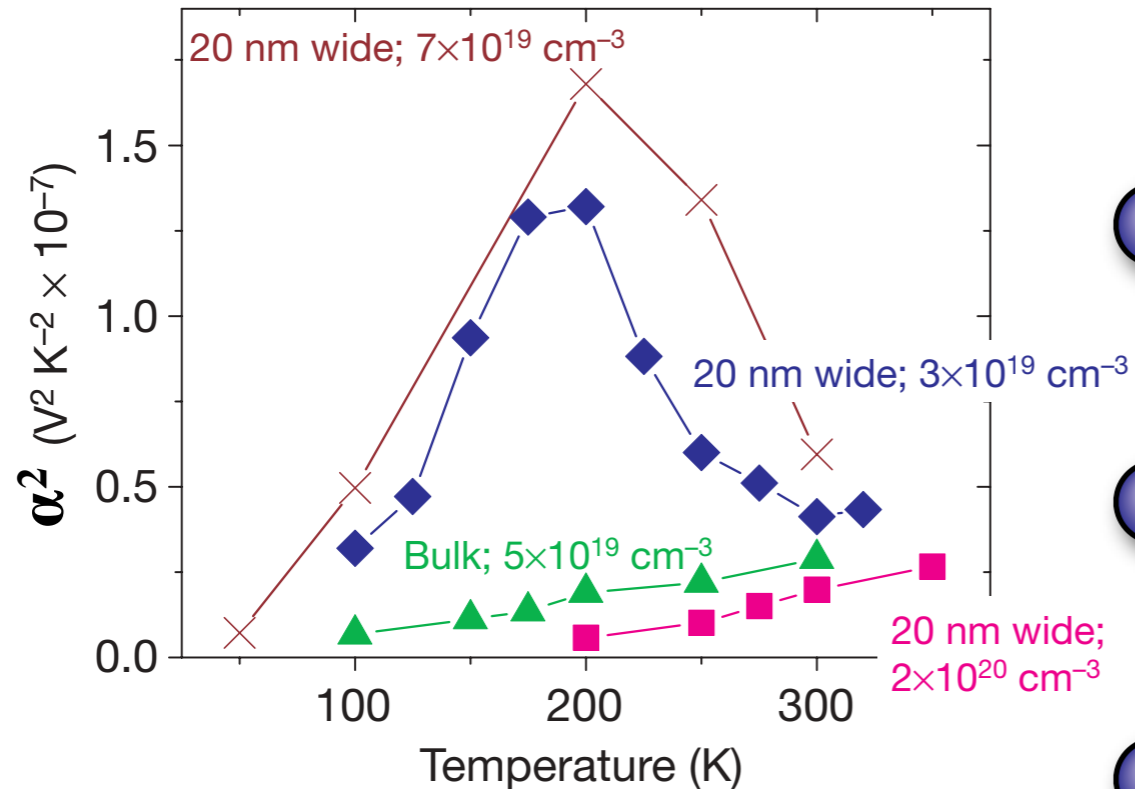
Substrate removed by etching

Heaters



A.I. Boukai et al., Nature 451, 168 (2007)

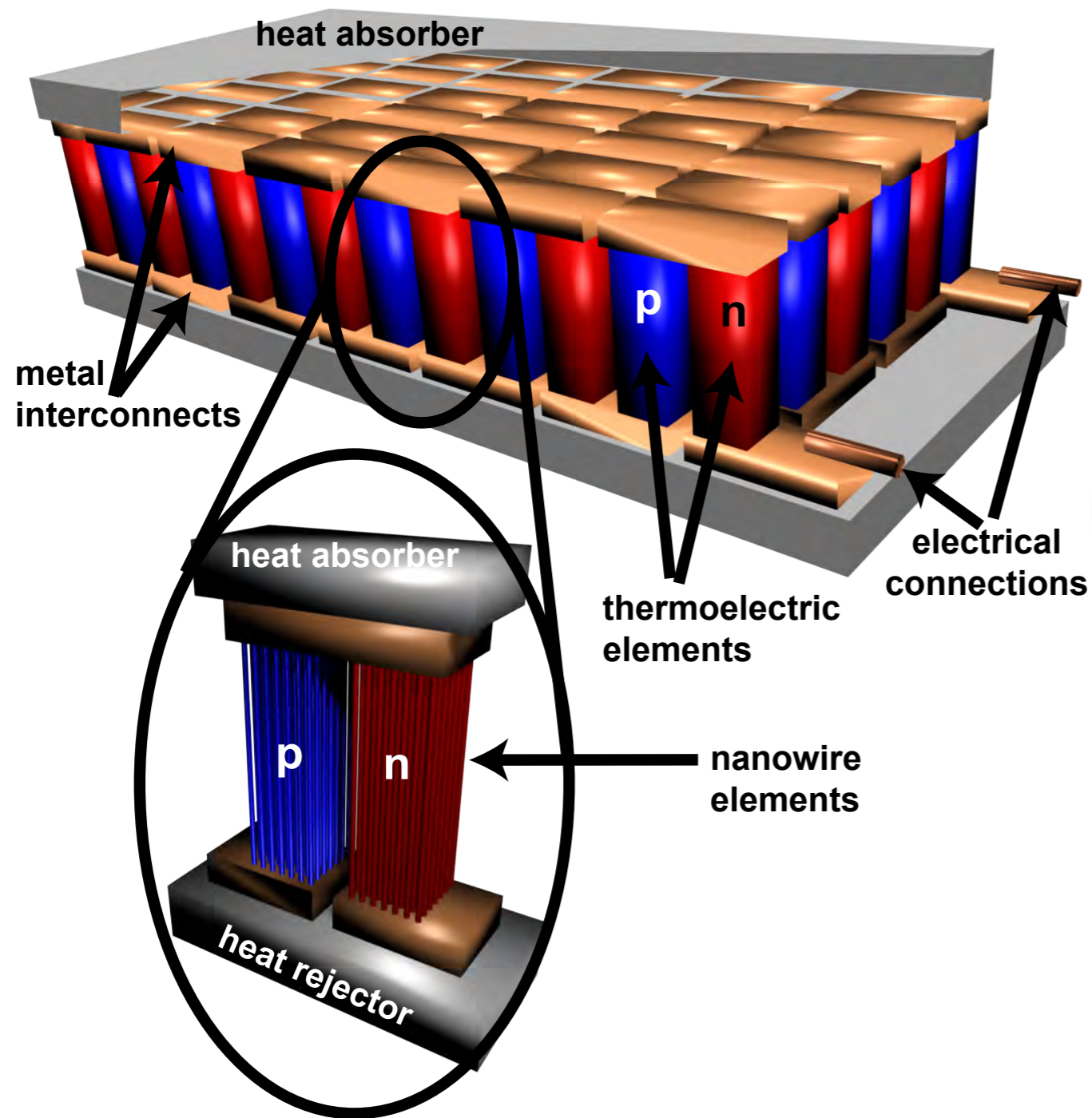
1D Silicon Nanowires



- Higher α from the higher DOS, $g(E)$
- α increased by ~ 2
- κ reduced by factor ~ 150
- ZT increased by factor 600
- Thermal conductivity reduced more than electrical conductivity

A.I. Boukai et al., Nature 451, 168 (2007)

For Module Require Vertical Nanowires

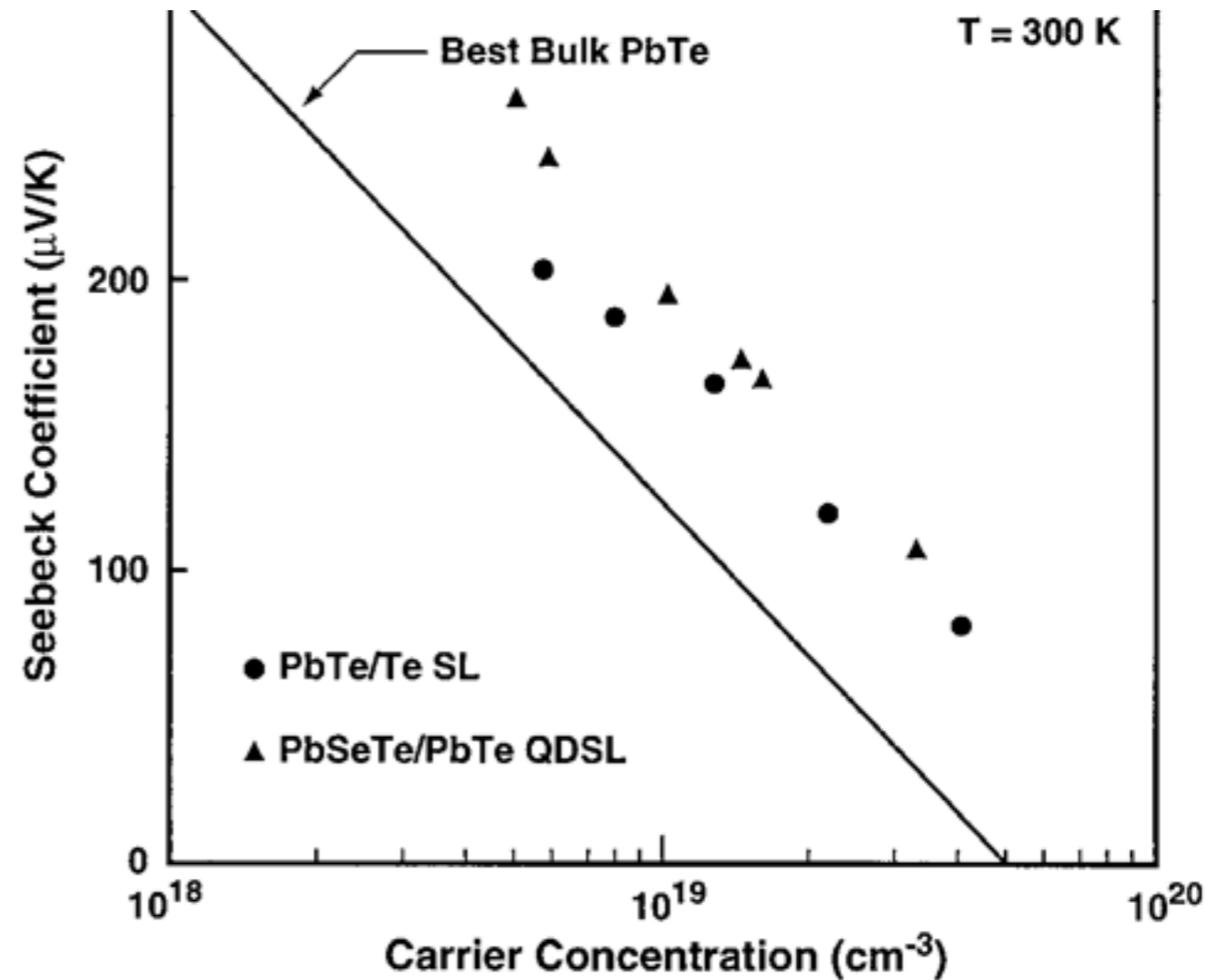
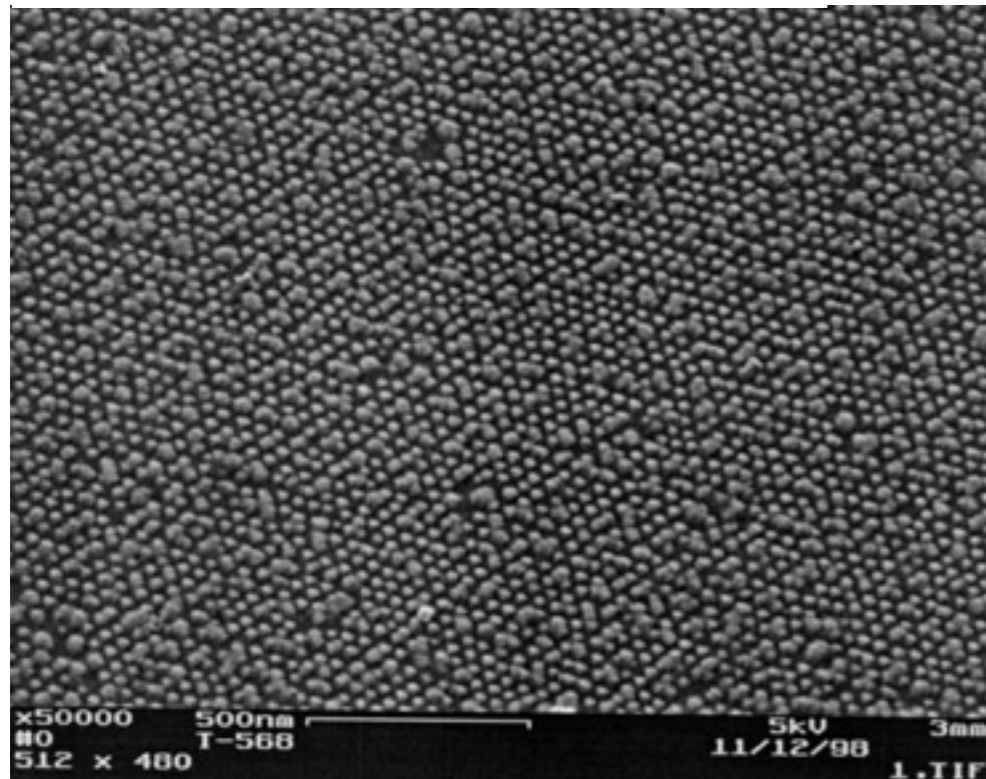
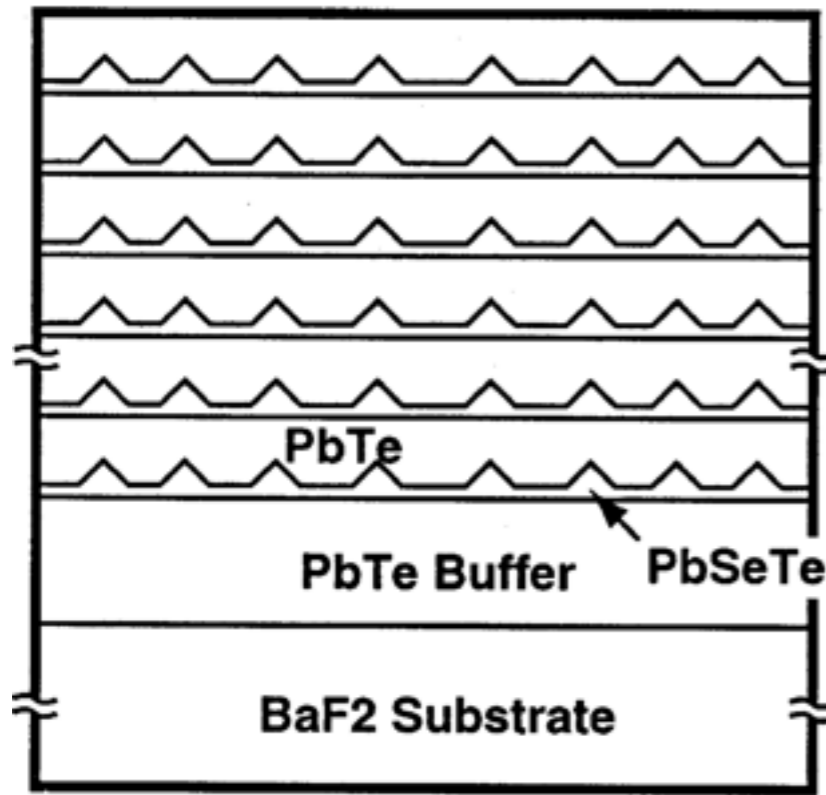


● 20nm vertical Si nanowires
>> 5 μm height required

● High aspect ratio nanowires
difficult to etch

● Also difficult to grow

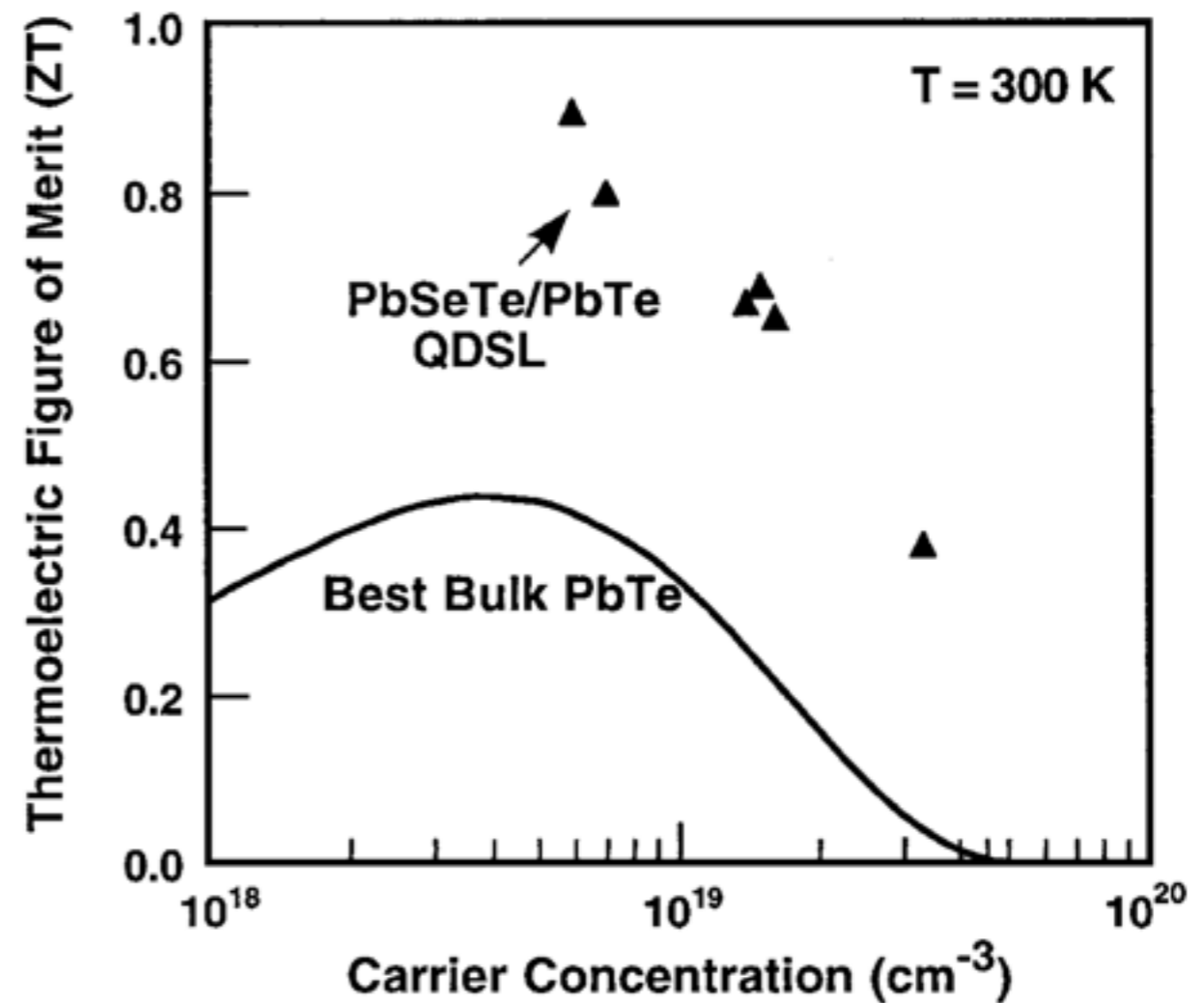
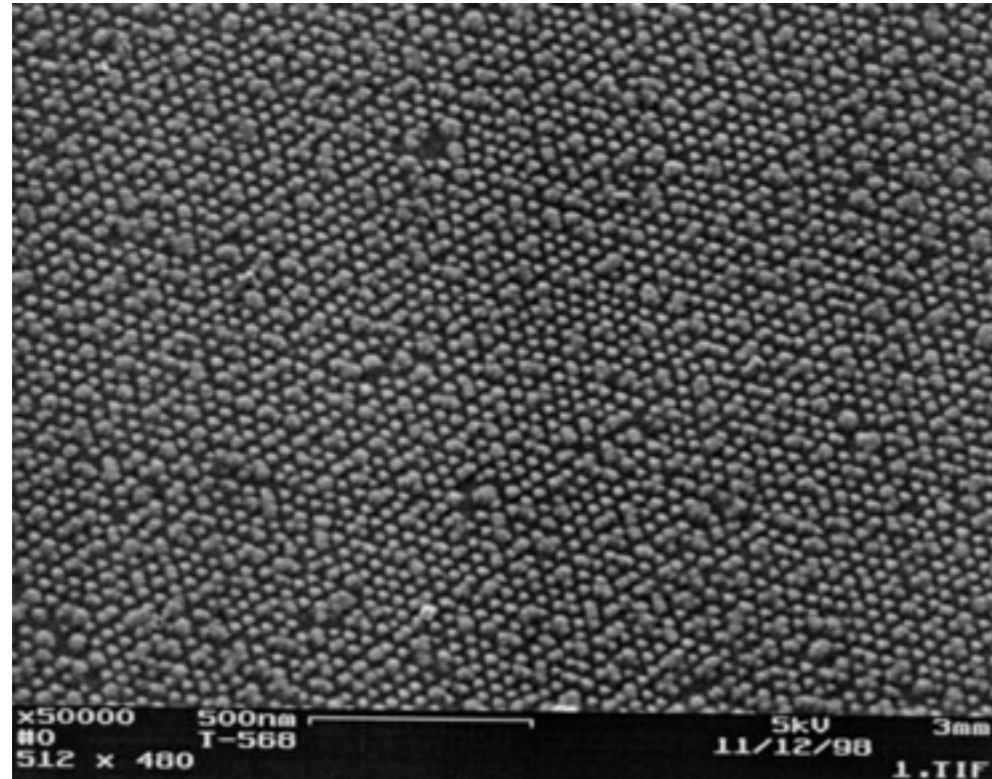
0D Quantum Dots



● Seebeck α : bulk < superlattice < QD

T.C. Harman et al., J. Elec. Mat. 29, L1 (2000)

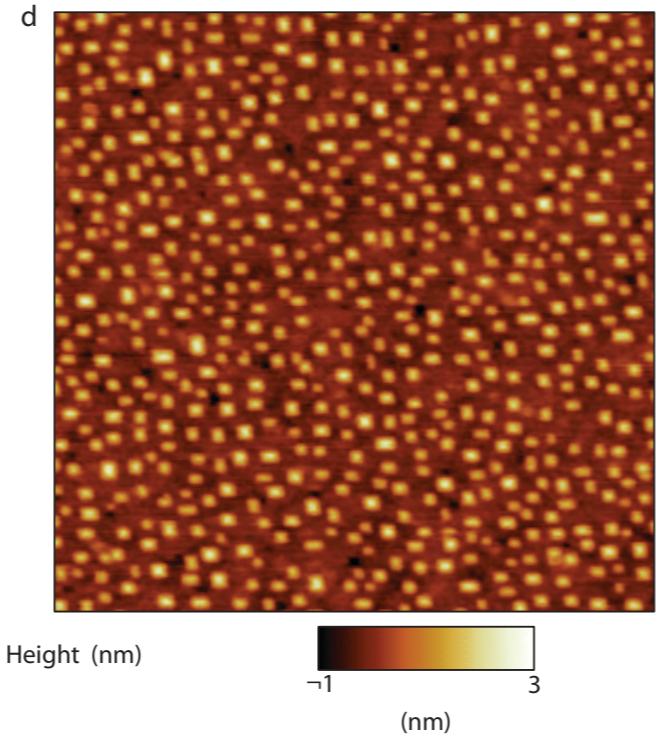
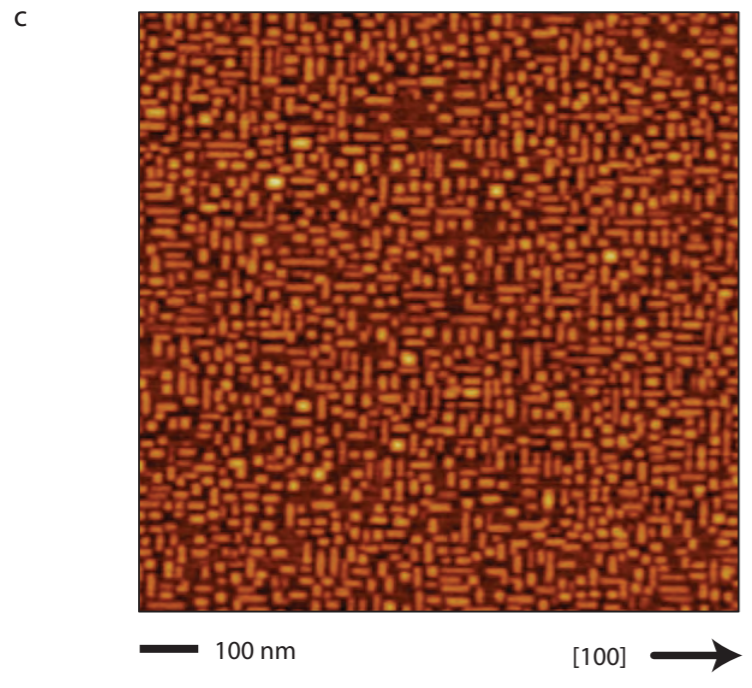
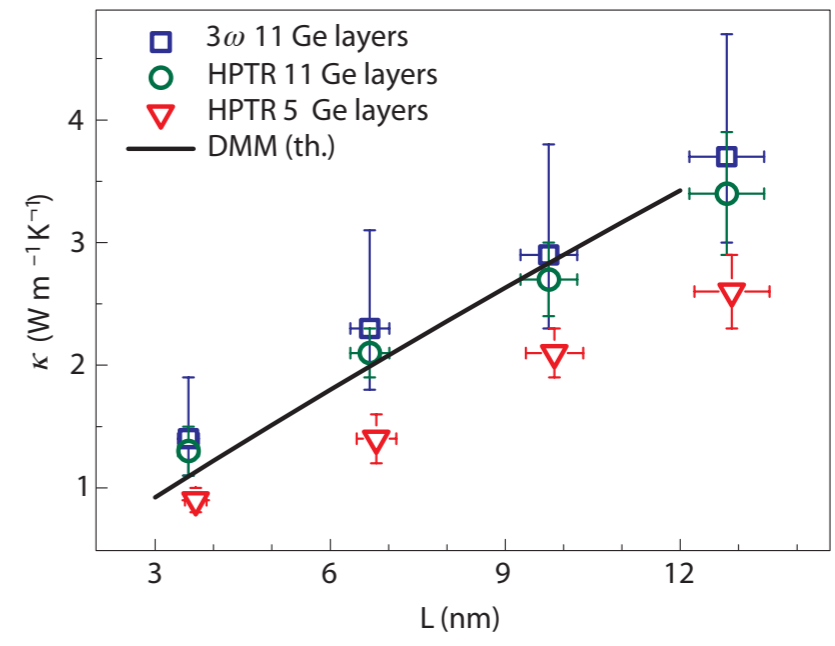
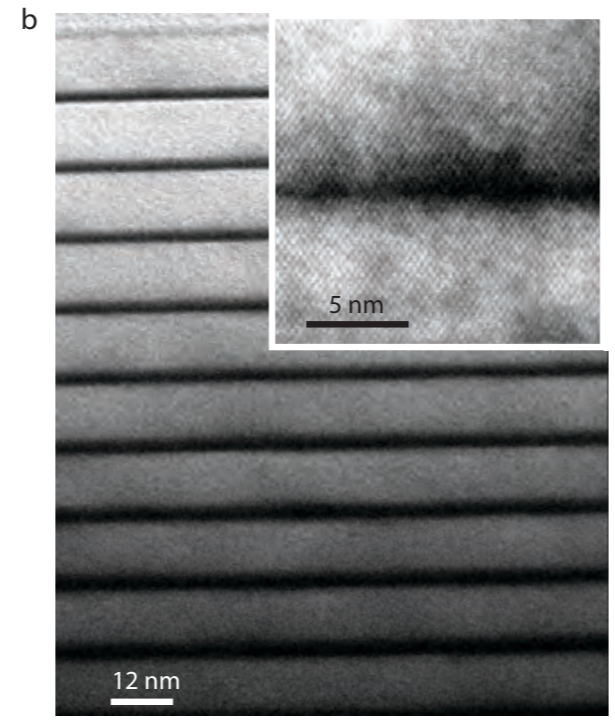
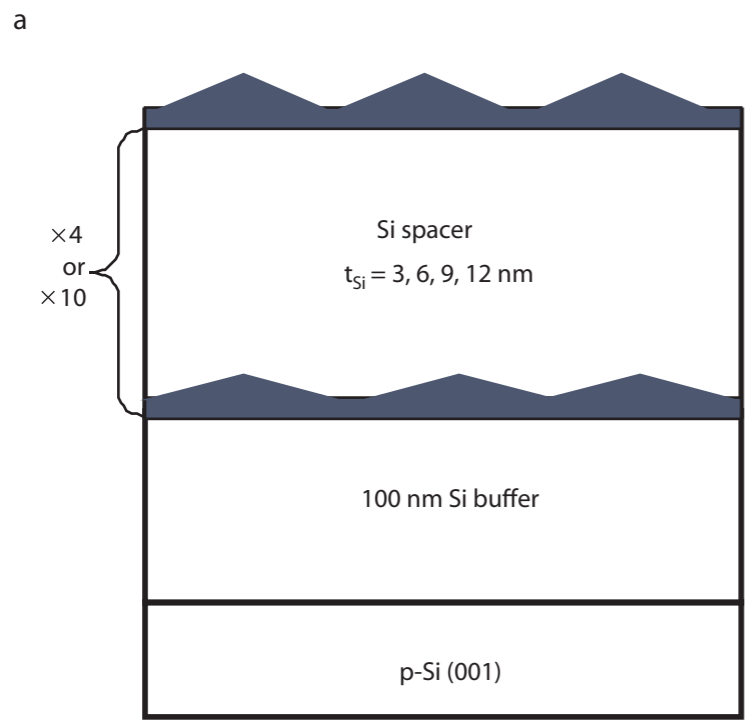
0D Quantum Dots



Thermal conductivity reduced more than electrical conductivity

T.C. Harman et al., J. Elec. Mat. 29, L1 (2000)

SiGe Quantum Dots



G. Perot et al., Nat. Mat. 9, 491 (2010)

Nanoparticle Engineering

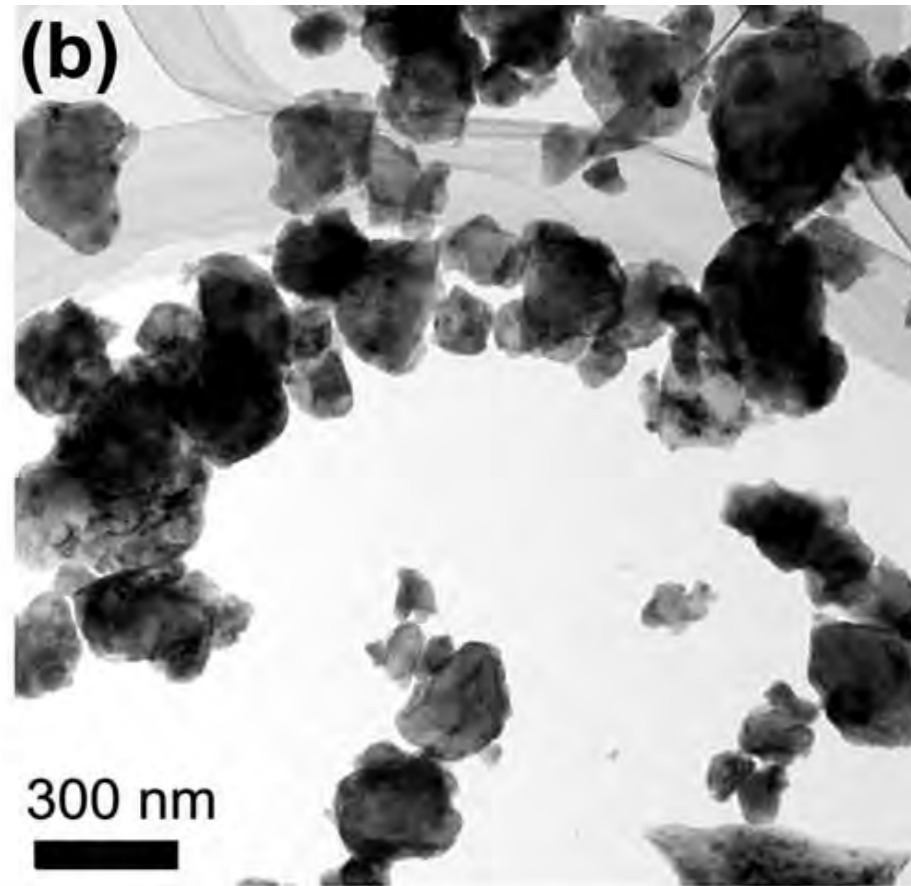
Advantages:

- **Potentially cheap, mass manufacturable technology**
- **Periodic structures not required to reduce thermal conductivity**
- **In SiGe material, particles below 50 nm demonstrate improved ZT**

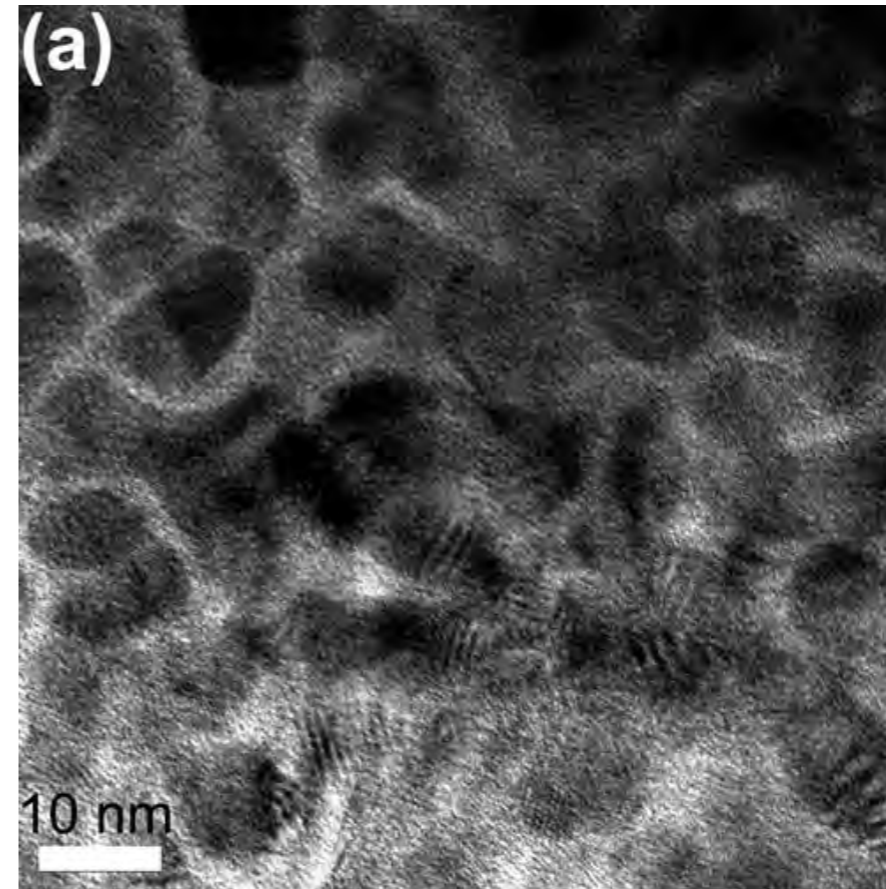
Disadvantages:

- **Many orders of magnitude change in ZT for small change in density (few %)**
- **Technology immature and process dependent**

Nanoparticle / Quantum Dot Materials

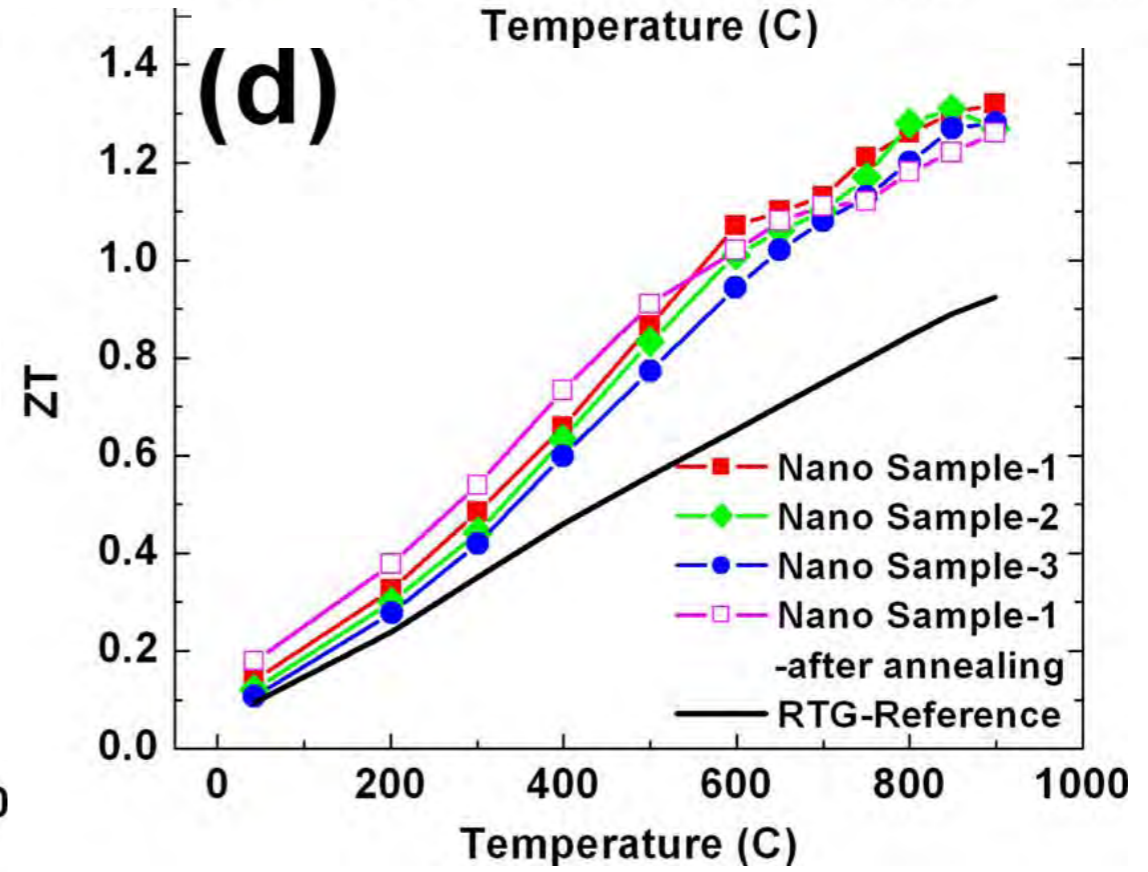
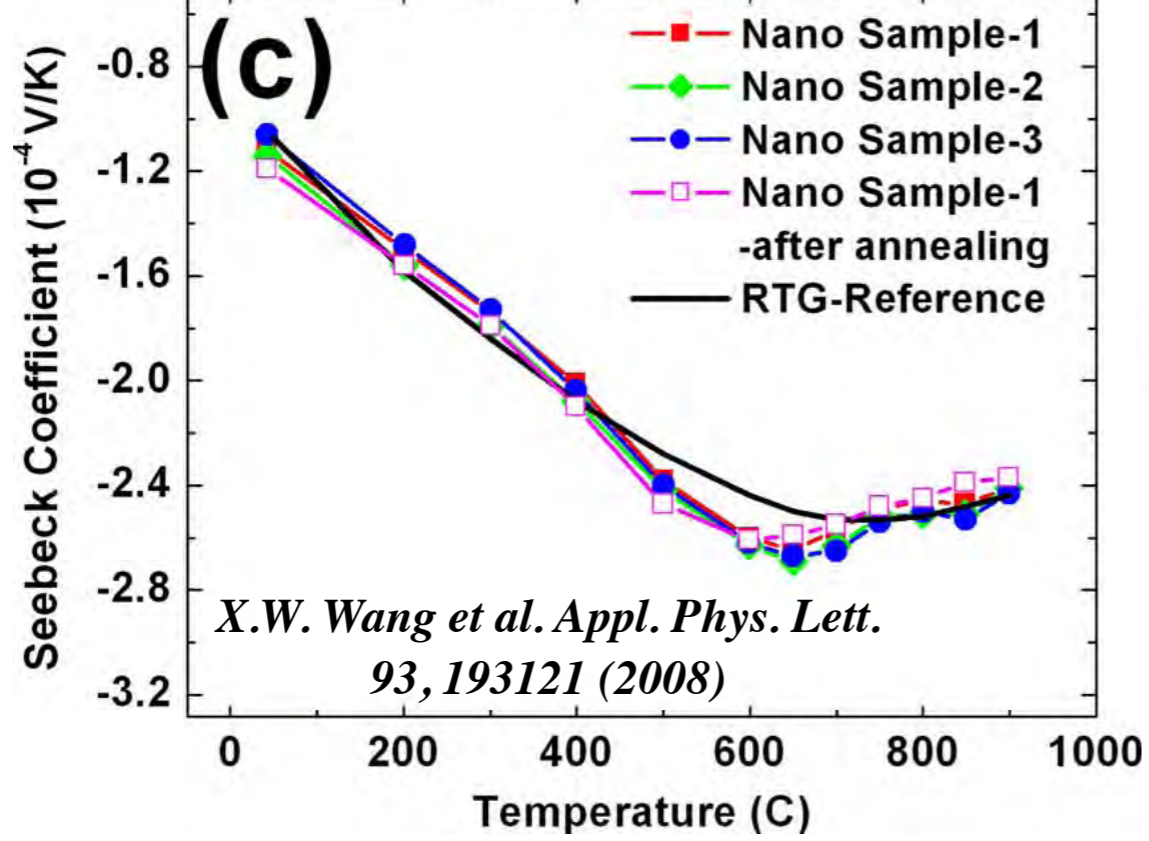
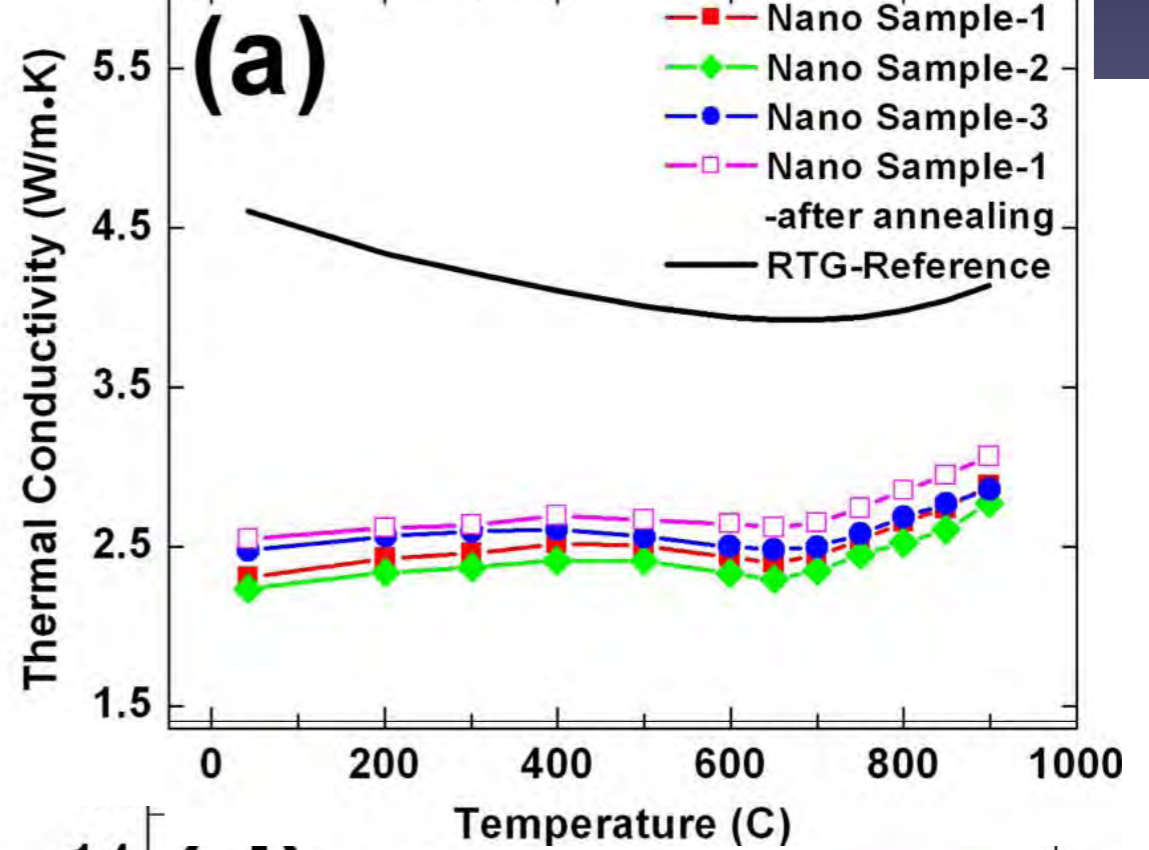
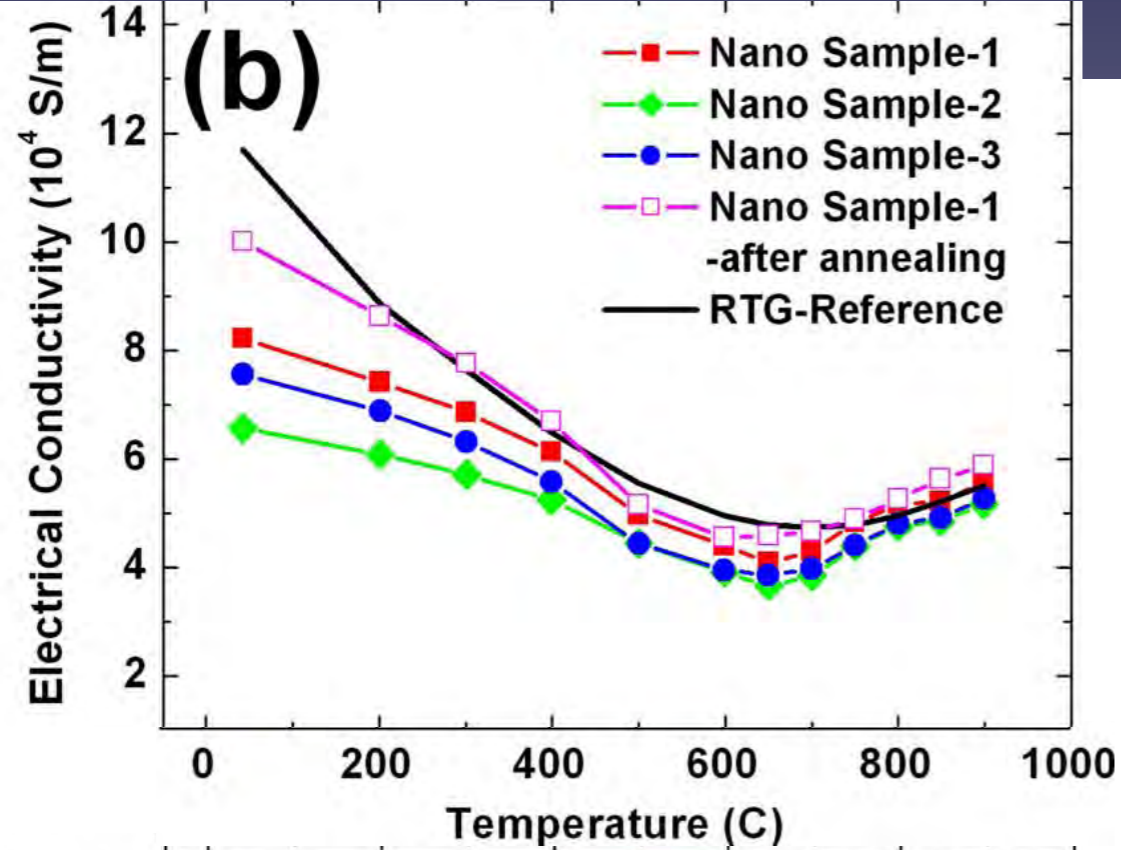


Ball milled bulk alloy

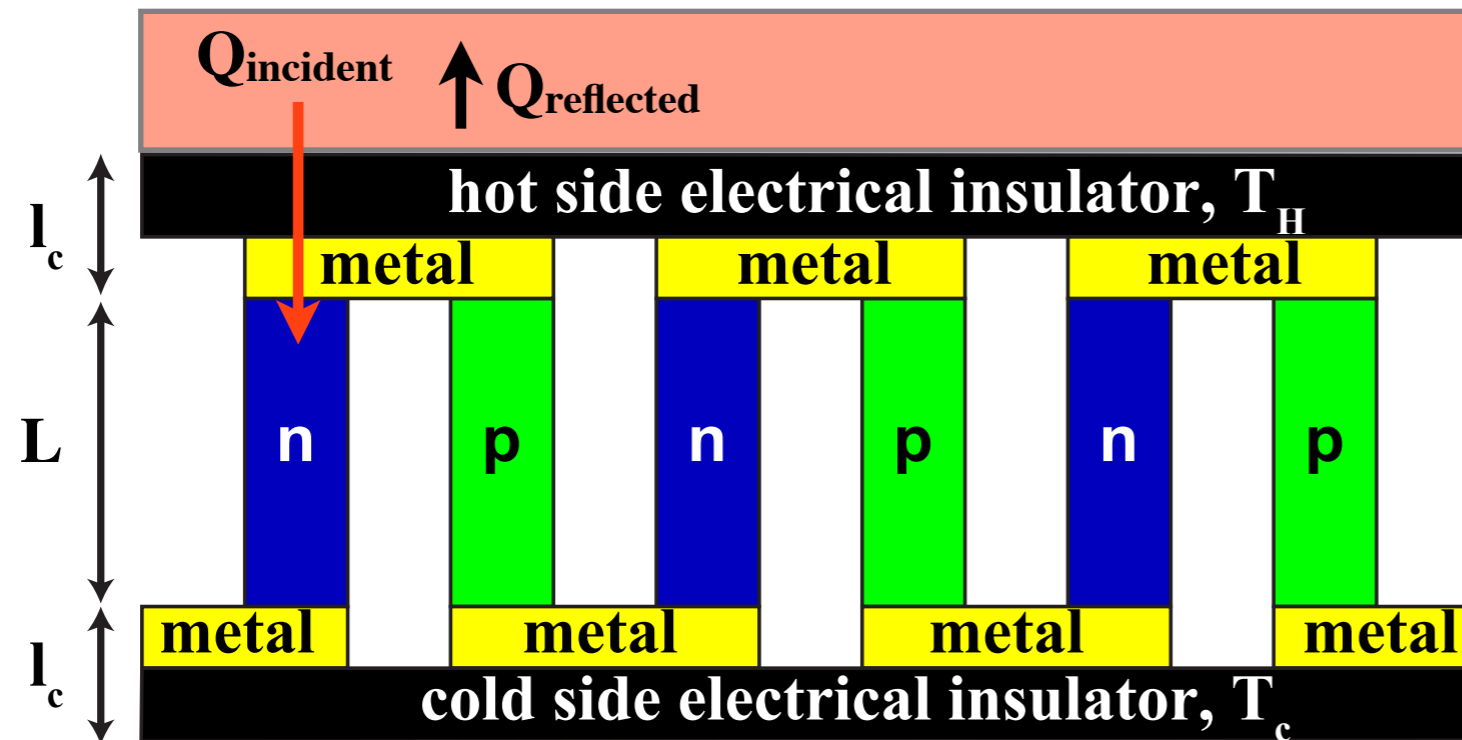


Hot pressed material with ~ 10 nm nanoparticles

X.W. Wang et al. Appl. Phys. Lett. 93, 193121 (2008)



Maximum Output Power



A = module leg area

L = module leg length

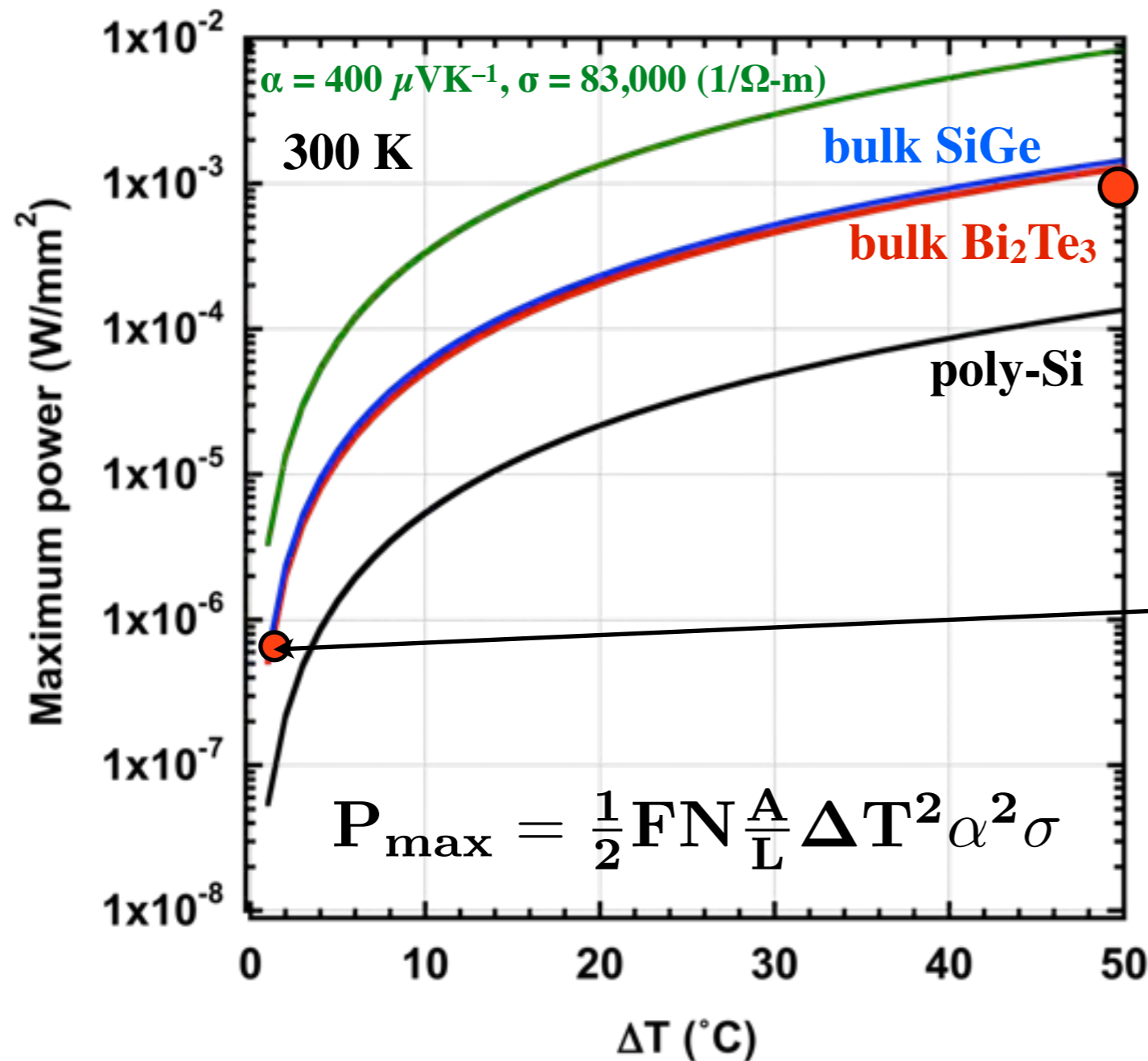
N = number of modules

- F = fabrication factor = perfect system – R_{contact} – R_{series} – Lost heat
- **Practical systems: both electrical and thermal impedance matching is required**

$$P_{\text{max}} = \frac{1}{2} F N \frac{A}{L} \Delta T^2 \alpha^2 \sigma$$

D.M. Rowe (Ed.), 'Thermoelectrics Handbook: Macro to Nano' CRC Taylor and Francis (2006)

Maximum Power Examples



Dense microfabricated module

N = 2500

L = 10 μm

l_c = 1 μm

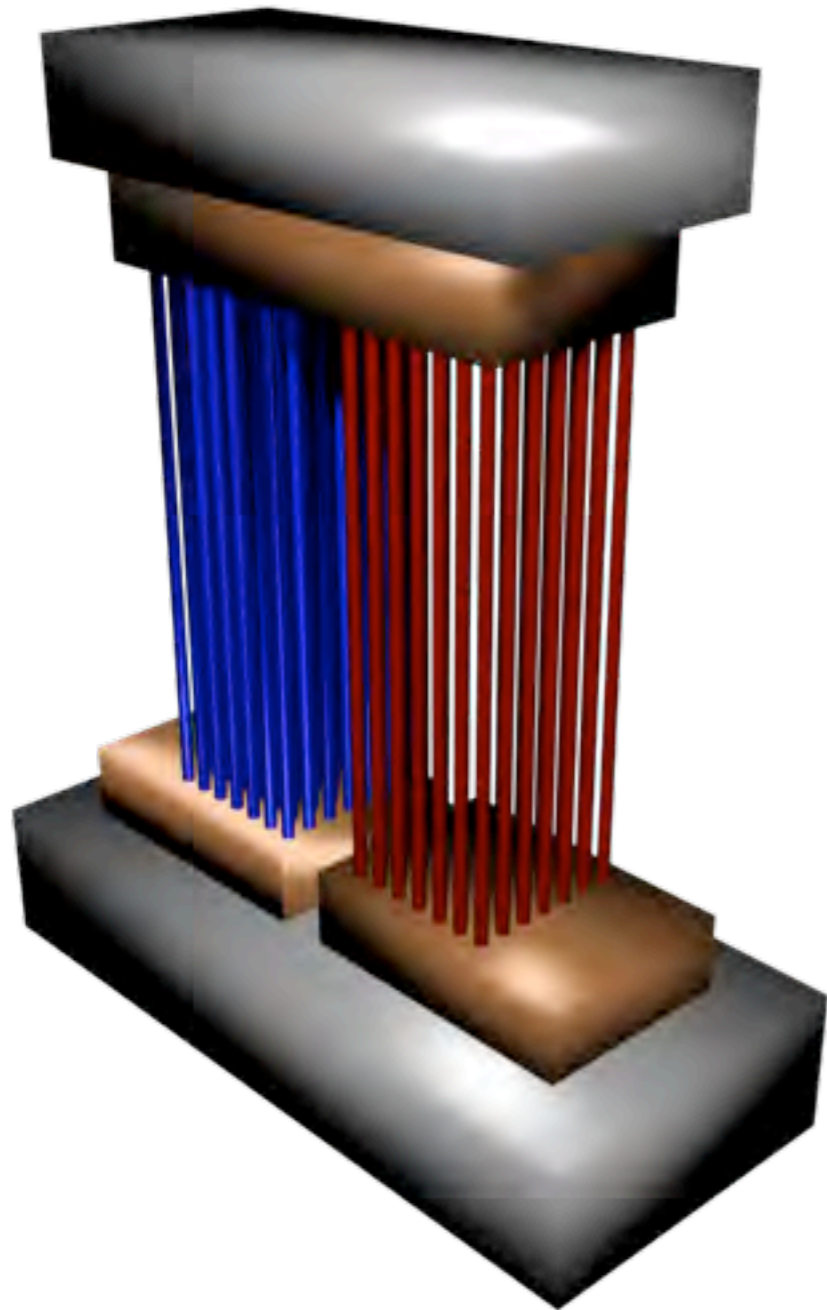
A = 10 x 10 μm²

F = 0.2

bulk Bi₂Te₃ experiment
Nat. Mat. 2, 528 (2003)
(scaled from L = 20 → 10 μm)

N.B. The thermal conductivity must also be considered for ΔT_{max}!

Generate Renewable Energy Efficiently using Nanofabricated Silicon (GREEN Silicon)



D.J. Paul, J.M.R. Weaver, P. Dobson & J. Watling
University of Glasgow, U.K.

G. Isella, D. Chrastina & H. von Känel
L-NESS, Politecnico de Milano, Como, Italy

J. Stangl, T. Fromherz & G. Bauer
University of Linz, Austria

E. Müller
ETH Zürich, Switzerland

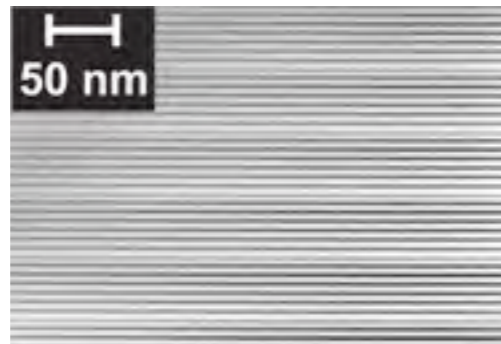
D.J. Paul – Co-ordinator GREEN Si
EC FP7 ICT FET
"2ZeroPowerICT" No.: 257750



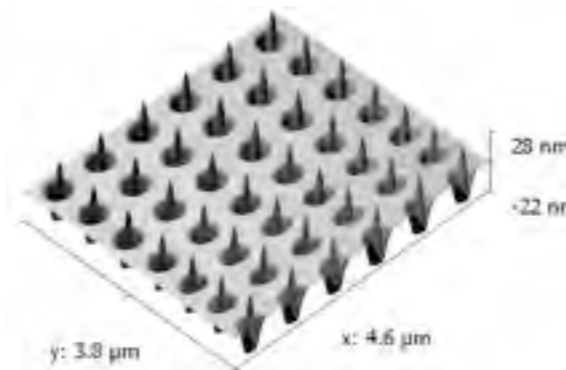
**University
of Glasgow**

GREEN Silicon Approach

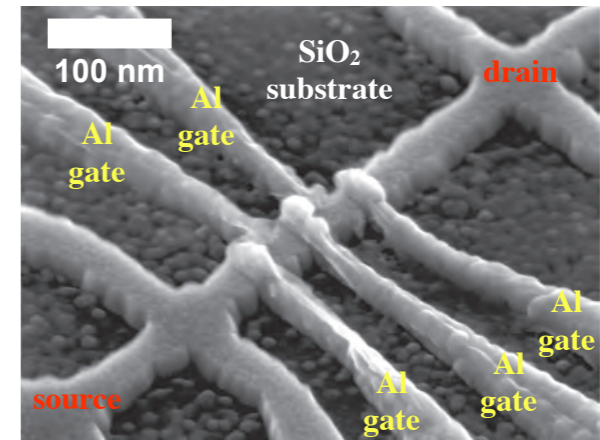
Low dimension technology



superlattice

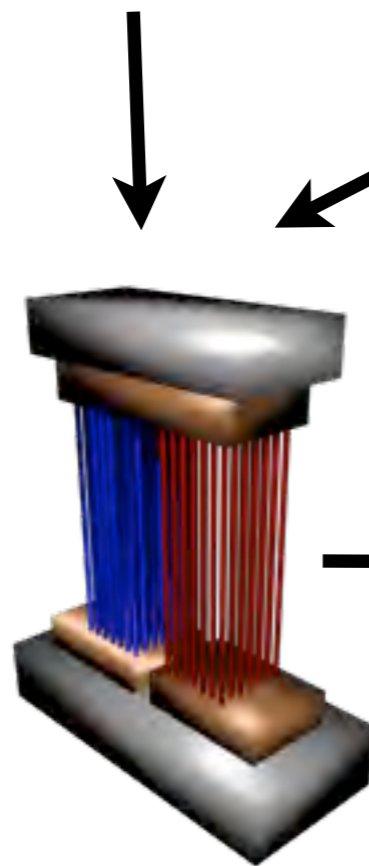


quantum dot

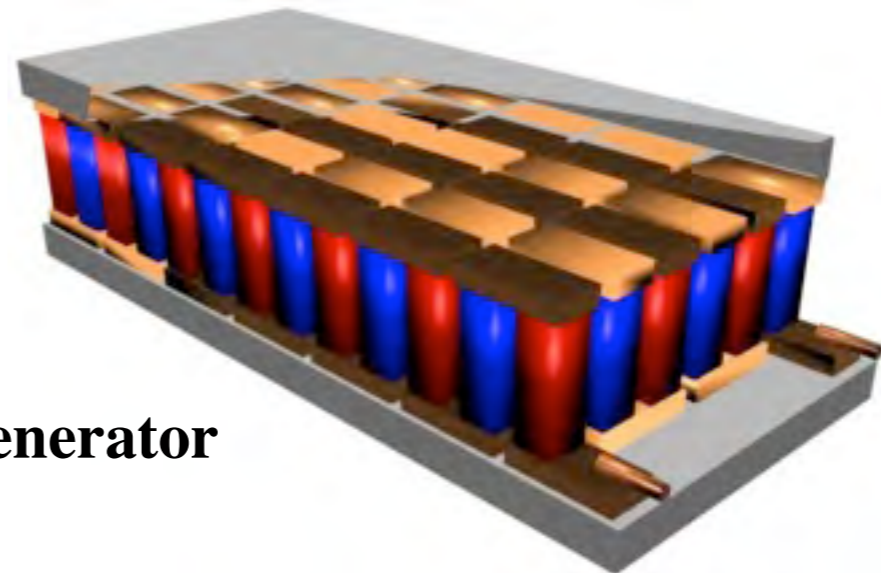


nanowires

Module



Generator



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Summary

- **Waste heat is everywhere → enormous number of applications**
- **Low dimensional structures are yet to demonstrate the predicted increases in α due to DOS**
- **Reducing κ_{ph} faster than σ has been the most successful approach to improving ZT to date**
- **Heterointerface scattering of phonons has been successful in reducing κ**
- **TE materials and generators are not optimised → there is plenty of room for innovation**

Further Reading

- **D.M. Rowe (Ed.), “Thermoelectrics Handbook: Macro to Nano”
CRC Taylor and Francis (2006) ISBN 0-8494-2264-2**
- **G.S. Nolas, J. Sharp and H.J. Goldsmid “Thermoelectrics: Basic Principles
and New Materials Development (2001) ISBN 3-540-41245-X**
- **M.S. Dresselhaus et al. “New directions for low-dimensional
thermoelectric materials” Adv. Mat. 19, 1043 (2007)**